



Intel® Stratix® 10 MX FPGA Development Kit User Guide

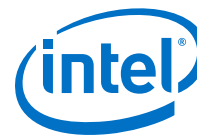


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1. Overview

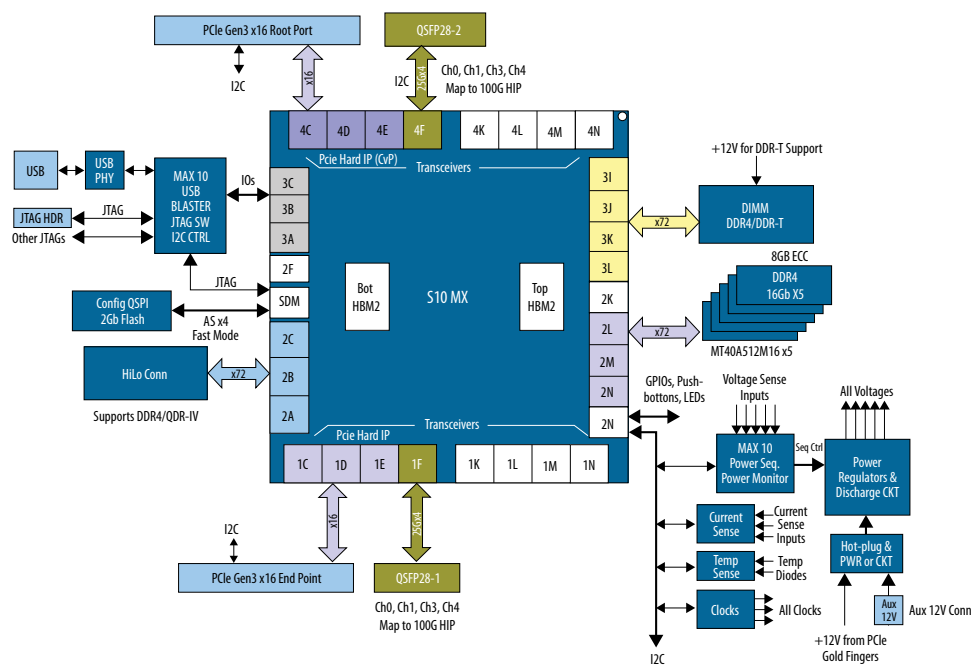
The Intel® Stratix® 10 MX FPGA development kit provides a hardware platform for evaluating the performance and features of the Intel Stratix 10 MX device.

Table 1. Ordering Information

Board Version	Board Part Number	Device Part Number
Intel Stratix 10 MX FPGA H-Tile (8 GB)	DK-DEV-1SMX-H-A	1SM21BHU2F53E1VG
Intel Stratix 10 MX FPGA H-Tile (16 GB)	DK-DEV-1SMC-H-A	1SM21CHU1F53E1VG

1.1. General Development Kit Description

Figure 1. Intel Stratix 10 MX FPGA Development Kit Block Diagram



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Feature Summary

- Intel Stratix 10 MX FPGA device
 - 0.85 V - 0.89 V VID-adjustable VCC core, 1 mm pitch, 2597 pin BGA
 - H-Tile transceivers capable of 28.3 gigabit per second (Gbps) data rates
 - HBM2 embedded memory tiles: 8 GB (4 GB x 2) or 16 GB (8 GB x 2)
- FPGA Configuration
 - Partial reconfiguration support
 - 2 gigabits (Gb) QSPI Flash
 - Storage for two configuration images in flash (Factory and User)
 - JTAG header for device programming
 - Built-in Intel FPGA Download Cable II for device programming
- Programmable Clock Sources
 - 644.53125 MHz Differential LVDS for QSFP
 - 100.000 MHz Differential LVDS for PCIe*
 - 133.333 MHz Differential LVDS to Memory
 - 125 MHz Configuration Clock
- Transceiver Interfaces
 - PCIe x16 interface supporting Gen3 End-Point mode connected to a x16 PCIe edge connector (gold edge fingers)
 - PCIe x16 interface supporting Gen3 Root-Port mode connected to a x16 straddle-mount PCIe edge connector
 - 2x standard QSFP28 optical module interfaces connected to the FPGA H-Tile transceivers
- Memory Interfaces
 - One on-board independent single rank DDR4 x72 (ECC) channels operating at 1333 MHz (DDR4-2666)
 - One DIMM socket supporting DDR4 DIMM or DDR-T DIMM
 - One HiLo connector supporting DDR4 and QDR-IV
- Communication Ports
 - 2x QSFP28 optical interface port
 - JTAG header
 - USB (Micro) on-board Intel FPGA Download Cable II
- Buttons, Switches and LEDs
 - System Reset Pushbutton
 - CPU Reset Pushbutton
 - PCIe Reset Pushbutton
 - Four dedicated User LEDs
 - Two dedicated configuration status LEDs



- Heatsink and Fan
 - Air-cooled heatsink assembly
 - Red Over-Temperature Warning LED Indicator
- Power
 - PCIe input power including required 2 x 4 Aux power connector
 - Blue Power-On LED
 - On/Off Slide Power Switch for bench-top operation
 - On board Power Measurement Circuitry
- Mechanical
 - PCIe standard height form factor
 - 4.376" x 10.8" board size
 - 3 Slots height requirement (with Air-cooled thermal solution)
- Operating Environment
 - Maximum ambient temperature of 0 °C - 35 °C

1.2. Recommended Operating Conditions

- Recommended ambient operating temperature range: 0 °C to 35 °C
- Maximum ICC load current: 192 A
- Maximum ICC load transient percentage: 30 %
- Maximum board power consumption: 192 Watts

1.3. Handling the Development Kit

When handling the kit, it is important to observe static discharge precautions.

Note: Without proper anti-static handling, the board could be damaged. Use anti-static handling precautions when handling the board.

Note: You must not operate this development kit in a Vibration environment.

Note: This development kit requires the top cover to be enclosed for proper cooling during operation.



2. Getting Started

2.1. About the Intel Quartus® Prime Software

The Intel Quartus® Prime design software is a multi-platform design environment that easily adapts to your specific needs in all phases of FPGA, CPLD and SoC designs. The Intel Quartus Prime software delivers the highest performance and productivity for Intel FPGAs, CPLDs, and SoCs.

The Intel Quartus Prime Design Suite software includes everything needed to design for using Intel FPGAs, SoCs and CPLDs from design entry and synthesis to optimization, verification and simulation.

Intel Quartus Prime Software

The Intel Quartus Prime Design Suite software is available in three editions based on specific design requirements: Pro, Standard, and Lite Edition.

The Intel Quartus Prime Pro Edition is optimized to support the advanced features in Intel's next generation FPGAs and SoCs.

The Intel Stratix 10 MX FPGA is only supported on Intel Quartus Prime Pro Edition. There is no paid license fee required for Intel Stratix 10 support in Intel Quartus Prime Pro Edition.

Included in the Intel Quartus Prime Pro Edition are the Intel Quartus Prime software, Nios® II EDS and the Intel FPGA IP Library.

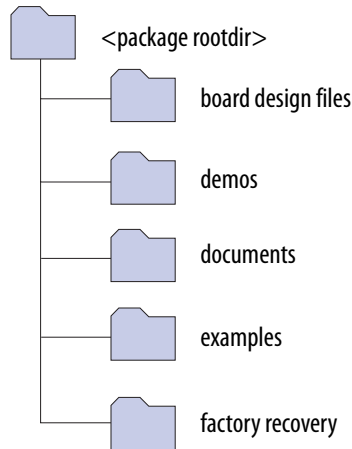
To install Intel's development tools, download the Intel Quartus Prime Pro Edition software from the Quartus Prime Pro Edition page from the [Download Center](#) of Intel's website.

2.2. Development Kit Package

To download the Intel Stratix 10 MX FPGA Development Kit package, perform the following steps:

1. Download the development kit package from the Intel Stratix 10 MX FPGA Development Kit link (provided below) on the Intel website.
2. Unzip the Intel Stratix 10 MX FPGA Development Kit package contents to your machine's local hard drive.
3. The package creates the directory structure shown in the figure below.

Figure 2. Development Kit Directory Structure



The table below lists the file directory names and a description of their contents

Table 2. Installed Development Kit Directory Structure

Directory Name	Description of Directory Contents
board_design_files	Contains schematics, layout, assembly and bill of material board design files. Use these files as a starting point for a new prototype board design
demos	Contains demonstration applications when available
documents	Contains the development kit documentation
examples	Contains the sample design files for the development kit
factory_recovery	Contains the original data programmed onto the board before shipment. Use this data to restore the board with its original factory contents.

Note: To view the layout *.brd files in the board package, you can download the Cadence® Allegro®/OrCAD® Free Viewer from Cadence's website.

Related Information

- [Intel Stratix 10 MX FPGA Development Kit](#)
The downloadable development kit package is in Table #3 at the link provided on Intel website.
- [Cadence Allegro Downloads](#)

2.3. Installing the Intel FPGA Download Cable Driver

The Intel Stratix 10 MX FPGA Development Kit includes embedded Intel FPGA Download Cable circuits for FPGA programming. However, for the host computer and board to communicate, you must install the Intel FPGA Download Cable driver on the host computer.

Installation instructions for the Intel FPGA Download Cable driver for your operating system are available on the Intel website.



On the Intel website, navigate to the [Cable and Adapter Drivers Information](#) link to locate the table entry for your configuration and click the link to access the instructions.



3. Development Kit Setup

This chapter describes how to apply power to the development board and provides default switch and jumper settings.

3.1. Applying Power to the Development Kit

This development kit is designed to operate in two modes:

As a PCIe add-in card

When operating the card as a PCIe system, insert the card into an available PCIe slot and connect a 2x4 pin PCIe power cable from the system to the power connectors at Aux power connector J11 of the board.

Note: When operating as a PCIe add-in card, the board does not power on unless power is supplied to J11.

In bench-top mode

In bench-top mode, you must supply the board with the provided 240 W power supply connected to the Aux power connector J11, as follows

Note: This development board ships with its switches preconfigured to support the design examples in the kit. If you suspect that your board may not be correctly configured with the default settings, follow the instructions in the [Default Switch and Jumper Settings](#) on page 11 of this chapter.

1. Connect the provided power supply to an outlet and the DC Power Jack (J11) on the FPGA board.

Note: Use only the supplied power supply. Power regulation circuits on the board can be damaged by power supplies with greater voltage.

2. Set the power switch (SW3) to the ON position.

When the board powers up, the blue power LED illuminates and the board is ready for use.



3.2. Default Switch and Jumper Settings

Figure 3. Default Switch Settings

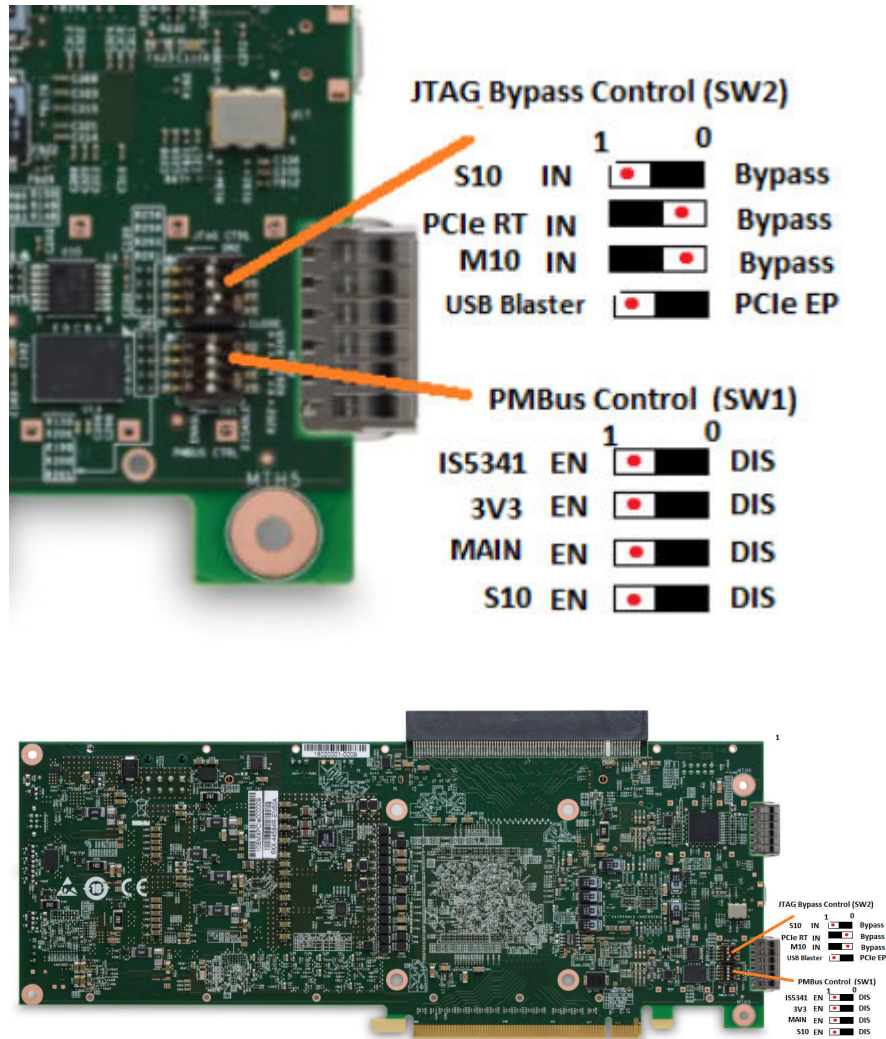




Table 3. SW2 DIP JTAG Switch Default Settings (Board Bottom)

Switch	Board Label	Function	Default Position
1	JTAG INPUT	JTAG Source Select	OFF (On-board Intel FPGA Download Cable)
2	M10	Intel MAX [®] 10 JTAG	ON (JTAG OUT)
3	PCIE RT	PCIe Root Port JTAG	ON (JTAG OUT)
4	S10	Intel Stratix 10 FPGA JTAG	OFF (JTAG IN)

Table 4. SW1 DIP PMBus Switch Default Settings (Board Bottom)

Switch	Board Label	Function	Default Position
1	SI5341 I2C BUS	Clock Generator I ² C Bus	OFF (Enable)
2	3V3 I2C BUS	3V3 VRM I ² C BUS	OFF (Enable)
3	MAIN I2C BUS	MAIN I ² C BUS	OFF (Enable)
4	S10 PMBus	Intel Stratix 10 FPGA PMBus	OFF (Enable)

4. Development Kit Components

This chapter introduces all the important components on the development kit. A complete set of schematics, a physical layout database and Gerber files for the development board reside in the development kit documents directory.

Figure 4. Intel Stratix 10 MX FPGA Development Kit - Front

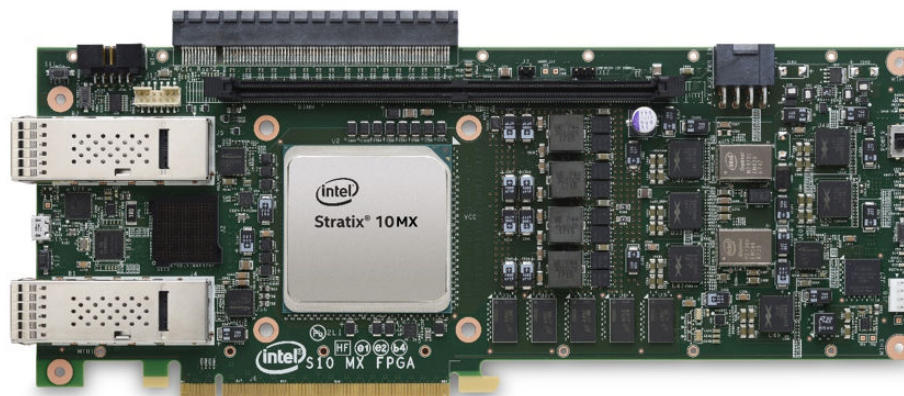
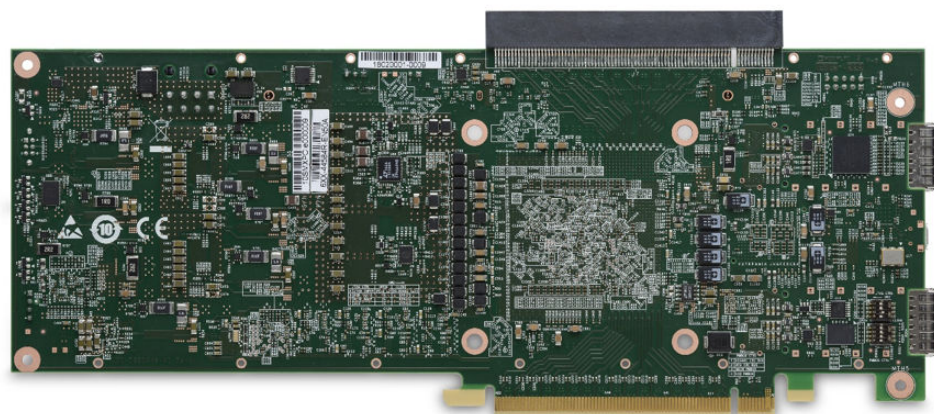


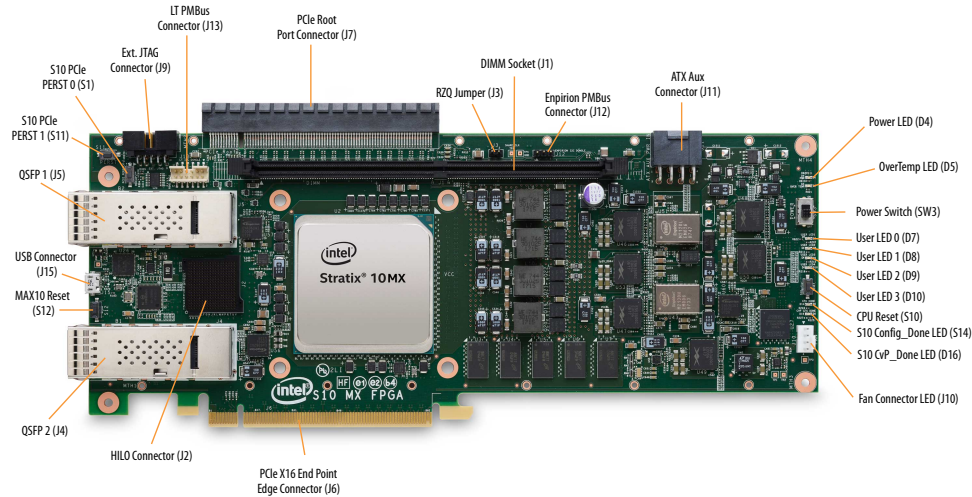
Figure 5. Intel Stratix 10 MX FPGA Development Kit - Rear



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*Other names and brands may be claimed as the property of others.

Figure 6. Intel Stratix 10 MX FPGA Development Kit Picture



4.1. Components Overview

Table 5. Development Kit Components Table

Board Reference	Type	Description
Featured Devices		
U1	FPGA	Intel Stratix 10 MX FPGA ⁽¹⁾ <ul style="list-style-type: none"> Adaptive Logic Modules (ALM): 702,720 Logic Elements (LE): 2,073K Registers: 2,810,880 M20K Memory Blocks: 6,847 Transceiver Count: 96 Package Type: 2597 BGA HMB2 DRAM (GB): 8 or 16
U11	FPGA	Intel MAX 10 FPGA, 4K LEs, 169 FBGA (System)
U27	FPGA	Intel MAX 10, 16K LEs, 169 FBGA (Power)
Configuration and Setup Elements		
J15	On-board Intel FPGA Download Cable II	Micro-USB 2.0 connector for programming and debugging the FPGA.
SW2	JTAG Bypass DIP Switch	Enable and disable devices in the JTAG chain. This switch is located on the back of the board.
<i>continued...</i>		

(1) Refer to [Overview](#) on page 4 for the part number for your specific board



Board Reference	Type	Description
SW1	I ² C Bus Selection Switch	Enable or Disable the I ² C Bus for Clock chip, 3.3 V VRM, Main I ² C, and Intel Stratix 10 FPGA
S10	CPU reset push button	The default reset for the FPGA logic.
S1	PCIe PERST 0 push button	This push button connects to Intel Stratix 10 FPGA's NPERSTL0 pin.
S11	PCIe PERST 1 push button	This push button connects to Intel Stratix 10 FPGA's NPERSTR1 pin.
S12	Intel MAX 10 Reset Push Button	The default reset for the Intel MAX 10 FPGA System Controller
Status Elements		
D14	Configuration Done LED	Illuminates when FPGA configuration is completed
D16	CvP Done LED	Illuminates when CvP process is completed
D4	Power LED (Blue)	Illuminates when board is powered on.
D5	Temperature LED (Green)	Illuminates when an over temperature condition occurs for the FPGA device. Ensure that an adequate heatsink/fan is properly installed.
D7, D8, D9, D10	User-defined LEDs	Four green color user LEDs. Illuminate when driven low.
Clock Circuits		
U17	Intel MAX 10 Reference Clock	Si510 Crystal Oscillator provides reference clocks for Intel MAX 10 devices Default Frequencies are: <ul style="list-style-type: none"> • Out0= 50.00 MHz • Out1= 50.00 MHz
U16	Programmable Clock Generator	Si5341A Programmable Clock Generator by the clock control GUI Default Frequencies are: <ul style="list-style-type: none"> • Out0= 644.53125 MHz • Out1= 644.53125 MHz • Out2= 100 MHz • Out3= 100 MHz • Out4= 100 MHz • Out5= 100 MHz • Out6= 100 MHz • Out7= 100 MHz • Out8= 100 MHz • Out9= 100 MHz
U18	Programmable Clock Generator	Si5338A Programmable Clock Generator by the Clock Control GUI Default Frequencies are: <ul style="list-style-type: none"> • CLK0= 50 MHz • CLK1= 100 MHz • CLK2= 125 MHz • CLK3= 100 MHz
<i>continued...</i>		



Board Reference	Type	Description
U19	Programmable Clock Generator	Si5338B Programmable Clock Generator by the Clock Control GUI Default Frequencies are: <ul style="list-style-type: none"> • CLK0= 133.333 MHz • CLK1= 133.333 MHz • CLK2= 133.333 MHz • CLK3= Not Used
Transceiver Interfaces		
J6	PCIe x16 gold fingers	PCIe TX/RX x16 interface from FPGA bank 1C, 1D, 1E
J7	PCIe x16 Root Port Connector	PCIe TX/RX x16 interface from FPGA bank 4C, 4D, 4E
J4	QSFP Connector	Four TX/RX channels from FPGA Bank 1F
J5	QSFP Connector	Four TX/RX channels from 4F from FPGA bank 4F
General User Input/Output		
D7, D8, D9, D10	User defined LEDs	Four green color user LEDs. Illuminates when driven low.
Memory Devices		
J2	HiLo Connector	One x72 memory interface supporting DDR3 (x72), DDR4 (x72), QDR-IV (x36) and RDRAM3 (x36). This development kit includes one plugin modules (daughtercards) that use the HiLo connector: DDR4 memory (x72) 1333 MHz
J1	DDR4, DDR-T, DIMM Socket	One X72 memory interface supporting DDR4 (x72) or DDR-T memory module. <ul style="list-style-type: none"> • DDR4 memory (x72) 1333 MHz • DDR-T memory (requires DDR-T IP)
U3, U4, U5, U6, U7	On-board DDR4 memory	On-board DDR4 memory (x72) 1333 MHz
Communication Ports		
J6	PCI Express* x16 Edge Connector	Gold-plated edge fingers for up to x16 signaling in either Gen1, Gen3 or Gen3 mode.
J7	PCI Express x16 Root Port Connector	Standard PCI Express Gen3 x16 Connector for connecting PCIe Endpoint card.
J4	QSFP interface	Provides four transceiver channels per port for a 100G QSFP module
J5	QSFP interface	Provides four transceiver channels per port for a 100G QSFP module
J13	Linear Tech VRM PMBus Port	Provides PMBus connection using dongle from Linear Tech.
J12	Enpirion VRM PMBus Port	Provides PMBus connection using dongle from Intel Enpirion®
<i>continued...</i>		



Board Reference	Type	Description
J9	External JTAG Port	This port allows the use of Intel FPGA Download Cable II dongle to access the JTAG links on the board. Connection to this port automatically disable the internal Intel FPGA Download Cable II JTAG.
J15	Micro-USB Connector	Embedded Intel FPGA Download Cable II JTAG for programming the FPGA via a USB cable.
Power Supply		
J6	PCI Express edge connector	Interfaces to a PCI Express root port such as an appropriate PC motherboard.
J11	DC Input Jack	Accepts a 12 V DC power supply when powering the board from the provided power brick for lab bench operation. When operating from the PCIe slot, this input must also be connected to the 8-pin Aux PCIe power connector provided by the PC system along with J11, or else the board does not power on.
SW3	Power Switch	Switch to power ON or OFF the board when supplied from the DC input jack.

Related Information

[Overview](#) on page 4

4.2. Intel MAX 10 FPGA System Controller

This development kit utilizes the Intel MAX 10 FPGA (10M04SCU169) as system controller for the following purposes:

- On-board Intel FPGA Download Cable
- JTAG Switch
- I²C Bus Control
- Control registers for all programmable clocks
- Control registers for QSFP and PCIe interfaces

Table 6. Intel MAX 10 FPGA System Controller Device Pin Table

Schematic Signal Name	Pin Number	I/O Standard	Description
FX2_PA0	K6	3.3V	Intel MAX 10 to USB PHY Download Cable bus A
FX2_PA1	M4	3.3V	Intel MAX 10 to USB PHY Download Cable bus A
FX2_PA2	M5	3.3V	Intel MAX 10 to USB PHY Download Cable bus A
FX2_PA3	K5	3.3V	Intel MAX 10 to USB PHY Download Cable bus A
<i>continued...</i>			



Schematic Signal Name	Pin Number	I/O Standard	Description
FX2_PA4	L4	3.3V	Intel MAX 10 to USB PHY Download Cable bus A
FX2_PA5	J5	3.3V	Intel MAX 10 to USB PHY Download Cable bus A
FX2_PA6	N4	3.3V	Intel MAX 10 to USB PHY Download Cable bus A
FX2_PA7	J7	3.3V	Intel MAX 10 to USB PHY Download Cable bus A
FX2_PB0	K7	3.3V	Intel MAX 10 to USB PHY Download Cable bus B
FX2_PB1	N9	3.3V	Intel MAX 10 to USB PHY Download Cable bus B
FX2_PB2	N7	3.3V	Intel MAX 10 to USB PHY Download Cable bus B
FX2_PB3	N6	3.3V	Intel MAX 10 to USB PHY Download Cable bus B
FX2_PB4	M13	3.3V	Intel MAX 10 to USB PHY Download Cable bus B
FX2_PB5	N5	3.3V	Intel MAX 10 to USB PHY Download Cable bus B
FX2_PB6	M9	3.3V	Intel MAX 10 to USB PHY Download Cable bus B
FX2_PB7	M11	3.3V	Intel MAX 10 to USB PHY Download Cable bus B
USB_MAX_TCK	G2	3.3V	Intel MAX 10 JTAG to USB PHY FX2_PD0
USB_MAX_TMS	G1	3.3V	Intel MAX 10 JTAG to USB PHY FX2_PD1
USB_MAX_TDI	F5	3.3V	Intel MAX 10 JTAG to USB PHY FX2_PD2
USB_MAX_TDO	F6	3.3V	Intel MAX 10 JTAG to USB PHY FX2_PD3
FX2_PD4	N8	3.3V	Intel MAX 10 to USB PHY Download Cable bus D
FX2_PD5	M7	3.3V	Intel MAX 10 to USB PHY Download Cable bus D
FX2_PD6	M8	3.3V	Intel MAX 10 to USB PHY Download Cable bus D
FX2_PD7	J6	3.3V	Intel MAX 10 to USB PHY Download Cable bus D
FX2_RESETn	N3	3.3V	USB PHY Reset
FX2_FLAGA	J8	3.3V	USB PHY FIFO output Flag signal to Intel MAX 10
FX2_FLAGB	L5	3.3V	USB PHY FIFO output Flag signal to Intel MAX 10
FX2_FLAGC	L11	3.3V	USB PHY FIFO output Flag signal to Intel MAX 10
continued...			

4. Development Kit Components

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Schematic Signal Name	Pin Number	I/O Standard	Description
FX2_SLRDn	M12	3.3V	USB PHY Read signal
FX2_SLWRn	N10	3.3V	USB PHY Write signal
FX2_SCL	K8	3.3V	USB PHY I ² C signal
FX2_SDA	L10	3.3V	USB PHY I ² C signal
USB_T_CLK	H6	3.3V	Interface Clock from USB PHY
USB_DISABLEn	N2	3.3V	External JTAG signal to Intel MAX 10 for disabling internal USB Blaster circuit
EM_PMBUS_ALERTn	L1	3.3V	PMBus Alert signal from Intel Enpirion Power Regulator
LT_PMBUS_ALERTn	N11	3.3V	PMBus Alert signal from LT Power regulator
ZQSFP0_1V8_RESET_L	K10	1.8V	QSFP module 0 Reset signal (Intel MAX 10 to FPGA)
ZQSFP0_1V8_MODPRS_L	K11	1.8V	QSFP module 0 control signal (Intel MAX 10 to FPGA)
ZQSFP0_1V8_LPMODE	J10	1.8V	QSFP module 0 Low Power signal (Intel MAX 10 to FPGA)
ZQSFP0_1V8_INT_L	L12	1.8V	QSFP module 0 interrupt signal (Intel MAX 10 to FPGA)
ZQSFP0_1V8_MODSEL_L	H9	1.8V	QSFP module 0 Mode Select signal (Intel MAX 10 to FPGA)
ZQSFP1_1V8_RESET_L	K12	1.8V	QSFP module 1 Reset signal (Intel MAX 10 to FPGA)
ZQSFP1_1V8_MODPRS_L	L13	1.8V	QSFP module 1 Present signal (Intel MAX 10 to FPGA)
ZQSFP1_1V8_LPMODE	J12	1.8V	QSFP module 1 Low Power signal (Intel MAX 10 to FPGA)
ZQSFP1_1V8_INT_L	J9	1.8V	QSFP module 1 interrupt signal (Intel MAX 10 to FPGA)
ZQSFP1_1V8_MODSEL_L	G13	1.8V	QSFP module 1 Mode Select signal (Intel MAX 10 to FPGA)
ZQSFP0_3V3_RESET_L	B10	3.3V	QSFP module 0 Reset signal to Intel MAX 10
ZQSFP0_3V3_MODPRS_L	A10	3.3V	QSFP module 0 control signal to Intel MAX 10
ZQSFP0_3V3_LPMODE	A11	3.3V	QSFP module 0 Low Power signal to Intel MAX 10

continued...



Schematic Signal Name	Pin Number	I/O Standard	Description
ZQSFP0_3V3_INT_L	E8	3.3V	QSFP module 0 interrupt signal to Intel MAX 10
ZQSFP0_3V3_MODSEL_L	A3	3.3V	QSFP module 0 Mode Select signal to Intel MAX 10
ZQSFP1_3V3_RESET_L	A7	3.3V	QSFP module 1 Reset signal to Intel MAX 10
ZQSFP1_3V3_MODPRS_L	A6	3.3V	QSFP module 1 Present signal to Intel MAX 10
ZQSFP1_3V3_LPMODE	B6	3.3V	QSFP module 1 Low Power signal to Intel MAX 10
ZQSFP1_3V3_INT_L	A4	3.3V	QSFP module 1 interrupt signal to Intel MAX 10
ZQSFP1_3V3_MODSEL_L	B5	3.3V	QSFP module 1 Mode Select signal to Intel MAX 10
PCIE_RT_JTAG_TCK	C10	3.3V	PCIe Root Port JTAG signal
PCIE_RT_JTAG_TDI	A8	3.3V	PCIe Root Port JTAG signal
PCIE_RT_JTAG_TMS	C9	3.3V	PCIe Root Port JTAG signal
PCIE_RT_JTAG_TDO	A9	3.3V	PCIe Root Port JTAG signal
PCIE_RT_JTAG_TRSTn	B2	3.3V	PCIe Root Port JTAG signal
PCIE_RT_PERSTn	D1	3.3V	PCIe Root Port signal
PCIE_RT_PRSN2n	C2	3.3V	PCIe Rootport signal
PCIE_RT_S10_PERSTn	F12	1.8V	PCIe Root Port signal (Intel MAX 10 to FPGA)
PCIE_RT_S10_PRSN2n	E12	1.8V	PCIe Rootport signal (Intel MAX 10 to FPGA)
PCIE_RT_WAKEN	B4	3.3V	PCIe Rootport Wake signal
PCIE_EP_JTAG_TCK	E3	3.3V	PCIe EndPoint JTAG signal
PCIE_EP_JTAG_TDI	F1	3.3V	PCIe EndPoint JTAG signal
PCIE_EP_JTAG_TMS	C1	3.3V	PCIe EndPoint JTAG signal
PCIE_EP_JTAG_TDO	F4	3.3V	PCIe EndPoint JTAG signal
S10_CVP_CONFDONE	E9	1.8V	CVP_CONFDONE signal from FPGA to Intel MAX 10
S10_CONF_DONE	B11	1.8V	CONF_DONE signal from FPGA to Intel MAX 10
S10_INIT_DONE	C12	1.8V	INIT_DONE signal from FPGA to Intel MAX 10
CPU_RESETh	C13	1.8V	RESETh signal from Intel MAX 10 to FPGA
S10_NCONFIG	D9	1.8V	N_CONFIG signal from Intel MAX 10 to FPGA
SI5341_ENn	B13	1.8V	Clock enable signal
SI5341_RSTn	C11	1.8V	Check chip reset
continued...			



Schematic Signal Name	Pin Number	I/O Standard	Description
SI5341_FINC	A12	1.8V	Clock Frequency increment control
SI5341_FDEC	E10	1.8V	Clock Frequency decrement control
EXT_JTAG_TDI	L3	3.3V	External JTAG signal
EXT_JTAG_TCK	J1	3.3V	External JTAG signal
EXT_JTAG_TMS	M2	3.3V	External JTAG signal
EXT_JTAG_TDO	K2	3.3V	External JTAG signal
PWR_MAX10_BYPASSn	J2	3.3V	Power Intel MAX 10 JTAG Bypass input (select by Dip switch SW2-2)
PCIE_RT_BYPASSn	M2	3.3V	PCIe Root Port JTAG Bypass input (select by Dip Switch SW2-3)
S10_BYPASSn	E4	3.3V	FPGA JTAG Bypass input (select by Dip Switch SW2-4)
JTAG_INPUT_SOURCE	M3	3.3V	JTAG input source selection, SW2-1 select between external JTAG or PCIe EP JTAG
PCIE_EP_3V3_I2C_SDA	L2	3.3V	I ² C bus from PCIE_End Point
PCIE_EP_3V3_I2C_SCL	K1	3.3V	I ² C bus from PCIE_End Point
MAIN_I2C_SCL	F8	1.8V	Main I ² C bus (Intel MAX 10)
MAIN_I2C_SDA	B12	1.8V	Main I ² C bus (Intel MAX 10)
3V3_I2C_EN	H3	3.3V	This Intel MAX 10 signal controls U22 that allows 3V3_I2C bus connect to the Main I ² C bus
S10_PMBUS_EN	G4	3.3V	This Intel MAX 10 signal controls U20 that allows CORE_PMBus connect to the S10 SDM I ² C bus
MAIN_PMBUS_EN	H2	3.3V	This Intel MAX 10 signal controls U21 that allows CORE_PMBus connect to MAIN I2C bus
PWR_GOOD	E1	3.3V	Power Good signal from Intel MAX 10 Power

4.3. Intel MAX 10 FPGA Power Manager

This development kit utilizes the Intel MAX 10 FPGA 10M16SAU169 FPGA as Power Manager (U27) for the following purposes:



- Power Sequencing Control
- Power Discharging Control
- Voltage Monitoring
- Fan Control

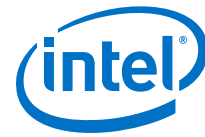
Table 7. Intel MAX 10 FPGA Power Manager Pin Table

Schematic Signal Name	Pin Number	I/O Standard	Description
3p3V_EN	L5	3.3V	Enable or disable 3.3V power rail
S10_VCC_EN	M4	3.3V	Enable or disable FPGA Core power rail
S10_VCCERAM_EN	L4	3.3V	Enable or disable VCCERAM power rail
S10_VCCRL_EN	M5	3.3V	Enable or disable Left side Receiver Power VCCRL power rail
S10_VCCRR	K5	3.3V	Enable or disable Right side Receiver Power VCCRR power rail
S10_VCCT	N4	3.3V	Enable or disable Transmitter Power VCCT power rail
1p8V_EN	J5	3.3V	Enable or disable 1.8V power rail
VCCIO_UIB_EN	N5	3.3V	Enable or disable VCCIO_UIB power rail
VCCM_EN	N6	3.3V	Enable or disable VCCM power rail
1p2V_DDR4_EN	N7	3.3V	Enable or disable 1.2V for DDR4 power rail
HILO_VDDQ_EN	M7	3.3V	Enable or disable VDDQ power rail for HILO memory
HILO_VDD_EN	N8	3.3V	Enable or disable VDD power rail for HILO memory
2p5V_EN	J6	3.3V	Enable or disable 2.5V power rail
ZQSFP0_PWR_EN	M8	3.3V	Enable or disable the power to QSFP_0 module
ZQSFP1_PWR_EN	K6	3.3V	Enable or disable the power to QSFP_1 module
DIMM_VTT_EN	M9	3.3V	Enable or disable the termination power for DDR4 DIMM
COMP_VTT_EN	J7	3.3V	Enable or disable the termination power for on-board DDR4 memory
POWER_ON	M13	3.3V	Signal from power input circuit to Intel MAX 10 for starting power sequencing

continued...

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Schematic Signal Name	Pin Number	I/O Standard	Description
1p2V_DDR4_DIS	N2	3.3V	Signal to enable discharge circuit for 1.2 V DDR4 power rail
VCCIO_UIB_DIS	N3	3.3V	Signal to enable discharge circuit for 1.2 V VCCIO UIB power rail
HILO_VDD_DIS	M11	3.3V	Signal to enable discharge circuit for HILO VDD power rail
HILO_VDDQ_DIS	L11	3.3V	Signal to enable discharge circuit for HILO VDDQ power rail
VCCM_DIS	K8	3.3V	Signal to enable discharge circuit for HBM's VCCM power rail
1p8V_DIS	G9	3.3V	Signal to enable discharge circuit for 1.8 V power rail
VCCRL_GXB_DIS	G10	3.3V	Signal to enable discharge circuit for VCCRL_GXB power rail
VCCRR_GXB_DIS	F13	3.3V	Signal to enable discharge circuit for VCCRR_GXB power rail
VCCT_DIS	E13	3.3V	Signal to enable discharge circuit for VCCT_GXB power rail
VCCERAM_DIS	F9	3.3V	Signal to enable discharge circuit for VCCERAM power rail
2p5V_DIS	F10	3.3V	Signal to enable discharge circuit for 2.5V power rail
3p3V_DIS	C10	3.3V	Signal to enable discharge circuit for 3.3V power rail
I2C_3V3_SDA	M12	3.3V	I2C signals
I2C_3V3_SCL	N9	3.3V	I2C signals
PWR_MAX10_JTAG_TMS	G1	3.3V	JTAG signals
PWR_MAX10_JTAG_TCK	G2	3.3V	JTAG signals
PWR_MAX10_JTAG_TDI	F5	3.3V	JTAG signals
PWR_MAX10_JTAG_TDO	F6	3.3V	JTAG signals
3p3V_PG	A6	3.3V	Power Good signal from 3.3V power supply
S10_VCC_PG	A9	3.3V	Power Good signal from VCC Core power supply
S10_VCCERAM_PG	B10	3.3V	Power Good signal from VCCERAM power supply
S10_VCCRL_PG	A10	3.3V	Power Good signal from VCCRL power supply

continued...



Schematic Signal Name	Pin Number	I/O Standard	Description
S10_VCCRR_PG	A11	3.3V	Power Good signal from VCCRR power supply
S10_VCCT_PG	E8	3.3V	Power Good signal from VCCT power supply
1p8V_PG	A4	3.3V	Power Good signal from 1.8V power supply
1p2V_VCCIO_UIB_PG	A7	3.3V	Power Good signal from VCCIO_UIB power supply
VCCM_PG	A4	3.3V	Power Good signal from VCCM power supply
HILO_VDD_PG	B5	3.3V	Power Good signal from VDD power supply for HILO
HILO_VDDQ_PG	A3	3.3V	Power Good signal from VDDQ power supply for HILO
1p2V_DDR4_PG	E6	3.3V	Power Good signal from 1.2V power supply for DDR4 Memory
12V_G1_PG	F12	3.3V	Power Good signal from 12V Group1 of input power circuit
12V_G2_PG	E12	3.3V	Power Good signal from 12V Group2 of input power circuit
5V_PG	C13	3.3V	Power Good signal from 5V power supply
2p5V_PG	E10	3.3V	Power Good signal from 2.5V power supply
COMP_VTT_PG	F8	3.3V	Power Good signal from on-board DDR4 termination power supply
DIMM_VTT_PG	B13	3.3V	Power Good signal from DIMM DDR4 termination power supply
12V_G1_UV_PG	D9	3.3V	Power Good signal from 12V Group 1's Under-Voltage monitor
12V_G1_OV_PG	D12	3.3V	Power Good signal from 12V Group 1's Over-Voltage monitor
S10_VCCFAULT	B4	3.3V	Fault signal from FPGA VCC Core power supply
EM_PMBUS_ALERTn	B11	3.3V	Alert signal from Enpirion power regulators
LT_PMBUS_ALERTn	C12	3.3V	Alert signal from Linear Technology power regulators
ZQSFP0_FAULT_N	C11	3.3V	Fault signal from QSFP_0 module
ZQSFP1_FAULT_N	A12	3.3V	Fault signal from QSFP_1 module
continued...			



Schematic Signal Name	Pin Number	I/O Standard	Description
PCIE_RT_PRSNT2n	D11	3.3V	PCIE Root Port Present signal
PCIE_EP_PERSTN	H4	3.3V	PCIE End Point Present signal
PWR_LED_DR	B12	3.3V	Power LED drive signal
PWR_GOOD	E9	3.3V	Power Good signal of all power supplies to Intel MAX 10 System Controller
OVERTEMPn	K11	3.3V	Over Temperature signal from Board Temp sensor chip U29
TSENSE_ALERTn	L12	3.3V	Temperature Sense Alert signal from Board Temp sensor chip U29
FAN_CTRL	K12	3.3V	Fan speed control signal to cooling fans driver
S10MX_VCC	D2	Analog	FPGA Core Voltage sensing input
S10_VCCERAM	D1	Analog	VCCERAM Voltage sensing input
S10_VCCRL_GXB	C2	Analog	FPGA Left side receiver voltage sensing input
S10_VCCRR_GXB	E3	Analog	FPGA Right side receiver voltage sensing input
S10_VCCT_GXB	E4	Analog	FPGA Transmitter voltage sensing input
1p2V_VCCIO_UIB	C1	Analog	1.2V VCCIO UIB Voltage sensing input
1p8V	B1	Analog	1.8V Voltage sensing input
1p2V_DDR4	F1	Analog	1,2V for DDR4 voltage sensing input
VCCM	E1	Analog	VCCM for HMB voltage sensing input

4.4. FPGA Configuration

You can use the Intel Quartus Prime Programmer to configure the FPGA with your SRAM Object File (.sof).

Ensure the following

- The Intel Quartus Prime Programmer is installed on your PC.
- The micro-USB cable is connected to the FPGA development board.
- Power to the board is ON, and no other applications that use the JTAG chain are running.

Steps

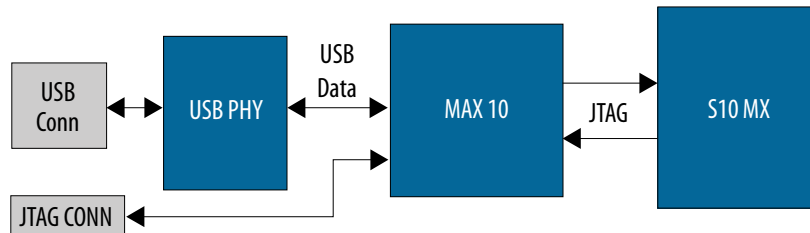
1. Start the Intel Quartus Prime Programmer.
2. Click **Auto Detect** to display the devices in the JTAG chain.
3. Click **Change File** and select the path to the desired .sof.
4. Turn on the **Program/Configure** option for the added file.
5. Click **Start** to download the selected file to the FPGA. Configuration is complete when the progress bar reaches 100%.

Using the Intel Quartus Prime Programmer to configure a device on the board causes other JTAG based applications such as the Board Test System and the Power Monitor to lose their connection to the board. Restart those applications after configuration is complete.

Programming the FPGA over Intel FPGA Download Cable II

The figure below shows the high-level conceptual block diagram for programming the Intel Stratix 10 MX FPGA over the embedded Intel FPGA Download Cable II or External Intel FPGA Download Cable II.

Figure 7. Embedded Intel FPGA Download Cable Conceptual Block Diagram



Connection on the external JTAG header (J9) automatically disables the on-board JTAG Intel FPGA Download Cable II. This allows the use of an external USB JTAG dongle to access the JTAG bus on the board.

Supported Configuration Modes

This development kit supports two configuration modes: Active Serial x4 (AS x4) and JTAG. The default configuration is AS x4 using a 2 Gb QSPI Flash device. JTAG configuration is supported by using either the on-board Intel FPGA Download Cable II or the through an external Intel FPGA Download Cable II dongle.

Active Serial x4 Mode

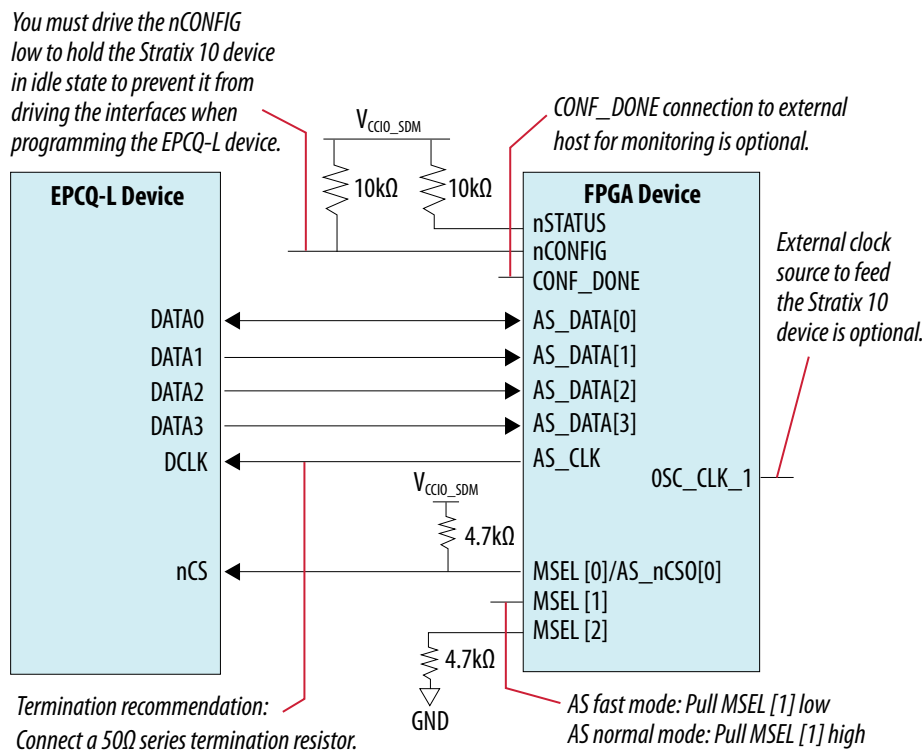
The Secure Device Manager (SDM) block in the Intel Stratix 10 MX FPGA device controls the configuration process and interface. The flash memory is a Micron Technology 1.8 V core, 1.8 V I/O 2 Gigabit CFI NOR-type device (P/N: MT25Qu02GCBB3E12). For AS x4 Fast modes, **MSEL [2:0]** signals need to be set according to the table below. Not all modes are supported. AS x4 is the default configuration mode.



Table 8. Active Serial Mode

Configuration Scheme	MSEL [2:0]
Avalon-ST (x32)	000 (Not Supported)
Avalon-ST (x16)	101 (Not Supported)
Avalon-ST (x8)	110 (Not Supported)
AS (Fast Mode for CvP)	001
AS (Normal Mode)	011 (Not Supported)
NAND x8	010 (Not Supported)
SD/MMC x4/x8	100 (Not Supported)
JTAG only	111

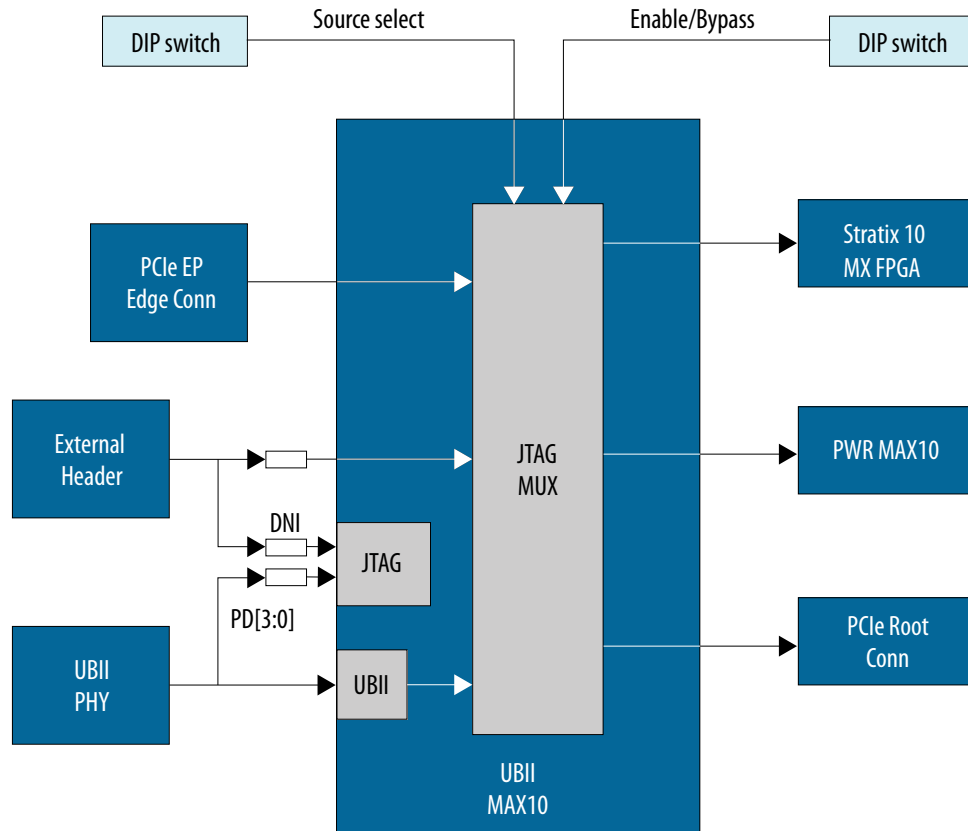
Figure 8. AS x4 Configuration Conceptual Block Diagram



JTAG Configuration Mode

The JTAG Switch implemented in the Intel MAX 10 System Control FPGA (U24) allows the selection of the device(s) to be included in the JTAG chain. It is done by the settings of the DIP switch SW2. The embedded Intel FPGA Download Cable (or external Intel FPGA Download Cable) or PCIe JTAG can be selected as the source for programming the device(s) on the chain. The embedded Intel FPGA Download Cable is the default setting for this configuration mode.

Figure 9. JTAG Chain Conceptual Block Diagram



Note: AS x4 is default configuration mode. Changing to JTAG mode requires changing pull-up/pull-down resistors for the MSEL lines on the board. Please refer to the board schematics and layout for detailed resistor locations.

4.5. Status and User I/O Elements

The Intel Stratix 10 MX FPGA development kit includes status LEDs as listed below.

Table 9. Board-Specific Status LEDs

Board Reference	Schematic Signal Name	FPGA Pin Number	I/O Standard
D14	S10_CONF_DONE	AY39	1.8 V
D16	S10_CVP_CONFDONE	BC42	1.8 V
D5	OVERTEMPn	K11 (MAX10_U27)	1.8 V
D4	PWR_LED_DR	B12 (MAX10_U27)	1.8 V

**Table 10. Board-Specific Push Buttons**

Board Reference	Schematic Signal Name	FPGA Pin Number	I/O Standard
S1	S10_PCIE_PERST_0	AH39	1.8 V
S11	S10_PCIE_PERST_1	BL10	1.8 V
S12	MAX10_Reset	N3 (MAX10_U24)	1.8 V
S10	CPU_Reset	BL14	1.8 V

User-Defined LEDs

The Intel Stratix 10 MX FPGA development kit includes a set of four user-defined LEDs. The LEDs illuminate (turn ON) when a logic 0 is driven, and turn OFF when a logic 1 is driven. There are no board-specific functions for these LEDs.

Table 11. User-Defined LEDs

Board Reference	Schematic Signal Names	FPGA Pin Number	I/O Standard
D7	S10_LED0	BG12	1.8 V
D8	S10_LED1	BF12	1.8 V
D9	S10_LED2	BG11	1.8 V
D10	S10_LED3	BH11	1.8 V

4.6. Interfaces and Ports

This section describes the development board's communication ports and interface cards relative to the Intel Stratix 10 MX FPGA device.

4.6.1. PCI Express

The Intel Stratix 10 MX FPGA development kit supports two PCI Express interfaces: PCI Express End Point via a standard PCI Express x16 Edge connector and PCI Express Root Port via a standard PCI Express x16 connector.

The Intel Stratix 10 MX FPGA development board is designed to fit entirely into a PC motherboard with a x16 PCI Express slot that can accommodate a full height, 3-slot long form factor add-in card. This interface uses the PCI Express hard IP block on the Intel Stratix 10 MX FPGA, saving logic resources for the user logic application. The PCI Express edge connector has a presence detect feature to allow the motherboard to determine if a card is installed.

The PCI Express interface supports bus width of x16 by using the PCIe Intel FPGA IP. The PCI Express edge connector has a connection speed of 2.5 Gbps/lane for a maximum of 40 Gbps full-duplex (Gen1), 5.0 Gbps/lane for maximum of 80 Gbps full-duplex (Gen 2), or 8.0 Gbps/lane for a maximum of 128 Gbps full-duplex (Gen3).

The power for the board can be sourced entirely from the PC host when installed into a PC motherboard with the PC's 2x4 ATX auxiliary power connected to the 12V ATX inputs (J11) of the Intel Stratix 10 MX development kit.



The REFCLK_PCIE_EP_EDGE_P/N signal is a 100 MHz differential input that is driven from the PC motherboard on to this board through the edge connector. This signal connects directly to an Intel Stratix 10 MX FPGA REFCLK input pin pair using DC coupling.

This clock is terminated on the motherboard, and therefore no on-board termination is required. This clock can have spread-spectrum properties that change its period between 9.847 ps and 10.203 ps.

The I/O standard is High-Speed Current Steering Logic (HCSL). The JTAG and SMB are optional signals in the PCI Express TDI to PCI Express TDO and are not used on this board. The SMB signals are wired to the Intel Stratix 10 MX FPGA but are not required for normal operation.

Table 12. PCI Express (J6) End Point Interface Pin Connections

Receive Bus	Schematic Signal Name	FPGA Pin Number	I/O Standard	Description
A11	PCIE_EP_PERST_N	-	-	Connect to PRSNT2n_x16 (pin B81)
B17	PCIE_PRSNT2n_X1	-	-	No connect
B31	PCIE_PRSNT2n_X4	-	-	No connect
B48	PCIE_PRSNT2n_X8	-	-	No connect
B81	PCIE_PRSNT2n_X16	-	-	Connect to PCIE_PRSNT1n (pin A11)
B15	PCIE_EP_TX_N0	BH44	1.4 V PCML	Transmit bus
B20	PCIE_EP_TX_N1	BJ46	1.4 V PCML	Transmit bus
B24	PCIE_EP_TX_N2	BG46	1.4 V PCML	Transmit bus
B28	PCIE_EP_TX_N3	BF44	1.4 V PCML	Transmit bus
B34	PCIE_EP_TX_N4	BE46	1.4 V PCML	Transmit bus
B38	PCIE_EP_TX_N5	BD44	1.4 V PCML	Transmit bus
B42	PCIE_EP_TX_N6	BB44	1.4 V PCML	Transmit bus
B46	PCIE_EP_TX_N7	BC46	1.4 V PCML	Transmit bus
B51	PCIE_EP_TX_N8	BA46	1.4 V PCML	Transmit bus
B55	PCIE_EP_TX_N9	AY44	1.4 V PCML	Transmit bus
B59	PCIE_EP_TX_N10	AW46	1.4 V PCML	Transmit bus
B63	PCIE_EP_TX_N11	AV44	1.4 V PCML	Transmit bus
B67	PCIE_EP_TX_N12	AU46	1.4 V PCML	Transmit bus
B71	PCIE_EP_TX_N13	AT44	1.4 V PCML	Transmit bus
B75	PCIE_EP_TX_N14	AR46	1.4 V PCML	Transmit bus
B79	PCIE_EP_TX_N15	AP44	1.4 V PCML	Transmit bus
B14	PCIE_EP_TX_P0	BH45	1.4 V PCML	Transmit bus
<i>continued...</i>				

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Receive Bus	Schematic Signal Name	FPGA Pin Number	I/O Standard	Description
B19	PCIE_EP_TX_P1	BJ47	1.4 V PCML	Transmit bus
B23	PCIE_EP_TX_P2	BG47	1.4 V PCML	Transmit bus
B27	PCIE_EP_TX_P3	BF45	1.4 V PCML	Transmit bus
B33	PCIE_EP_TX_P4	BE47	1.4 V PCML	Transmit bus
B37	PCIE_EP_TX_P5	BD45	1.4 V PCML	Transmit bus
B41	PCIE_EP_TX_P6	BB45	1.4 V PCML	Transmit bus
B45	PCIE_EP_TX_P7	BC47	1.4 V PCML	Transmit bus
B50	PCIE_EP_TX_P8	BA47	1.4 V PCML	Transmit bus
B54	PCIE_EP_TX_P9	AY45	1.4 V PCML	Transmit bus
B58	PCIE_EP_TX_P10	AW47	1.4 V PCML	Transmit bus
B62	PCIE_EP_TX_P11	AV45	1.4 V PCML	Transmit bus
B66	PCIE_EP_TX_P12	AU47	1.4 V PCML	Transmit bus
B70	PCIE_EP_TX_P13	AT45	1.4 V PCML	Transmit bus
B74	PCIE_EP_TX_P14	AR47	1.4 V PCML	Transmit bus
B78	PCIE_EP_TX_P15	AP45	1.4 V PCML	Transmit bus
A17	PCIE_EP_RX_N0	BL46	1.4 V PCML	Receive bus
A22	PCIE_EP_RX_N1	BK48	1.4 V PCML	Receive bus
A26	PCIE_EP_RX_N2	BH48	1.4 V PCML	Receive bus
A30	PCIE_EP_RX_N3	BG50	1.4 V PCML	Receive bus
A36	PCIE_EP_RX_N4	BF48	1.4 V PCML	Receive bus
A40	PCIE_EP_RX_N5	BE50	1.4 V PCML	Receive bus
A44	PCIE_EP_RX_N6	BD48	1.4 V PCML	Receive bus
A48	PCIE_EP_RX_N7	BC50	1.4 V PCML	Receive bus
A53	PCIE_EP_RX_N8	BB48	1.4 V PCML	Receive bus
A57	PCIE_EP_RX_N9	BA50	1.4 V PCML	Receive bus
A61	PCIE_EP_RX_N10	AY48	1.4 V PCML	Receive bus
A65	PCIE_EP_RX_N11	AW50	1.4 V PCML	Receive bus
A69	PCIE_EP_RX_N12	AV48	1.4 V PCML	Receive bus
A73	PCIE_EP_RX_N13	AU50	1.4 V PCML	Receive bus
A77	PCIE_EP_RX_N14	AT48	1.4 V PCML	Receive bus
A81	PCIE_EP_RX_N15	AR50	1.4 V PCML	Receive bus
A16	PCIE_EP_RX_P0	BL47	1.4 V PCML	Receive bus
A21	PCIE_EP_RX_P1	BK49	1.4 V PCML	Receive bus
A25	PCIE_EP_RX_P2	BH49	1.4 V PCML	Receive bus
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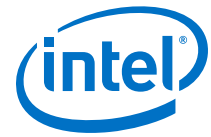
Receive Bus	Schematic Signal Name	FPGA Pin Number	I/O Standard	Description
A29	PCIE_EP_RX_P3	BG51	1.4 V PCML	Receive bus
A35	PCIE_EP_RX_P4	BF49	1.4 V PCML	Receive bus
A39	PCIE_EP_RX_P5	BE51	1.4 V PCML	Receive bus
A43	PCIE_EP_RX_P6	BD49	1.4 V PCML	Receive bus
A47	PCIE_EP_RX_P7	BC51	1.4 V PCML	Receive bus
A52	PCIE_EP_RX_P8	BB49	1.4 V PCML	Receive bus
A56	PCIE_EP_RX_P9	BA51	1.4 V PCML	Receive bus
A60	PCIE_EP_RX_P10	AY49	1.4 V PCML	Receive bus
A64	PCIE_EP_RX_P11	AW51	1.4 V PCML	Receive bus
A68	PCIE_EP_RX_P12	AV49	1.4 V PCML	Receive bus
A72	PCIE_EP_RX_P13	AU51	1.4 V PCML	Receive bus
A76	PCIE_EP_RX_P14	AT49	1.4 V PCML	Receive bus
A80	PCIE_EP_RX_P15	AR51	1.4 V PCML	Receive bus
B11	PCIE_EP_WAKEN	BH16	1.8V	Wake signal

Table 13. PCI Express Root Port Interface (J7) Pin Connections

Receive Bus	Schematic Signal Name	FPGA Pin Number	I/O Standard	Description
A1	PCIE_PRSNT1n	-	-	Connect to PCIE_PRSNT2n_X16
B17	PCIE_PRSNT2n_X1	-	-	No connect
B31	PCIE_PRSNT2n_X4	-	-	No connect
B48	PCIE_PRSNT2n_X8	-	-	No connect
B81	PCIE_PRSNT2n_X16	-	-	Connect to PCIE_PRSNT1n
B15	PCIE_RT_TX_N0	BL6	1.4 V PCML	Transmit bus
B20	PCIE_RT_TX_N1	BK4	1.4 V PCML	Transmit bus
B24	PCIE_RT_TX_N2	BH4	1.4 V PCML	Transmit bus
B28	PCIE_RT_TX_N3	BG2	1.4 V PCML	Transmit bus
B34	PCIE_RT_TX_N4	BF4	1.4 V PCML	Transmit bus
B38	PCIE_RT_TX_N5	BE2	1.4 V PCML	Transmit bus
B42	PCIE_RT_TX_N6	BD4	1.4 V PCML	Transmit bus
B46	PCIE_RT_TX_N7	BC2	1.4 V PCML	Transmit bus
B51	PCIE_RT_TX_N8	BB4	1.4 V PCML	Transmit bus
B55	PCIE_RT_TX_N9	BA2	1.4 V PCML	Transmit bus
B59	PCIE_RT_TX_N10	AY4	1.4 V PCML	Transmit bus
<i>continued...</i>				

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Receive Bus	Schematic Signal Name	FPGA Pin Number	I/O Standard	Description
B63	PCIE_RT_TX_N11	AW2	1.4 V PCML	Transmit bus
B67	PCIE_RT_TX_N12	AV4	1.4 V PCML	Transmit bus
B71	PCIE_RT_TX_N13	AU2	1.4 V PCML	Transmit bus
B75	PCIE_RT_TX_N14	AT4	1.4 V PCML	Transmit bus
B79	PCIE_RT_TX_N15	AR2	1.4 V PCML	Transmit bus
B14	PCIE_RT_TX_P0	BL5	1.4 V PCML	Transmit bus
B19	PCIE_RT_TX_P1	BK3	1.4 V PCML	Transmit bus
B23	PCIE_RT_TX_P2	BH3	1.4 V PCML	Transmit bus
B27	PCIE_RT_TX_P3	BG1	1.4 V PCML	Transmit bus
B33	PCIE_RT_TX_P4	BF3	1.4 V PCML	Transmit bus
B37	PCIE_RT_TX_P5	BE1	1.4 V PCML	Transmit bus
B41	PCIE_RT_TX_P6	BB8	1.4 V PCML	Transmit bus
B45	PCIE_RT_TX_P7	BC5	1.4 V PCML	Transmit bus
B50	PCIE_RT_TX_P8	BA5	1.4 V PCML	Transmit bus
B54	PCIE_RT_TX_P9	AY7	1.4 V PCML	Transmit bus
B58	PCIE_RT_TX_P10	AW5	1.4 V PCML	Transmit bus
B62	PCIE_RT_TX_P11	AV7	1.4 V PCML	Transmit bus
B66	PCIE_RT_TX_P12	AV3	1.4 V PCML	Transmit bus
B70	PCIE_RT_TX_P13	AU1	1.4 V PCML	Transmit bus
B74	PCIE_RT_TX_P14	At3	1.4 V PCML	Transmit bus
B78	PCIE_RT_TX_P15	AR1	1.4 V PCML	Transmit bus
A17	PCIE_RT_RX_N0	BH7	1.4 V PCML	Receive bus
A22	PCIE_RT_RX_N1	BJ5	1.4 V PCML	Receive bus
A26	PCIE_RT_RX_N2	BG5	1.4 V PCML	Receive bus
A30	PCIE_RT_RX_N3	BF7	1.4 V PCML	Receive bus
A36	PCIE_RT_RX_N4	BE5	1.4 V PCML	Receive bus
A40	PCIE_RT_RX_N5	BD7	1.4 V PCML	Receive bus
A44	PCIE_RT_RX_N6	BB7	1.4 V PCML	Receive bus
A48	PCIE_RT_RX_N7	BC6	1.4 V PCML	Receive bus
A53	PCIE_RT_RX_N8	BA6	1.4 V PCML	Receive bus
A57	PCIE_RT_RX_N9	AY8	1.4 V PCML	Receive bus
A61	PCIE_RT_RX_N10	AW6	1.4 V PCML	Receive bus
A65	PCIE_RT_RX_N11	AV8	1.4 V PCML	Receive bus
A69	PCIE_RT_RX_N12	AU6	1.4 V PCML	Receive bus
				<i>continued...</i>



Receive Bus	Schematic Signal Name	FPGA Pin Number	I/O Standard	Description
A73	PCIE_RT_RX_N13	AT8	1.4 V PCML	Receive bus
A77	PCIE_RT_RX_N14	AR6	1.4 V PCML	Receive bus
A81	PCIE_RT_RX_N15	AP8	1.4 V PCML	Receive bus
A16	PCIE_RT_RX_P0	BH8	1.4 V PCML	Receive bus
A21	PCIE_RT_RX_P1	BJ5	1.4 V PCML	Receive bus
A25	PCIE_RT_RX_P2	BG6	1.4 V PCML	Receive bus
A29	PCIE_RT_RX_P3	BF8	1.4 V PCML	Receive bus
A35	PCIE_RT_RX_P4	BE6	1.4 V PCML	Receive bus
A39	PCIE_RT_RX_P5	BD8	1.4 V PCML	Receive bus
A43	PCIE_RT_RX_P6	BB8	1.4 V PCML	Receive bus
A47	PCIE_RT_RX_P7	BC5	1.4 V PCML	Receive bus
A52	PCIE_RT_RX_P8	AY7	1.4 V PCML	Receive bus
A56	PCIE_RT_RX_P9	AW5	1.4 V PCML	Receive bus
A60	PCIE_RT_RX_P10	AW5	1.4 V PCML	Receive bus
A64	PCIE_RT_RX_P11	AV7	1.4 V PCML	Receive bus
A68	PCIE_RT_RX_P12	AU5	1.4 V PCML	Receive bus
A72	PCIE_RT_RX_P13	AT7	1.4 V PCML	Receive bus
A76	PCIE_RT_RX_P14	AR5	1.4 V PCML	Receive bus
A80	PCIE_RT_RX_P15	AP7	1.4 V PCML	Receive bus
B11	PCIE_RT_WAKEN	B4	1.8V	Wake signal

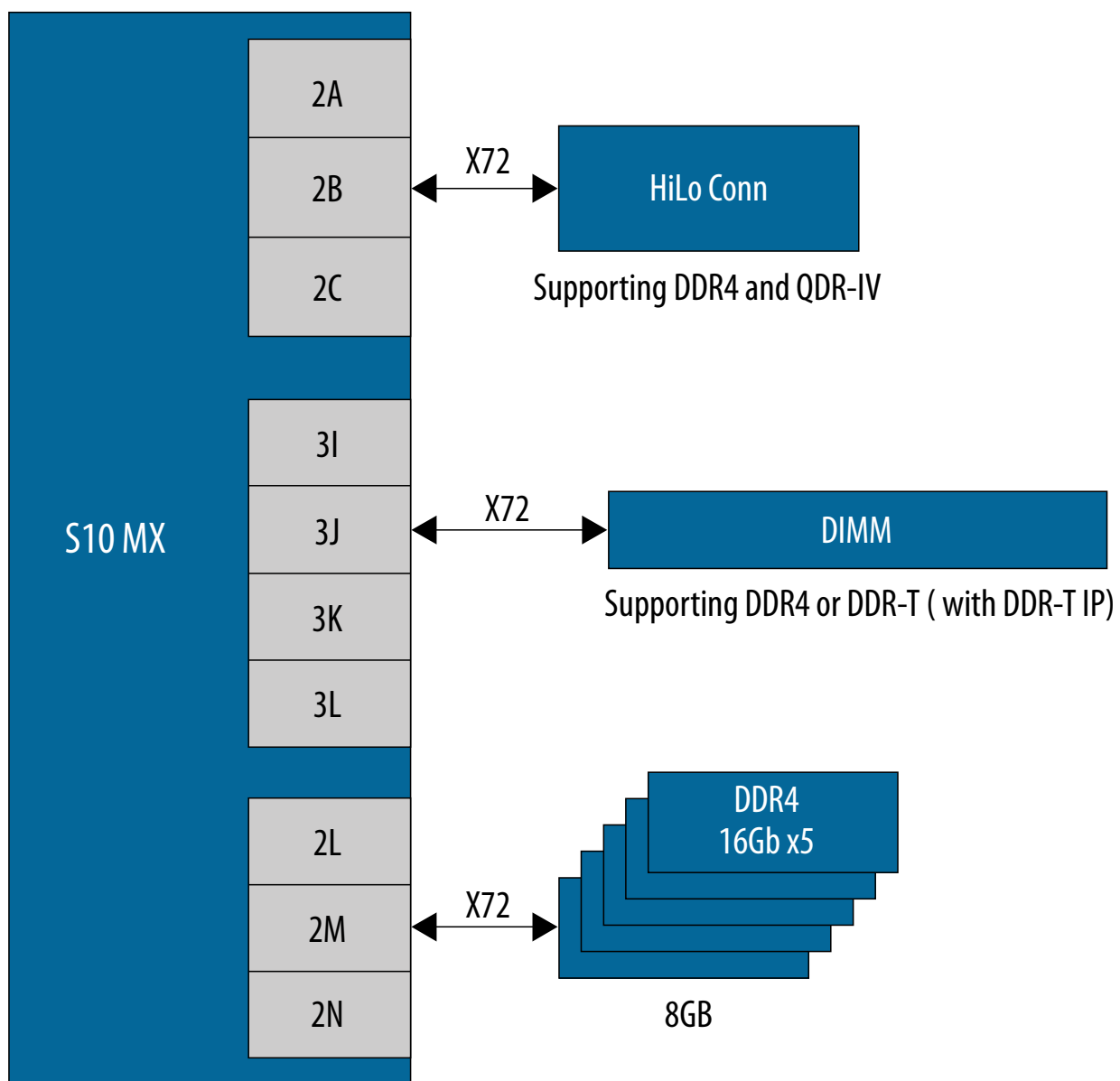
4.6.2. Memory Interface

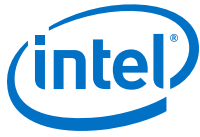
This section describes the Intel Stratix 10 MX FPGA development kit's memory interface support and their signal names, types and connectivity relative to the Intel Stratix 10 MX FPGA.

Three independent memory interfaces are supported: On-board DDR4, DIMM for DDR4 or DDR-T, and HiLo for DDR4 or QDR-IV.

- The on-board DDR4 uses five 16 Gb DDR4 single rank devices connecting to Bank 2L, 2M, 2N of the Intel Stratix 10 MX FPGA. The total memory size is 8 GB running at 1333 MHz.
- The 288-pin DIMM socket interfaces to Bank 3I, 3J, 3K, 3L of the Intel Stratix 10 MX FPGA. This socket accepts DDR4 module or DDR-T module (requires DDR-T protocol IP).
- The HiLo connector interfaces to Bank 2A, 2B, 2C of the Intel Stratix 10 MX FPGA. Supported HiLo modules are DDR4 and QDR-IV.

Figure 10. Memory Interfaces





4.6.2.1. On-board DDR4 Memory Interface

The on-board DDR4 memory uses five Micron Technology's MT40A1G16KNR-075E 16 Gb DDR4 single rank devices mapping to the FPGA's 2L, 2M and 2N I/O blocks. The total memory size is 8 GB running at 1333 MHz.

Table 14. On-board DDR4 Memory Interface Pin Connections

Board Reference - DDR4 device	Schematic Signal Name	FPGA Pin Number	I/O Standard
U3,U4,U5,U6,U7 pin P3	DDR4_COMP_A0	H34	1.2V
U3,U4,U5,U6,U7 pin P7	DDR4_COMP_A1	J34	1.2V
U3,U4,U5,U6,U7 pin R3	DDR4_COMP_A2	G35	1.2V
U3,U4,U5,U6,U7 pin N7	DDR4_COMP_A3	H35	1.2V
U3,U4,U5,U6,U7 pin N3	DDR4_COMP_A4	L35	1.2V
U3,U4,U5,U6,U7 pin P8	DDR4_COMP_A5	K35	1.2V
U3,U4,U5,U6,U7 pin P2	DDR4_COMP_A6	L34	1.2V
U3,U4,U5,U6,U7 pin R8	DDR4_COMP_A7	K34	1.2V
U3,U4,U5,U6,U7 pin R2	DDR4_COMP_A8	N34	1.2V
U3,U4,U5,U6,U7 pin R7	DDR4_COMP_A9	P34	1.2V
U3,U4,U5,U6,U7 pin M3	DDR4_COMP_A10	M35	1.2V
U3,U4,U5,U6,U7 pin T2	DDR4_COMP_A11	N35	1.2V
U3,U4,U5,U6,U7 pin M7	DDR4_COMP_A12	B40	1.2V
U3,U4,U5,U6,U7 pin T8	DDR4_COMP_A13	C39	1.2V
U3,U4,U5,U6,U7 pin L2	DDR4_COMP_A14	D39	1.2V
U3,U4,U5,U6,U7 pin M8	DDR4_COMP_A15	D38	1.2V
U3,U4,U5,U6,U7 pin L8	DDR4_COMP_A16	C38	1.2V
U3_G2	DDR4_COMP_DQ0	K36	1.2V
U3_F7	DDR4_COMP_DQ1	H36	1.2V
U3_H3	DDR4_COMP_DQ2	P36	1.2V
U3_H7	DDR4_COMP_DQ3	T35	1.2V
U3_H2	DDR4_COMP_DQ4	J36	1.2V
U3_H8	DDR4_COMP_DQ5	G36	1.2V
U3_J3	DDR4_COMP_DQ6	R36	1.2V
U3_J7	DDR4_COMP_DQ7	T34	1.2V
U3_A3	DDR4_COMP_DQ8	K37	1.2V
U3_B8	DDR4_COMP_DQ9	G38	1.2V
U3_C3	DDR4_COMP_DQ10	M37	1.2V
U3_C7	DDR4_COMP_DQ11	P38	1.2V
<i>continued...</i>			

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Board Reference - DDR4 device	Schematic Signal Name	FPGA Pin Number	I/O Standard
U3_C2	DDR4_COMP_DQ12	L37	1.2V
U3_C8	DDR4_COMP_DQ13	P37	1.2V
U3_D3	DDR4_COMP_DQ14	N38	1.2V
U3_D7	DDR4_COMP_DQ15	R37	1.2V
U4_G2	DDR4_COMP_DQ16	G42	1.2V
U4_F7	DDR4_COMP_DQ17	J39	1.2V
U4_H3	DDR4_COMP_DQ18	H42	1.2V
U4_H7	DDR4_COMP_DQ19	G40	1.2V
U4_H2	DDR4_COMP_DQ20	H41	1.2V
U4_H8	DDR4_COMP_DQ21	L39	1.2V
U4_J3	DDR4_COMP_DQ22	H40	1.2V
U4_J7	DDR4_COMP_DQ23	G41	1.2V
U4_A3	DDR4_COMP_DQ24	B32	1.2V
U4_B8	DDR4_COMP_DQ25	G32	1.2V
U4_C3	DDR4_COMP_DQ26	C33	1.2V
U4_C7	DDR4_COMP_DQ27	J31	1.2V
U4_C2	DDR4_COMP_DQ28	B33	1.2V
U4_C8	DDR4_COMP_DQ29	H31	1.2V
U4_D3	DDR4_COMP_DQ30	D33	1.2V
U4_D7	DDR4_COMP_DQ31	K31	1.2V
U5_G2	DDR4_COMP_DQ32	M33	1.2V
U5_F7	DDR4_COMP_DQ33	R31	1.2V
U5_H3	DDR4_COMP_DQ34	N33	1.2V
U5_H7	DDR4_COMP_DQ35	R32	1.2V
U5_H2	DDR4_COMP_DQ36	L33	1.2V
U5_H8	DDR4_COMP_DQ37	T32	1.2V
U5_J3	DDR4_COMP_DQ38	P33	1.2V
U5_J7	DDR4_COMP_DQ39	T33	1.2V
U5_A3	DDR4_COMP_DQ40	P39	1.2V
U5_B8	DDR4_COMP_DQ41	T39	1.2V
U5_C3	DDR4_COMP_DQ42	T38	1.2V
U5_C7	DDR4_COMP_DQ43	V39	1.2V
U5_C2	DDR4_COMP_DQ44	M38	1.2V
U5_C8	DDR4_COMP_DQ45	V38	1.2V
			<i>continued...</i>



Board Reference - DDR4 device	Schematic Signal Name	FPGA Pin Number	I/O Standard
U5_D3	DDR4_COMP_DQ46	U38	1.2V
U5_D7	DDR4_COMP_DQ47	W39	1.2V
U6_G2	DDR4_COMP_DQ48	C40	1.2V
U6_F7	DDR4_COMP_DQ49	E39	1.2V
U6_H3	DDR4_COMP_DQ50	B42	1.2V
U6_H7	DDR4_COMP_DQ51	F39	1.2V
U6_H2	DDR4_COMP_DQ52	D41	1.2V
U6_H8	DDR4_COMP_DQ53	F38	1.2V
U6_J3	DDR4_COMP_DQ54	D42	1.2V
U6_J7	DDR4_COMP_DQ55	F40	1.2V
U6_A3	DDR4_COMP_DQ56	C34	1.2V
U6_B8	DDR4_COMP_DQ57	H33	1.2V
U6_C3	DDR4_COMP_DQ58	D34	1.2V
U6_C7	DDR4_COMP_DQ59	J32	1.2V
U6_C2	DDR4_COMP_DQ60	C35	1.2V
U6_C8	DDR4_COMP_DQ61	J33	1.2V
U6_D3	DDR4_COMP_DQ62	E34	1.2V
U6_D7	DDR4_COMP_DQ63	L32	1.2V
U7_G2	DDR4_COMP_DQ64	C31	1.2V
U7_F7	DDR4_COMP_DQ65	C30	1.2V
U7_H3	DDR4_COMP_DQ66	A34	1.2V
U7_H7	DDR4_COMP_DQ67	A30	1.2V
U7_H2	DDR4_COMP_DQ68	D31	1.2V
U7_H8	DDR4_COMP_DQ69	E31	1.2V
U7_J3	DDR4_COMP_DQ70	B35	1.2V
U7_J7	DDR4_COMP_DQ71	B30	1.2V
U3,U4,U5,U6,U7 pin M2	DDR4_COMP_BG0	G37	1.2V
U3,U4,U5,U6,U7 pin M9	DDR4_COMP_BG1	F34	1.2V
U3,U4,U5,U6,U7 pin N2	DDR4_COMP_BA0	D37	1.2V
U3,U4,U5,U6,U7 pin N8	DDR4_COMP_BA1	F37	1.2V
U3,U4,U5,U6,U7 pin B7	DDR4_COMP_DQS_P1	B7	1.2V
U3,U4,U5,U6,U7 pin A7	DDR4_COMP_DQS_N1	A7	1.2V
U3,U4,U5,U6,U7 pin G3	DDR4_COMP_DQS_P0	G3	1.2V
U3,U4,U5,U6,U7 pin F3	DDR4_COMP_DQS_N0	F3	1.2V
<i>continued...</i>			



Board Reference - DDR4 device	Schematic Signal Name	FPGA Pin Number	I/O Standard
U3,U4,U5,U6,U7 pin L7	DDR4_COMP_CS_N	E36	1.2V
U3,U4,U5,U6,U7 pin K3	DDR4_COMP_ODT	C36	1.2V
U3,U4,U5,U6,U7 pin L3	DDR4_COMP_ACT_N	E35	1.2V
U3,U4,U5,U6,U7 pin T3	DDR4_COMP_PAR	A39	1.2V
U3,U4,U5,U6,U7 pin K2	DDR4_COMP_CKE	B36	1.2V
U3,U4,U5,U6,U7 pin P1	DDR4_COMP_RESET_N	F35	1.2V
U3,U4,U5,U6,U7 pin P9	DDR4_COMP_ALERT_N	A38	1.2V
U3,U4,U5,U6,U7 pin E2	DDR4_COMP_DBI_N1	J37	1.2V
U3,U4,U5,U6,U7 pin E7	DDR4_COMP_DBI_N0	R34	1.2V
U3,U4,U5,U6,U7 pin K7	DDR4_COMP_CLK_P	B37	1.2V
U3,U4,U5,U6,U7 pin K8	DDR4_COMP_CLK_N	B38	1.2V

4.6.2.2. DDR4/DDR-T DIMM Memory Interface

The DIMM Memory interface uses a standard 288-pin DIMM connector that is mapped to the FPGA's 3I, 3J, 3K and 3L I/O blocks. The connector supports plugins for the following memory interfaces:

- DDR4 x72 (included in the kit)
- DDR-T module (not included in the kit. DDR-T support requires DDR-T protocol soft IP)

Table 15. DDR4/DDR-T DIMM Memory Interface Pin Connections

Board Reference - DIMM Pin	Schematic Signal Name	FPGA Pin Number	I/O Standard
1, 145	12V/NC		12V DC
5	DDR4_DIMM_DQ0	T14	1.2V
150	DDR4_DIMM_DQ1	R14	1.2V
12	DDR4_DIMM_DQ2	N14	1.2V
157	DDR4_DIMM_DQ3	H14	1.2V
3	DDR4_DIMM_DQ4	T15	1.2V
148	DDR4_DIMM_DQ5	P14	1.2V
10	DDR4_DIMM_DQ6	P14	1.2V
155	DDR4_DIMM_DQ7	J14	1.2V
16	DDR4_DIMM_DQ8	N16	1.2V
161	DDR4_DIMM_DQ9	M16	1.2V
23	DDR4_DIMM_DQ10	H16	1.2V
168	DDR4_DIMM_DQ11	G16	1.2V

continued...



Board Reference - DIMM Pin	Schematic Signal Name	FPGA Pin Number	I/O Standard
14	DDR4_DIMM_DQ12	R16	1.2V
159	DDR4_DIMM_DQ13	P16	1.2V
21	DDR4_DIMM_DQ14	L15	1.2V
166	DDR4_DIMM_DQ15	K15	1.2V
27	DDR4_DIMM_DQ16	K21	1.2V
172	DDR4_DIMM_DQ17	J22	1.2V
34	DDR4_DIMM_DQ18	M20	1.2V
179	DDR4_DIMM_DQ19	H23	1.2V
25	DDR4_DIMM_DQ20	N20	1.2V
170	DDR4_DIMM_DQ21	H23	1.2V
32	DDR4_DIMM_DQ22	N20	1.2V
177	DDR4_DIMM_DQ23	J21	1.2V
38	DDR4_DIMM_DQ24	H10	1.2V
183	DDR4_DIMM_DQ25	A10	1.2V
45	DDR4_DIMM_DQ26	G10	1.2V
190	DDR4_DIMM_DQ27	C11	1.2V
36	DDR4_DIMM_DQ28	F10	1.2V
181	DDR4_DIMM_DQ29	A9	1.2V
43	DDR4_DIMM_DQ30	H11	1.2V
188	DDR4_DIMM_DQ31	D11	1.2V
97	DDR4_DIMM_DQ32	C14	1.2V
242	DDR4_DIMM_DQ33	C16	1.2V
104	DDR4_DIMM_DQ34	F15	1.2V
249	DDR4_DIMM_DQ35	E15	1.2V
95	DDR4_DIMM_DQ36	G15	1.2V
240	DDR4_DIMM_DQ37	C15	1.2V
102	DDR4_DIMM_DQ38	D16	1.2V
247	DDR4_DIMM_DQ39	H15	1.2V
108	DDR4_DIMM_DQ40	C26	1.2V
253	DDR4_DIMM_DQ41	C25	1.2V
115	DDR4_DIMM_DQ42	B27	1.2V
260	DDR4_DIMM_DQ43	G26	1.2V
106	DDR4_DIMM_DQ44	E26	1.2V
251	DDR4_DIMM_DQ45	D26	1.2V
			<i>continued...</i>



Board Reference - DIMM Pin	Schematic Signal Name	FPGA Pin Number	I/O Standard
113	DDR4_DIMM_DQ46	B26	1.2V
258	DDR4_DIMM_DQ47	G27	1.2V
119	DDR4_DIMM_DQ48	B25	1.2V
264	DDR4_DIMM_DQ49	F24	1.2V
126	DDR4_DIMM_DQ50	F25	1.2V
171	DDR4_DIMM_DQ51	H25	1.2V
117	DDR4_DIMM_DQ52	A25	1.2V
262	DDR4_DIMM_DQ53	E24	1.2V
124	DDR4_DIMM_DQ54	E25	1.2V
269	DDR4_DIMM_DQ55	G25	1.2V
130	DDR4_DIMM_DQ56	A22	1.2V
275	DDR4_DIMM_DQ57	F22	1.2V
137	DDR4_DIMM_DQ58	A24	1.2V
282	DDR4_DIMM_DQ59	B23	1.2V
128	DDR4_DIMM_DQ60	C23	1.2V
273	DDR4_DIMM_DQ61	G22	1.2V
135	DDR4_DIMM_DQ62	A23	1.2V
280	DDR4_DIMM_DQ63	D23	1.2V
49	DDR4_DIMM_DQ64	D12	1.2V
194	DDR4_DIMM_DQ65	E12	1.2V
56	DDR4_DIMM_DQ66	A12	1.2V
201	DDR4_DIMM_DQ67	A13	1.2V
47	DDR4_DIMM_DQ68	D13	1.2V
192	DDR4_DIMM_DQ69	F12	1.2V
54	DDR4_DIMM_DQ70	C13	1.2V
199	DDR4_DIMM_DQ71	B13	1.2V
79	DDR4_DIMM_A0	J19	1.2V
72	DDR4_DIMM_A1	H19	1.2V
216	DDR4_DIMM_A2	L19	1.2V
71	DDR4_DIMM_A3	K19	1.2V
214	DDR4_DIMM_A4	G18	1.2V
213	DDR4_DIMM_A5	F18	1.2V
69	DDR4_DIMM_A6	G17	1.2V
211	DDR4_DIMM_A7	F17	1.2V
			<i>continued...</i>



Board Reference - DIMM Pin	Schematic Signal Name	FPGA Pin Number	I/O Standard
68	DDR4_DIMM_A8	G17	1.2V
66	DDR4_DIMM_A9	E16	1.2V
225	DDR4_DIMM_A10	D17	1.2V
210	DDR4_DIMM_A11	D18	1.2V
65	DDR4_DIMM_A12	A17	1.2V
232	DDR4_DIMM_A13	E19	1.2V
226	DDR4_DIMM_A14	F19	1.2V
86	DDR4_DIMM_A15	C19	1.2V
82	DDR4_DIMM_A16	D19	1.2V
234	DDR4_DIMM_A17	A20	1.2V
152	DDR4_DIMM_DQS_N0	K14	1.2V
153	DDR4_DIMM_DQS_P0	L14	1.2V
163	DDR4_DIMM_DQS_N1	N15	1.2V
164	DDR4_DIMM_DQS_P1	M15	1.2V
174	DDR4_DIMM_DQS_N2	K20	1.2V
175	DDR4_DIMM_DQS_P2	L20	1.2V
185	DDR4_DIMM_DQS_N3	E11	1.2V
186	DDR4_DIMM_DQS_P3	E10	1.2V
244	DDR4_DIMM_DQS_N4	A15	1.2V
245	DDR4_DIMM_DQS_P4	A14	1.2V
255	DDR4_DIMM_DQS_N5	E27	1.2V
256	DDR4_DIMM_DQS_P5	F27	1.2V
266	DDR4_DIMM_DQS_N6	C24	1.2V
267	DDR4_DIMM_DQS_P6	D24	1.2V
277	DDR4_DIMM_DQS_N7	E27	1.2V
278	DDR4_DIMM_DQS_P7	F27	1.2V
196	DDR4_DIMM_DQS_N8	B11	1.2V
197	DDR4_DIMM_DQS_P8	B12	1.2V
7	DDR4_DIMM_DBI_N0	F13	1.2V
18	DDR4_DIMM_DBI_N1	J16	1.2V
29	DDR4_DIMM_DBI_N2	N19	1.2V
40	DDR4_DIMM_DBI_N3	C10	1.2V
99	DDR4_DIMM_DBI_N4	B15	1.2V
110	DDR4_DIMM_DBI_N5	J26	1.2V
<i>continued...</i>			



Board Reference - DIMM Pin	Schematic Signal Name	FPGA Pin Number	I/O Standard
121	DDR4_DIMM_DBI_N6	J24	1.2V
132	DDR4_DIMM_DBI_N7	G23	1.2V
8	DDR4_DIMM_TDQS_N9	F14	1.2V
19	DDR4_DIMM_TDQS_N10	K16	1.2V
30	DDR4_DIMM_TDQS_N11	P19	1.2V
41	DDR4_DIMM_TDQS_N12	B10	1.2V
100	DDR4_DIMM_TDQS_N13	B16	1.2V
111	DDR4_DIMM_TDQS_N14	H26	1.2V
122	DDR4_DIMM_TDQS_N15	H24	1.2V
133	DDR4_DIMM_TDQS_N16	F23	1.2V
52	DDR4_DIMM_TDQS_N17	E14	1.2V
74	DDR4_DIMM_CK_P0	K17	1.2V
75	DDR4_DIMM_CK_N0	J17	1.2V
218	DDR4_DIMM_CK_P1	D22	1.2V
219	DDR4_DIMM_CK_N1	E22	1.2V
139	DDR4_DIMM_SA0	-	Pull up to 2.5V
140	DDR4_DIMM_SA1	-	Pull up to 2.5V
238	DDR4_DIMM_SA2	-	Pull up to 2.5V
141	DDR4D_SCL	H30	1.8V
285	DDR4D_SDA	D29	1.8V

4.6.2.3. HiLo Memory Interface

The HiLo Memory interface is mapped to the FPGA's 2A, 2B and 2C I/O blocks. The connector supports plugins for the following memory interfaces:

- DDR4 x72
- QDR-IV x72

Table 16. HiLo Memory Interface Pin Connections

Board Reference - HiLo Connector Pin Number	Schematic Signal Name	FPGA Pin Number	I/O Standard
F1	MEM_ADDR_CMD0	BL34	Adjustable
H1	MEM_ADDR_CMD1	BK34	Adjustable
F2	MEM_ADDR_CMD2	BJ34	Adjustable
G2	MEM_ADDR_CMD3	BH34	Adjustable
H2	MEM_ADDR_CMD4	BH33	Adjustable
J2	MEM_ADDR_CMD5	BJ33	Adjustable

continued...



Board Reference - HiLo Connector Pin Number	Schematic Signal Name	FPGA Pin Number	I/O Standard
K2	MEM_ADDR_CMD6	BK35	Adjustable
G3	MEM_ADDR_CMD7	BL34	Adjustable
J3	MEM_ADDR_CMD8	BD33	Adjustable
L3	MEM_ADDR_CMD9	BC33	Adjustable
E4	MEM_ADDR_CMD10	BG33	Adjustable
F4	MEM_ADDR_CMD11	BF33	Adjustable
G4	MEM_ADDR_CMD12	BB33	Adjustable
H4	MEM_ADDR_CMD13	BB32	Adjustable
J4	MEM_ADDR_CMD14	BA32	Adjustable
K4	MEM_ADDR_CMD15	Aw32	Adjustable
M1	MEM_ADDR_CMD16	BF32	Adjustable
M2	MEM_ADDR_CMD17	BE32	Adjustable
N2	MEM_ADDR_CMD18	BD32	Adjustable
L4	MEM_ADDR_CMD19	BG32	Adjustable
P5	MEM_ADDR_CMD20	BD34	Adjustable
M5	MEM_ADDR_CMD21	BC34	Adjustable
P1	MEM_ADDR_CMD22	Aw34	Adjustable
R4	MEM_ADDR_CMD23	AV34	Adjustable
M4	MEM_ADDR_CMD24	BA34	Adjustable
R3	MEM_ADDR_CMD25	AY34	Adjustable
L2	MEM_ADDR_CMD26	AY32	Adjustable
K1	MEM_ADDR_CMD27	AW33	Adjustable
P2	MEM_ADDR_CMD28	AV33	Adjustable
N4	MEM_ADDR_CMD29	BL32	Adjustable
P4	MEM_ADDR_CMD30	BG35	Adjustable
N3	MEM_ADDR_CMD31	BH35	Adjustable
V2	MEM_CLK_P	BF34	Adjustable
V1	MEM_CLK_N	BE34	Adjustable
B10	MEM_DMA0	BF40	Adjustable
C4	MEM_DMA1	BD38	Adjustable
B17	MEM_DMA2	BE37	Adjustable
F17	MEM_DMA3	BH36	Adjustable
A4	MEM_DQA0	BJ39	Adjustable
B4	MEM_DQA1	BH40	Adjustable
			<i>continued...</i>

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Board Reference - HiLo Connector Pin Number	Schematic Signal Name	FPGA Pin Number	I/O Standard
B5	MEM_DQA2	BH39	Adjustable
B6	MEM_DQA3	BG40	Adjustable
A8	MEM_DQA4	BK40	Adjustable
B8	MEM_DQA5	BL40	Adjustable
B9	MEM_DQA6	BE40	Adjustable
A10	MEM_DQA7	BE39	Adjustable
B1	MEM_DQA8	BL38	Adjustable
B2	MEM_DQA9	BG38	Adjustable
C2	MEM_DQA10	BF38	Adjustable
C3	MEM_DQA11	BD39	Adjustable
E3	MEM_DQA12	BC38	Adjustable
D4	MEM_DQA13	BC39	Adjustable
D1	MEM_DQA14	BJ37	Adjustable
D2	MEM_DQA15	BL37	Adjustable
A12	MEM_DQA16	BD37	Adjustable
B12	MEM_DQA17	BF37	Adjustable
B13	MEM_DQA18	BG37	Adjustable
B14	MEM_DQA19	BB36	Adjustable
C15	MEM_DQA20	BC36	Adjustable
A16	MEM_DQA21	AW37	Adjustable
B16	MEM_DQA22	AY37	Adjustable
A18	MEM_DQA23	AW36	Adjustable
C16	MEM_DQA24	BA35	Adjustable
D16	MEM_DQA25	BB35	Adjustable
E16	MEM_DQA26	BC35	Adjustable
F16	MEM_DQA27	BF35	Adjustable
D17	MEM_DQA28	AY35	Adjustable
C18	MEM_DQA29	BD36	Adjustable
D18	MEM_DQA30	BE36	Adjustable
E18	MEM_DQA31	BE35	Adjustable
E2	MEM_DQA32	BK37	Adjustable
G16	MEM_DQA33	BG36	Adjustable
A6	MEM_DQSA_P0	BK39	Adjustable
A7	MEM_DQSA_N0	BL39	Adjustable
			<i>continued...</i>



Board Reference - HiLo Connector Pin Number	Schematic Signal Name	FPGA Pin Number	I/O Standard
A2	MEM_DQSA_P1	BH38	Adjustable
A3	MEM_DQSA_N1	BJ38	Adjustable
A14	MEM_DQSA_P2	BA37	Adjustable
A15	MEM_DQSA_N2	BB37	Adjustable
F18	MEM_DQSA_P3	BJ36	Adjustable
G18	MEM_DQSA_N3	BK36	Adjustable
A11	MEM_QKA_P0	BF39	Adjustable
B18	MEN_QKA_P1	AY36	Adjustable
R6	MEM_DQ_ADDR_CMD0	BE31	Adjustable
T1	MEM_DQ_ADDR_CMD1	BG31	Adjustable
R2	MEM_DQ_ADDR_CMD2	BD31	Adjustable
T2	MEM_DQ_ADDR_CMD3	BB31	Adjustable
U2	MEM_DQ_ADDR_CMD4	BC31	Adjustable
U3	MEM_DQ_ADDR_CMD5	BH31	Adjustable
T4	MEM_DQ_ADDR_CMD6	BK32	Adjustable
U4	MEM_DQ_ADDR_CMD7	BJ32	Adjustable
T5	MEM_DQ_ADDR_CMD8	BL33	Adjustable
V4	MEM_DQ_ADDR_CMD_P	BK31	Adjustable
V5	MEM_DQ_ADDR_CMD_N	BJ31	Adjustable
V1	MEM_CLK_P	BF34	Adjustable
V2	MEM_CLK_N	BE34	Adjustable
M16	MEM_DMB0	BL24	Adjustable
U16	MEM_DMB1	BD28	Adjustable
U11	MEM_DMB2	BL30	Adjustable
U6	MEM_DMB3	BE30	Adjustable
H16	MEM_DQB0	BE27	Adjustable
J16	MEM_DQB1	BJ26	Adjustable
K16	MEM_DQB2	BK24	Adjustable
L16	MEM_DQB3	BF27	Adjustable
H17	MEM_DQB4	BH26	Adjustable
K17	MEM_DQB5	BL25	Adjustable
K18	MEM_DQB6	BJ24	Adjustable
L18	MEM_DQB7	BG27	Adjustable
M17	MEM_DQB8	BF28	Adjustable
<i>continued...</i>			

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Board Reference - HiLo Connector Pin Number	Schematic Signal Name	FPGA Pin Number	I/O Standard
N18	MEM_DQB9	BG28	Adjustable
P17	MEM_DQB10	Bk27	Adjustable
P18	MEM_DQB11	BJ27	Adjustable
R18	MEM_DQB12	BC28	Adjustable
T16	MEM_DQB13	BL27	Adjustable
T17	MEM_DQB14	BB28	Adjustable
T18	MEM_DQB15	BD27	Adjustable
U15	MEM_DQB16	BH29	Adjustable
T14	MEM_DQB17	BA29	Adjustable
U14	MEM_DQB18	BA28	Adjustable
V14	MEM_DQB19	BJ29	Adjustable
T13	MEM_DQB20	BK30	Adjustable
T12	MEM_DQB21	BC29	Adjustable
U12	MEM_DQB22	BD29	Adjustable
V12	MEM_DQB23	BL29	Adjustable
T10	MEM_DQB24	AV30	Adjustable
U10	MEM_DQB25	AY29	Adjustable
V10	MEM_DQB26	BA30	Adjustable
T9	MEM_DQB27	AW29	Adjustable
T8	MEM_DQB28	AV29	Adjustable
U8	MEM_DQB29	AY30	Adjustable
U7	MEM_DQB30	BH30	Adjustable
V6	MEM_DQB31	BG30	Adjustable
R16	MEM_DQB32	BL28	Adjustable
T6	MEM_DQB33	BF30	Adjustable
H18	MEM_DQSB_P0	BK26	Adjustable
J18	MEM_DQSB_N0	BK25	Adjustable
U18	MEM_DQSB_P1	BJ28	Adjustable
V18	MEM_DQSB_N1	BH28	Adjustable
V16	MEM_DQSB_P2	BF29	Adjustable
V17	MEM_DQSB_N2	BE29	Adjustable
V8	MEM_DQSB_P3	BB30	Adjustable

continued...

Board Reference - HiLo Connector Pin Number	Schematic Signal Name	FPGA Pin Number	I/O Standard
V9	MEM_DQSB_N3	BC30	Adjustable
M18	MEM_QKB_P0	BG26	Adjustable
V13	MEM_QKB_P1	BK29	Adjustable

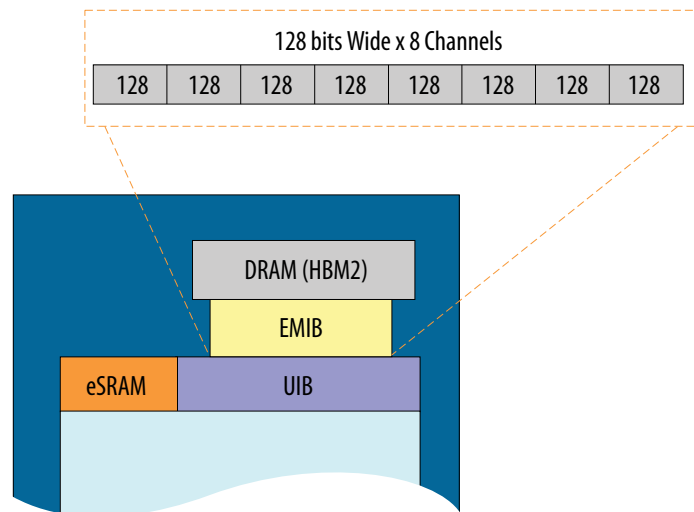
4.6.3. High Bandwidth Memory (HBM2)

The integrated 3D stack High-Bandwidth DRAM Memory (HBM2) is a "near memory" implementation where the high-density stacked DRAM is integrated very close to the FPGA in the same package.

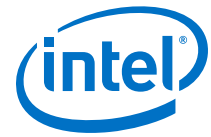
In this configuration, the in-package memory is able to deliver up to 512 GBps of total aggregate bandwidth which represents over 10 times increase in bandwidth compared to traditional "far memory" implemented in separate devices on the board.

The Intel Stratix 10 MX FPGA on this development kit has two 4 GB on-package 3D stacked HBM2 DRAM memories. Each of these DRAM stacks has:

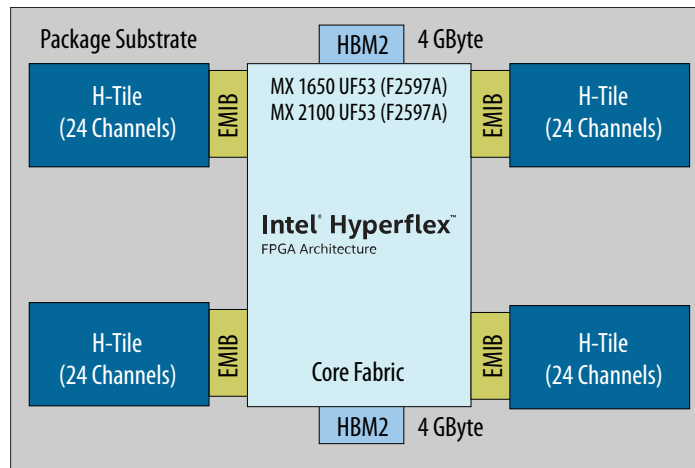
- 8 GB total density (4 GB x2)
- 256 GB/sec total aggregate bandwidth
- 8 independent channels, each 128 bit wide
- Data transfer rates up to 2 Gbps, per signal, between core fabric and HBM2 DRAM
- Full-rate transfer to core fabric



There are two Universal Interface Blocks (UIB).

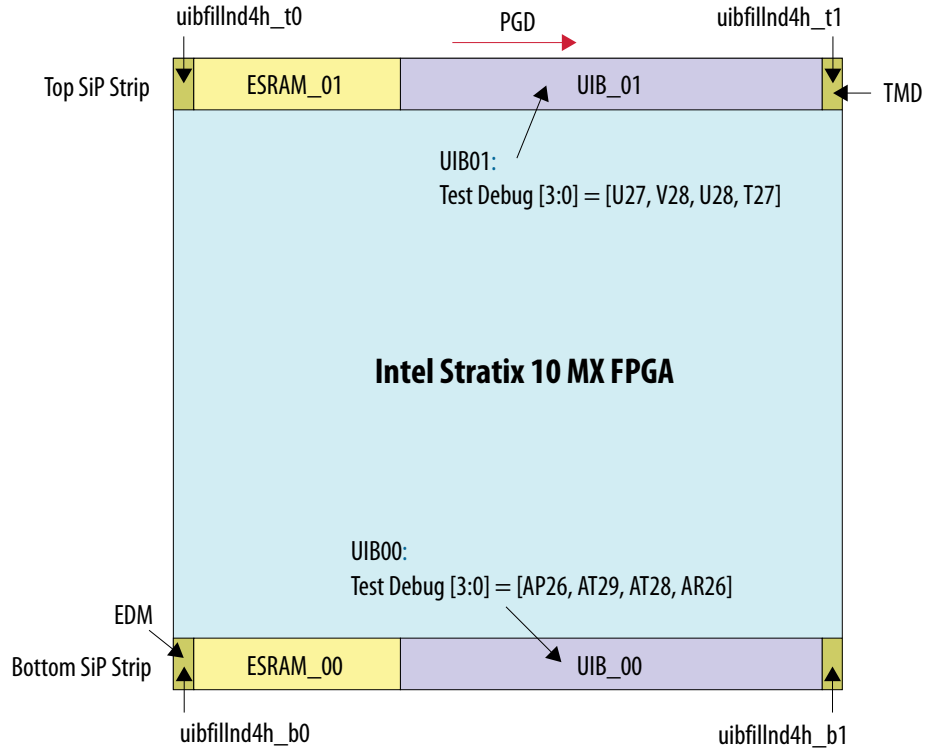


- CLK_UIB0_N/P: programmable LVDS clock inputs to UIB tiles 0 of the device.
- CLK_UIB1_N/P: programmable LVDS clock inputs to UIB tiles 1 of the device.
- 240 Ohm 1% external reference resistors
- Test points on top-side of the board for ATB nodes access
- atb0/atb1/atb2/atb3 - Each UIB has four ATB test points.



ESRAM has the following pins:

- CLK_ESRAM0_N/P: LVDS input reference clock for ESRAM Block0
- CLK_ESRAM1_N/P: LVDS input reference clock for ESRAM Block1
- 2K Ohm 1% external reference resistors
- atb0/atb1 – access pads for probing



4.6.4. QSFP

The Intel Stratix 10 MX FPGA development kit includes two Quad Small Form-Factor Pluggable (QSFP) connectors (J4, J5). Each connector is mapped to the FPGA's 28 Gbps transceivers. There are four transceivers per connector supporting up to 100 Gbps data rate.

Table 17. QSFP_1 (J5) Pin Connections

Board Reference	Schematic Signal Name	FPGA Pin Number	I/O Standard	Description
28	ZQSFP1_3V3_INT_L	A4 (MAX10 U24)	3.3V	QSFP interrupt
31	ZQSFP1_3V3_LPMODE	B6 (MAX10 U24)	3.3V	QSFP low power mode
27	ZQSFP1_3V3_MODPRS_L	A6 (MAX10 U24)	3.3V	Module present
9	ZQSFP1_3V3_RESET_L	A7 (MAX10 U24)	3.3V	Module reset
8	ZQSFP1_3V3_MODSEL_L	B5 (MAX10 U24)	3.3V	Module select
11	ZQSFP_I2C_SCL	BJ16 via U15	1.8v	QSFP serial 2-wire clock
12	ZQSFP_I2C_SDA	BD16 via U15	1.8v	QSFP serial 2-wire data
18	ZQSFP1_RX0_N	AL6	1.4V PCML	QSFP receiver data
<i>continued...</i>				



Board Reference	Schematic Signal Name	FPGA Pin Number	I/O Standard	Description
21	ZQSFP1_RX1_N	AK8	1.4V PCML	QSFP receiver data
15	ZQSFP1_RX2_N	AH8	1.4V PCML	QSFP receiver data
24	ZQSFP1_RX3_N	AG6	1.4V PCML	QSFP receiver data
17	ZQSFP1_RX0_P	AL5	1.4V PCML	QSFP receiver data
22	ZQSFP1_RX1_P	AK7	1.4V PCML	QSFP receiver data
14	ZQSFP1_RX2_P	AH7	1.4V PCML	QSFP receiver data
25	ZQSFP1_RX3_P	AG5	1.4V PCML	QSFP receiver data
37	ZQSFP1_TX0_N	AM4	1.4V PCML	QSFP transmitter data
2	ZQSFP1_TX1_N	AL2	1.4V PCML	QSFP transmitter data
34	ZQSFP1_TX2_N	AJ2	1.4V PCML	QSFP transmitter data
5	ZQSFP1_TX3_N	AH4	1.4V PCML	QSFP transmitter data
36	ZQSFP1_TX0_P	AM3	1.4V PCML	QSFP transmitter data
3	ZQSFP1_TX1_P	AL1	1.4V PCML	QSFP transmitter data
33	ZQSFP1_TX2_P	AJ1	1.4V PCML	QSFP transmitter data
6	ZQSFP1_TX3_P	AH3	1.4V PCML	QSFP transmitter data

Table 18. QSFP_0 (J4) Pin Connections

Board Reference	Schematic Signal Name	FPGA Pin Number	I/O Standard	Description
28	ZQSFP0_3V3_INT_L	E8 (MAX10 U24)	3.3 V	QSFP interrupt
31	ZQSFP0_3V3_LPMODE	A11 (MAX10 U24)	3.3 V	QSFP low power mode
27	ZQSFP0_3V3_MODPRS_L	A10 (MAX10 U24)	3.3 V	Module present
9	ZQSFP0_3V3_RESET_L	B10 (MAX10 U24)	3.3 V	Module reset
8	ZQSFP0_3V3_MODSEL_L	A3 (MAX10 U24)	3.3 V	Module select
11	ZQSFP_I2C_SCL	BJ16 via U15	1.8 V	QSFP serial 2-wire clock
12	ZQSFP_I2C_SDA	BD16 via U15	1.8 V	QSFP serial 2-wire data
18	ZQSFP0_RX0_N	AM44	1.4V PCML	QSFP receiver data
21	ZQSFP0_RX1_N	AK44	1.4V PCML	QSFP receiver data
15	ZQSFP0_RX2_N	AF44	1.4V PCML	QSFP receiver data
24	ZQSFP0_RX3_N	AH44	1.4V PCML	QSFP receiver data
17	ZQSFP0_RX0_P	AM45	1.4V PCML	QSFP receiver data
22	ZQSFP0_RX1_P	AK45	1.4V PCML	QSFP receiver data

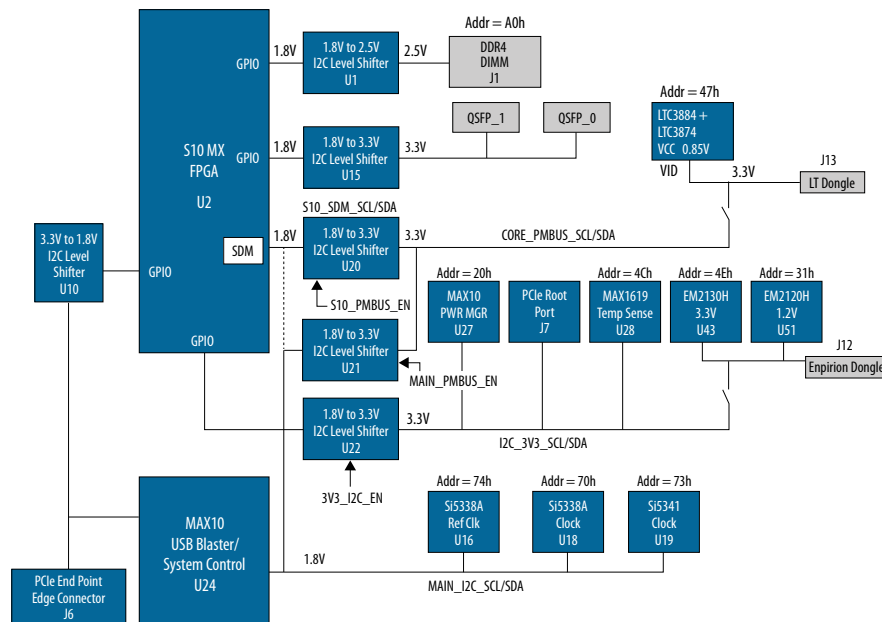
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Board Reference	Schematic Signal Name	FPGA Pin Number	I/O Standard	Description
14	ZQSFP0_RX2_P	AF45	1.4V PCML	QSFP receiver data
25	ZQSFP0_RX3_P	AH45	1.4V PCML	QSFP receiver data
37	ZQSFP0_TX0_N	AN50	1.4V PCML	QSFP transmitter data
2	ZQSFP0_TX1_N	AL50	1.4V PCML	QSFP transmitter data
34	ZQSFP0_TX2_N	AG50	1.4V PCML	QSFP transmitter data
5	ZQSFP0_TX3_N	AJ50	1.4V PCML	QSFP transmitter data
36	ZQSFP0_TX0_P	AN51	1.4V PCML	QSFP transmitter data
3	ZQSFP0_TX1_P	AL51	1.4V PCML	QSFP transmitter data
33	ZQSFP0_TX2_P	AG51	1.4V PCML	QSFP transmitter data
6	ZQSFP0_TX3_P	AJ51	1.4V PCML	QSFP transmitter data

4.6.5. I²C

I²C supports communication between integrated circuits on a board. It is a simple two-wire bus that consists of a serial data line (SDA) and a serial clock (SCL). The Intel MAX 10 and the Intel Stratix 10 devices use the I²C for reading and writing to the various components on the board such as programmable clock generators, VID regulators, ADC and temperature sensors. You can use the Intel Stratix 10 or Intel MAX 10 as the I²C host to access these devices, change clock frequencies or get status information of the board such as voltage and temperature readings.

Figure 11. I²C Block Diagram



**Table 19. Intel MAX 10 I²C Signals**

Schematic Signal Name	Intel MAX 10 Pin Number	I/O Standard	Description
MAIN_I2C_SCL	F8	1.8 V	I ² C serial clock from Intel MAX 10 (U24)
MAIN_I2C_SDA	B12	1.8 V	I ² C serial data from Intel MAX 10 (U24)
PCIE_EP_3V3_I2C_SCL	K1	3.3 V	I ² C serial clock from Intel MAX 10 (U24)
PCIE_EP_3V3_I2C_SDA	L2	3.3 V	I ² C serial data from Intel MAX 10 (U24)
I2C_3V3_SCL	N9	3.3 V	I ² C serial data from Intel MAX 10 (U27)
I2C_3V3_SDA	M12	3.3 V	I ² C serial data from Intel MAX 10 (U27)

Table 20. Intel Stratix 10 MX FPGA I²C Signals

Schematic Signal Name	Intel Stratix 10 MX FPGA Pin Number	I/O Standard	Description
S10_SDM_SCL	BA38	1.8V	Intel Stratix 10 FPGA I ² C from SDM IO pin (default)
S10_SDM_SDA	AW38	1.8V	Intel Stratix 10 FPGA I ² C from SDM IO pin (default)
DDR4_DIMM_SCL	H30	1.8V	Intel Stratix 10 FPGA I ² C from GPIO pin
DDR4_DIMM_SDA	D29	1.8V	Intel Stratix 10 FPGA I ² C from GPIO pin

Table 21. Intel Stratix 10 MX FPGA I²C Signals to Intel MAX 10 Intel FPGA Download Cable II

Schematic Signal Name	Intel Stratix 10 MX FPGA Pin Number	I/O Standard	Description
MAIN_I2C_SCL	BE14	1.8V	Not connected by default
MAIN_I2C_SDA	BF13	1.8V	Not connected by default

Table 22. Intel Stratix 10 MX FPGA I²C Signals to QSFP Module

Schematic Signal Names	Intel Stratix 10 MX FPGA Pin Number	I/O Standard	Description
ZQSFP_S10_I2C_SCL	BJ16	1.8V	Intel Stratix 10 FPGA I ² C from GPIO pin
ZQSFP_S10_I2C_SDA	BD16	1.8V	Intel Stratix 10 FPGA I ² C from GPIO pin



Table 23. Intel Stratix 10 MX FPGA I²C Signals to PCIe End Point Connector

Schematic Signal Name	Intel Stratix 10 MX FPGA Pin Number	PCIe Connector (J6) Pin Number	I/O Standard	Description
PCI_EP_I2C_SCL	BH15	B5	1.8V Via U10	Dedicated I ² C to PCIe Connector
PCI_EP_I2C_SDA	BH14	B6	1.8V Via U10	Dedicated I ² C to PCIe Connector

Table 24. I²C Device Address

Type	Address	Device
Intel Stratix 10 MX FPGA I ² C Address	0xA0	DDR4 DIMM (J1)
	0x47	LTC3884
	0x20	Intel MAX 10 Power (U27)
	0x4C	MAX1619 (U28)
	0x4E	EM2130H (U43)
	0x31	EM2120H (U51)
	TBD	QSFP0 (J5)
	TBD	QSFP1 (J4)
	TBD	PCIe Root Port (J7)
TBD	PCIe End Point (J6)	
Intel MAX 10 I ² C Address	0x74	Si5338A (U16)
	0x70	Si5338A (U18)
	0x73	Si5342 (U19)

4.6.6. Flash Memory

Flash

The Intel Stratix 10 MX FPGA development kit supports one 2 Gb CFI-compatible NOR-type device (P/N: MT25Qu02GCBB3E12) for non-volatile storage of FPGA configuration data, board information, test application data and user code space. This device is controlled by the FPGA's SDM.

Table 25. Flash Memory (U14) Pin Connections

Board Reference	Schematic Signal Name	FPGA Pin Number	I/O Standard	Description
D3	AS_DATA0	BH41	1.8V	Data
D2	AS_DATA1	BG42	1.8V	Data
C4	AS_DATA2	BF42	1.8V	Data
D4	AS_DATA3	BC40	1.8V	Data
B2	AS_CLK	AT37	1.8V	Clock from FPGA
C2	AS_CS0_MSEL0	AR37	1.8V	Chip Select signal



Flash Programming

You can use the Intel Quartus Prime Programmer to program the flash with your Programmer Object File (.pof).

Ensure the following conditions are met before you proceed

1. The Intel Quartus Prime Programmer and the Intel FPGA Download Cable II driver are installed on the host computer.
2. If you are using an external JTAG programmer, ensure the Intel FPGA Download Cable II is connected to the board through the 10-pin female connector. Verify that the Intel FPGA Download Cable II LED for proper connection to the host computer through a micro-USB cable.
3. Power to the board is on, and no other applications that use the JTAG chain are running.
4. The design running in the FPGA does not drive the FM bus.

Execute the steps below to program the Flash Memory

1. Start the Intel Quartus Prime Programmer.
2. Click **Auto Detect** to display the devices in the JTAG chain.
3. Select the flash attached to the Intel Stratix 10 MX FPGA and then click **Change File** and select the path to the desired .pof. If the flash is not detected, configure the FPGA with any configuration image which does not drive the flash signals and then go to step 2.
4. Turn on the **Program/Configure** option for the added file.
5. Click **Start** to program the selected file to flash. Programming is complete when the progress bar reaches 100%. If flash programming fails, change the TCK frequency to a lower frequency (16 MHz or 6 MHz). Run the command below in the Nios II command shell. `jtag --setparam <cable> JtagClock <frequency><Units>`. For example: `jtagconfig --setparam 1 JtagClock 16M` and then go to Step 4.

Attention: Using the Intel Quartus Prime Programmer to program a device on the board causes other JTAG- based applications such as the Board Test System and the Power Monitor to lose their connection to the board. Restart those applications after programming is complete.

4.7. HiLo Daughter Cards

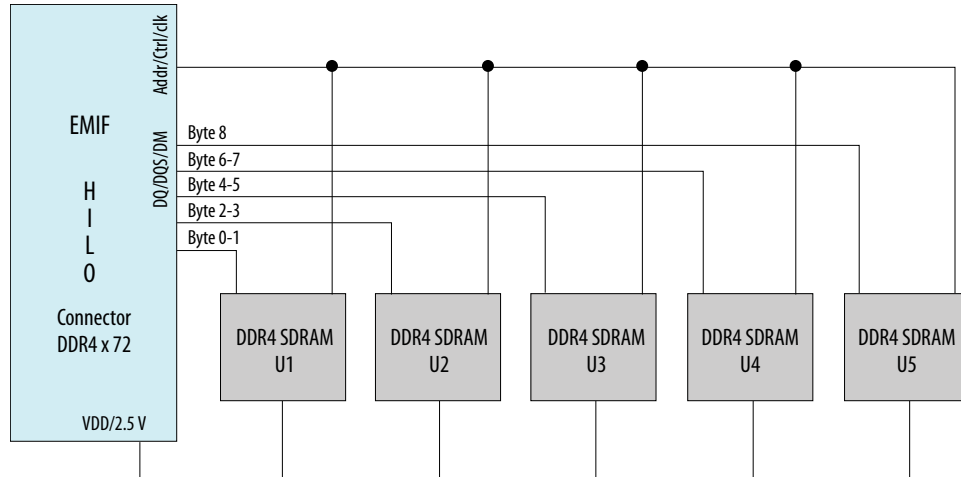
The Intel Stratix 10 MX FPGA development kit provides a full-featured hardware development platform for prototyping and testing high-speed interfaces to an Intel Stratix 10 MX FPGA.

Table 26. Supported Daughter Cards

Memory Type	Transfer Rate (Mbps)	Maximum Frequency (MHz)
DDR4	2666	1333
QDR-IV	2133	1066

4.7.1. DDR4

Figure 12. HiLo DDR4 Block Diagram

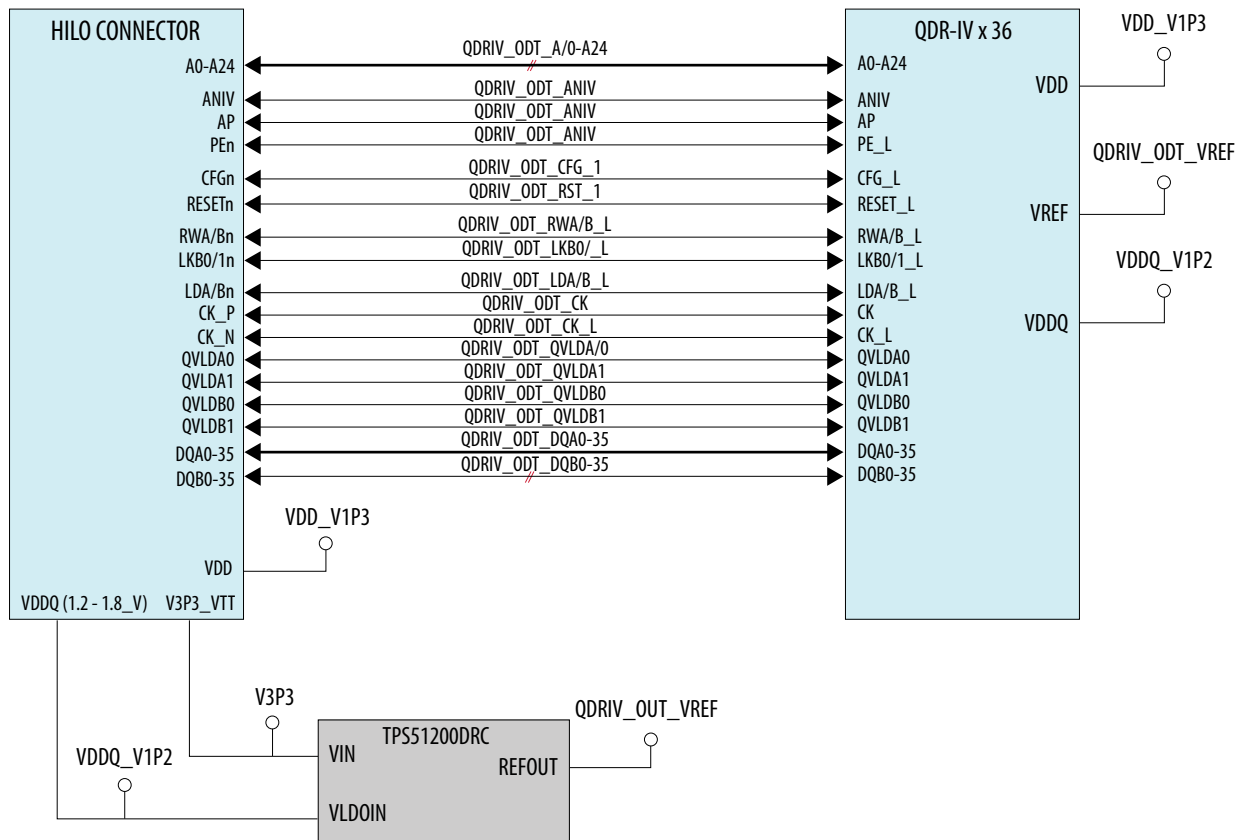


4.7.2. QDR-IV

QDR-IV x 36 SRAM devices enable you to maximize bandwidth with separate read and write ports.



Figure 13. HiLo QDR-IV Block Diagram



4.8. Clocks

Figure 14. Intel Stratix 10 MX FPGA Development Kit Clock Inputs and Default Frequencies

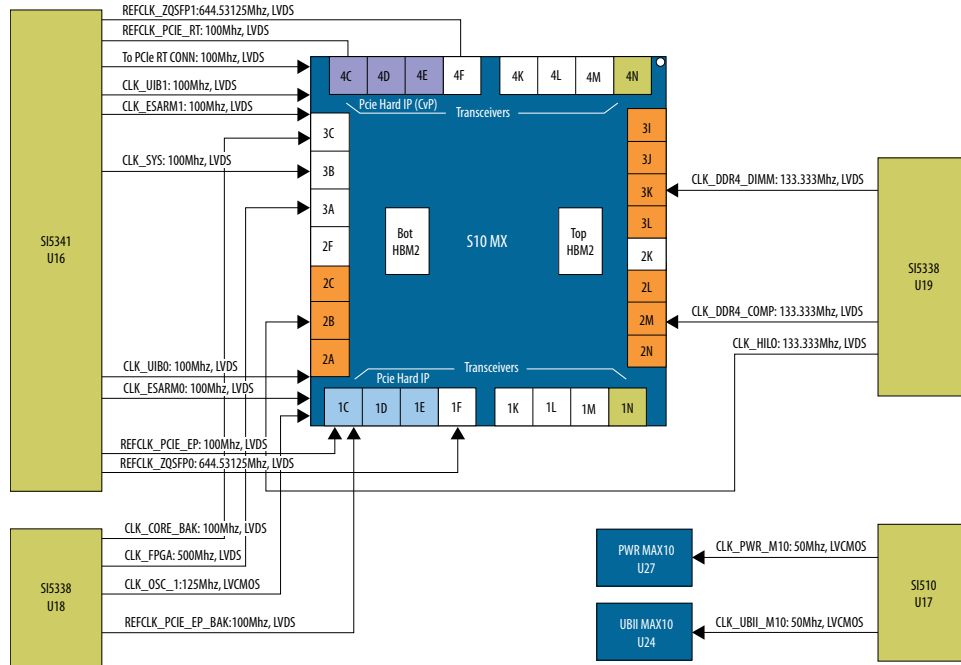


Table 27. On-board Clocks

Source	Schematic Signal Name	Default Frequency	I/O Standard	Intel Stratix 10 FPGA Pin Number	Application
U16	REFCLK_ZQSFP0_P	644.53125 MHz	LVDS	AJ43	QSFP0 Reference Clock
	REFCLK_ZQSFP0_N	644.53125 MHz	LVDS	AJ42	
	REFCLK_ZQSFP1_P	644.53125 MHz	LVDS	AJ9	QSFP1 Reference Clock
	REFCLK_ZQSFP1_N	644.53125 MHz	LVDS	AJ10	
	CLK_UIB0_P	100 MHz	LVDS	AR26	UIB0 Reference Clock
	CLK_UIB0_N	100 MHz	LVDS	AP26	
	CLK_UIB1_P	100 MHz	LVDS	P27	UIB1 Reference Clock
	CLK_UIB1_N	100 MHz	LVDS	R27	
	CLK_ESRAM0_P	100 MHz	LVDS	AU31	ESRAM0 Reference Clock
	CLK_ESRAM0_N	100 MHz	LVDS	AU32	
	CLK_ESRAM1_P	100 MHz	LVDS	V31	ESRAM1 Reference Clock
	CLK_ESRAM1_N	100 MHz	LVDS	U31	

continued...



Source	Schematic Signal Name	Default Frequency	I/O Standard	Intel Stratix 10 FPGA Pin Number	Application
	CLK_SYS_100M_P	100 MHz	LVDS	AU17	System Clock
	CLK_SYS_100M_N	100 MHz	LVDS	AU16	
	REFCLK_PCIE_RT_P	100 MHz	LVDS	AW9	PCIe Root Port Reference Clock
	REFCLK_PCIE_RT_N	100 MHz	LVDS	AW10	
	REFCLK_PCIE_EP_P	100 MHz	LVDS	AW43	PCIe End Point Reference Clock
	REFCLK_PCIE_EP_N	100 MHz	LVDS	AW42	
U18	CLK_SYS_50M_P	50 MHz	LVDS	BE17	FPGA Clocks
	CLK_SYS_50M_N	50 MHz	LVDS	BD17	
	CLK_CORE_BAK_P	100 MHz	LVDS	AT13	FPGA Core Clocks
	CLK_CORE_BAK_N	100 MHz	LVDS	AU13	
	S10_OSC_CLK_1	125 MHz	LVC MOS	AR35	Configuration Clock
	REFCLK_PCIE_EP1_N	100 MHz	LVDS	BA42	PCIe Transceivers Clock
	REFCLK_PCIE_EP1_P	100 MHz	LVDS	BA43	
U19	CLK_HILO_MEM_N	133.333 MHz	LVDS	AY31	HiLo Memory Clocks
	CLK_HILO_MEM_P	133.333 MHz	LVDS	AW31	
	CLK_DDR4_COMP_N	133.333 MHz	LVDS	B41	On-board DDR4 Memory clocks
	CLK_DDR4_COMP_P	133.333 MHz	LVDS	A42	
	CLK_DDR4_DIMM_N	133.333 MHz	LVDS	C18	DIMM Module Clocks
	CLK_DDR4_DIMM_P	133.333 MHz	LVDS	B18	

4.9. Power

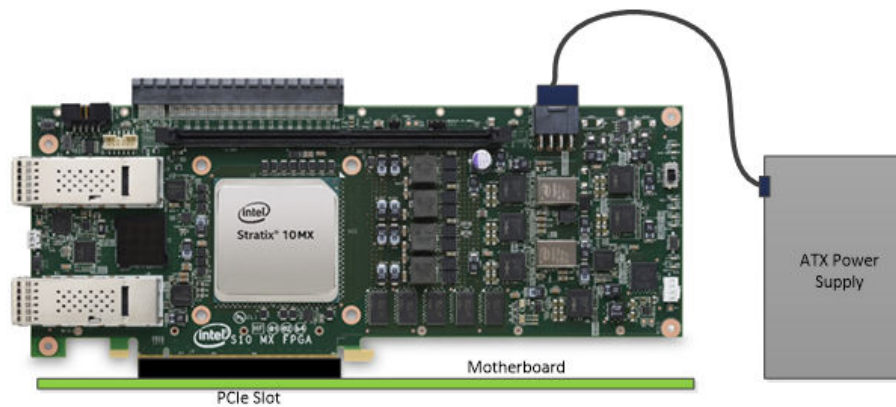
This section describes the Intel Stratix 10 MX FPGA development kit's power supply. A laptop style DC power adapter is provided with the development kit. Intel recommends that you use only the supplied power adapter. The power supply has an auto sensing input voltage of 100 ~ 240 V AC power and will output 12 V DC power at 20 A to the development board. The 12 V DC input power is then stepped down to various power rails used by the board components. An on-board multi-channel analog-to-digital converter (ADC) measures both the voltage and current for several specific board rails. The power utilization is displayed on a graphical user interface (GUI) that can graph power consumption versus time.

4.9.1. Power Guidelines

The Intel Stratix 10 FPGA development kit has two modes of operation as described below.

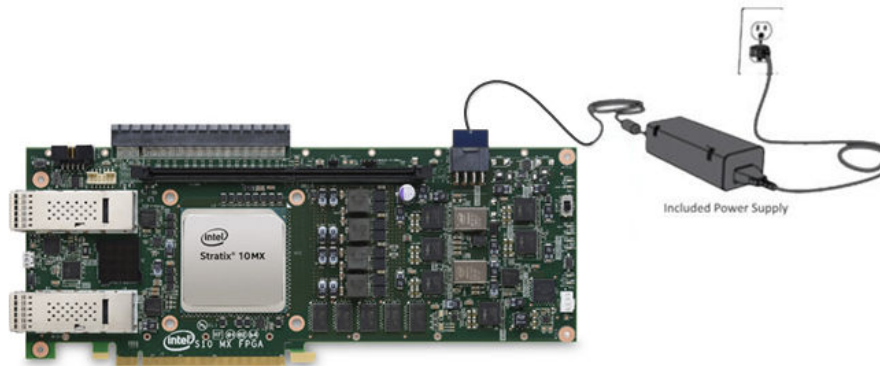
In a standard PCIe compliant system

In this mode, plug the board into an available PCI Express slot and connect the standard 2x4 power cords available from the PC's ATX power supply to J11 on the board. The PCIe slot together with the auxiliary PCIe power cords are required to power the entire board. If you do not connect the 2x4 auxiliary power connection, the board does not power on. The power switch SW3 is ignored when the board is used in the PCIe system.



As a stand-alone evaluation board powered by included power supply

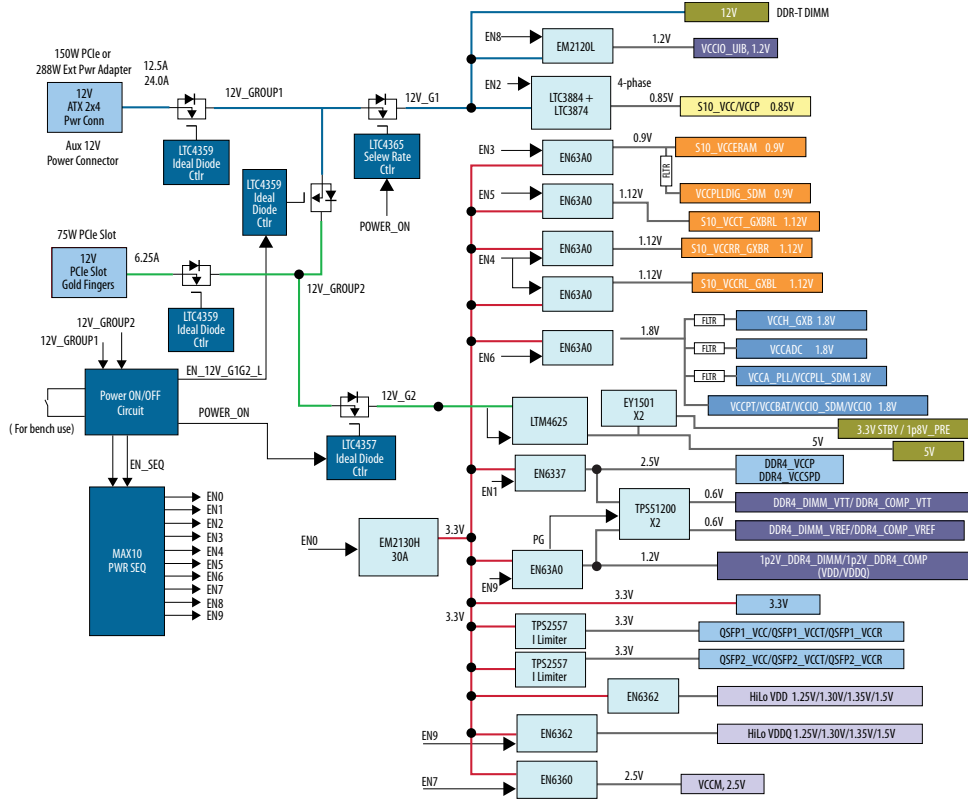
In this mode, plug the included power supply into the 2x4 pin connector (J11) and the AC power cord of the power supply into a power outlet. This power supply provides the entire power to the board without the need to obtain power from the PCIe slot. The power switch SW3 controls powering of the board.





4.9.2. Power Distribution System

Figure 15. Power Distribution System Block Diagram



Power-up Sequence: (Power-down sequence is reverse of power-up sequence)

- ① 5V/1p8V_PRE/3.3V_STBY/12V
- ② EN0: 3.3V
- ③ EN1: DDR4_VCCP, DDR4_VCCSPD, QSPF1_2_VCC, QSPF1_2_VCC7, QSPF1_2_VCCR
- ④ EN2: S10_VCC/VCCP
- ⑤ EN3: S10_VCCERAM, VCCPLLDIG_SDM
- ⑥ EN4: S10_VCCRR_GXB, S10_VCCRR_GXBL
- ⑦ EN5: S10_VCC_T_GXBRL
- ⑧ EN6: VCCPT, VCCBAT, VCCPLL_SDM, VCCA_PLL, VCCCH_GXB, VCCADC, VCCIO_SDM, VCCIO_1.8V
- ⑨ EN7: VCCM
- ⑩ EN8: VCCIO_UIB
- ⑪ EN9: VCCIO_1.2_DDR4, DDR4_VTT, DDR4_VREF, VCCIO_1.2_DDR4, DDR4_VDD, HILO VDD/VDDQ

Table 28. Power Supply List

Power Source Name	Power Name	Maximum Output Current (A)	Description
LTC3884 (U44)	VCC (0.85V) VCCP (0.85V)	132	Core Logic Power Periphery Power
EM2120L (U51)	VCCIO_UIB (1.2V)	12	Power for HBM's Universal Interface Block
EN63A0 (U46)	S10_VCCERAM (0.9V) VCCPLLDIG_SDM (0.9V)	4.6	Embedded memory and digital transceiver power

continued...



Power Source Name	Power Name	Maximum Output Current (A)	Description
EN63A0 (U49)	S10_VCCT_GXB (1.12V)	2.1	Transmitter Power
EN63A0 (U48)	S10_VCCRR_GXB (1.12V)	4.0	Receiver Power Right side
EN63A0 (U47)	S10_VCCRL_GXB (1.12V)	4.0	Receiver Power Left side
EN63A0 (U50)	VCCH_GXB(1.8V) VCCADC (1.8V) VCCA_PLL (1.8V) VCC_PLL_SDM (1.8V) VCCPT (1.8V) VCCBAT (1.8V) VCCIO_SDM (1.8V) VCCIO (1.8v)	11	Analog power for Receivers ADC power PLL Analog Global power PLL Power to SDM block Charge-pump power Battery Back-up power for encryption key Configuration pins power IO Power
LTM4625 (U40)	5V	5.0	System 5V Rail
EY1501 (U41)	3V3_STBY (3.3V)		
EY1501 (U42)	1p8V_PRE_STBY (1.8V)		
EN6337 (U58)	2p5V (2.5V) DDR4_VCCP (2.5V) DDR4_VCCSPD (2.5V)	1.0	System 2.5V Rail
EN6362 (U57)	HiLo VDD (1.25V/1.30V/ 1.35V/1.5V)	6.0	VDD power for HiLo
EN6362 (U56)	HiLo VDDQ (1.25V/1.30V/ 1.35V/1.5V)	2.0	VDDQ power for HiLo
EN6360 (U60)	VCCM (2.5V)	2.6	Embedded HBM2 memory power
EM2130H(U43)	3p3V (3.3V)	30	System 3.3V rail
TPS51200 (U54)	0p6V_DDR4_DIMM_VTT (0.6V)	1mA	Termination power for DIMM
TPS51200 (U55)	0p6V_DDR4_COMP_VTT (0.6V)	1mA	Termination power for on-board DDR4
12V_G1, 12V_G2	12V	20	System 12V rail

4.9.3. Power Sequence

The Power Sequencing function is implemented using an Intel MAX 10 device while sequencing 5 rails. The following voltage rails are sequenced up in the following group order from 1-3. Sequence down is the reverse order from 3-1.

- Group 1: VCC, VCCP, VCCERAM, VCCPLLDIG_SDM, VCCR_GXB, VCCT_GXB
- Group 2: VCCPT, VCCBAT, VCCIO_SDM, VCCIO_1.8V, VCCH_GXB, VCCA_PLL, VCCPLL_SDM, VCCADC
- Group 3: VCCIO_1.2_DDR4, VCCM, VCCIO_UIB, VCCIO_SDM, VCCFUSEWR_SDM

Note: Please refer to [AN 692: Power Sequencing Considerations for Intel Cyclone 10 GX, Intel Arria 10, and Intel Stratix 10 Devices](#) for additional information on Intel Stratix 10 FPGA power sequencing,

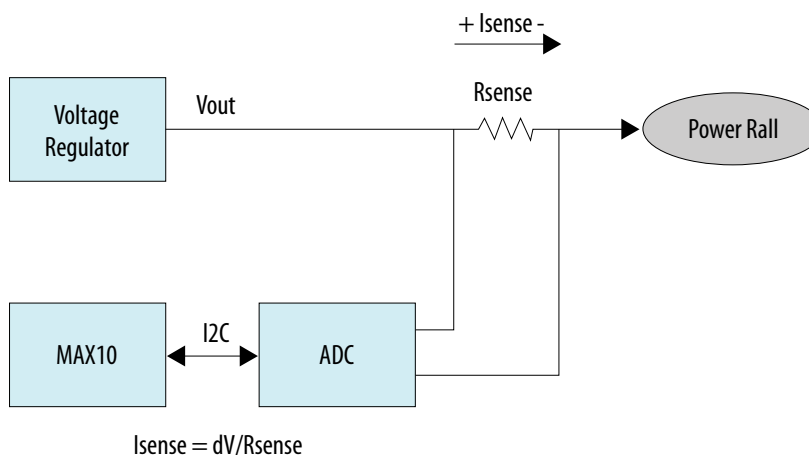
4.9.4. Power Measurement

Power measurements are provided for six FPGA power rails by using an ADC and sense resistors. The sense resistors are connected in series to the power regulator output. The I²C interface of the ADC or the regulators are used to sense the voltages. The I²C are connected to the Intel MAX 10 device for reading the voltage. Current reading is achieved by a LTC2497 reading the voltage drop across the sense resistor and software converts the voltage readings to current for each measured rail.

The following power rails are monitored:

1. VCC, VCCP (Power sensing by I²C on LTC3884)
2. VCCRERAM (Sense resistor R424, monitoring via LTC2497, U28)
3. VCCRL (Sense resistor R437, monitoring via LTC2497, U28)
4. VCCRR (Sense resistor R450, monitoring via LTC2497, U28)
5. VCCT (Sense resistor R463, monitoring via LTC2497, U28)
6. VCCIO_UIB (Power sensing by I²C on EM2120L, U51)
7. 3.3V (Power sensing by I²C on EM2130H, U43)

Figure 16. Power Measurement



4.9.5. Power Fast Discharging

The Intel Stratix 10 MX FPGA development kit implements a Fast Discharging circuit to facilitate a rapid discharging the capacitors of certain power rails during system power down sequence. This is to ensure the voltages are at minimum levels in case the system needs to be powered up again. The design is implemented using a Field Effect Transistor (FET), which is turned on to discharge of its respective power rail to ground through a Bleeding resistor during system power down.

The following rails are implemented with Fast Discharging:

- 1p2V_DDR4
- 1p2V_VCCIO_UIB
- HiLo_VDD



- HiLo_VDDQ
- 3p3V
- 2p5V
- VCCM
- 1p8V
- S10_VCCRL_GXB
- S10_VCCRR_GXB
- S10_VCCT_GXB
- S10_VCCERAM

4.9.6. Thermal Limitations and Protection

The Intel Stratix 10 MX FPGA development kit is designed to operate in a typical laboratory environment with an ambient temperature of approximately 25 °C. The cooling solution provided with the development kit allows sufficient cooling for the board to operate up to a maximum power consumption of 243 W under this environment.

A MAX1619 device is connected to the Intel Stratix 10 MX FPGA internal temperature diode to continuously monitor the FPGA internal temperature. In the meantime, a dedicated FPGA TSD real-time monitor solution under `~\ip\onchip_sensors\` is added to each transceiver or EMIF example design to monitor the temperatures of both FPGA core and each transceiver tile.

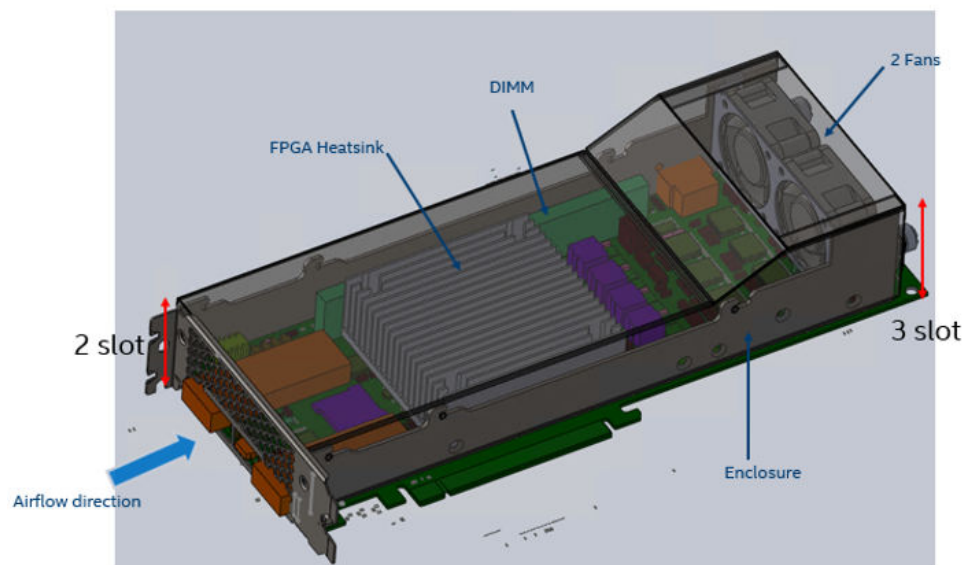
Based on the data from both MAX1619, and the Intel Stratix 10 MX FPGA will run at its maximum speed whenever any temperature is over 60 °C or immediately power off the board whenever the temperature crosses 100 °C.

Caution: Remember to unplug the power supply when the board is powered off when the temperature crosses 100 °C. Plug the power supply back again to ensure that the board can be normally turned on/off again.

4.9.7. Cooling Design

The Intel Stratix 10 MX FPGA development kit utilizes air-cooled design to maintain proper cooling of the board at maximum loads. Air is forced to blow from the front to the rear of the enclosure by two 40 mm x 40 mm fans. It requires a total airflow of 22 CFM to cool the board with maximum power of 243 W at 25 °C. Top cover is required during operations for proper cooling of the board.

Caution: Please ensure that the fan cable is connected during operation.

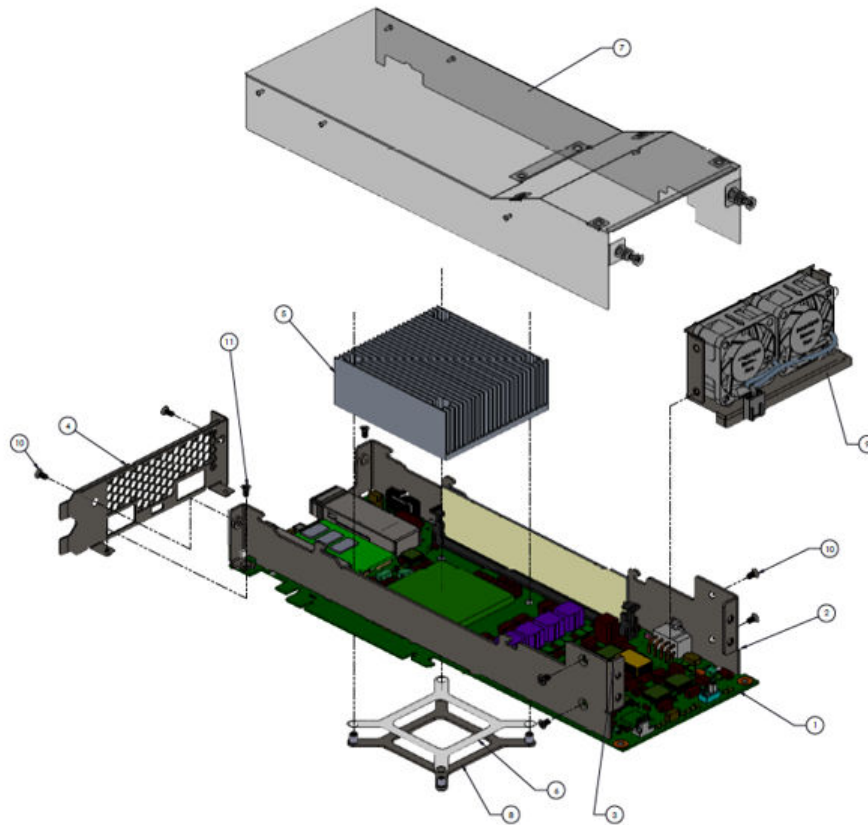


4.9.8. Mechanical Information

The Intel Stratix 10 MX FPGA development kit is a PCIe form factor with the following board dimensions:

- Width = 4.376 inches
- Length = 10.8 inches
- Height = 1.37 inches

Figure 17. Assembly View



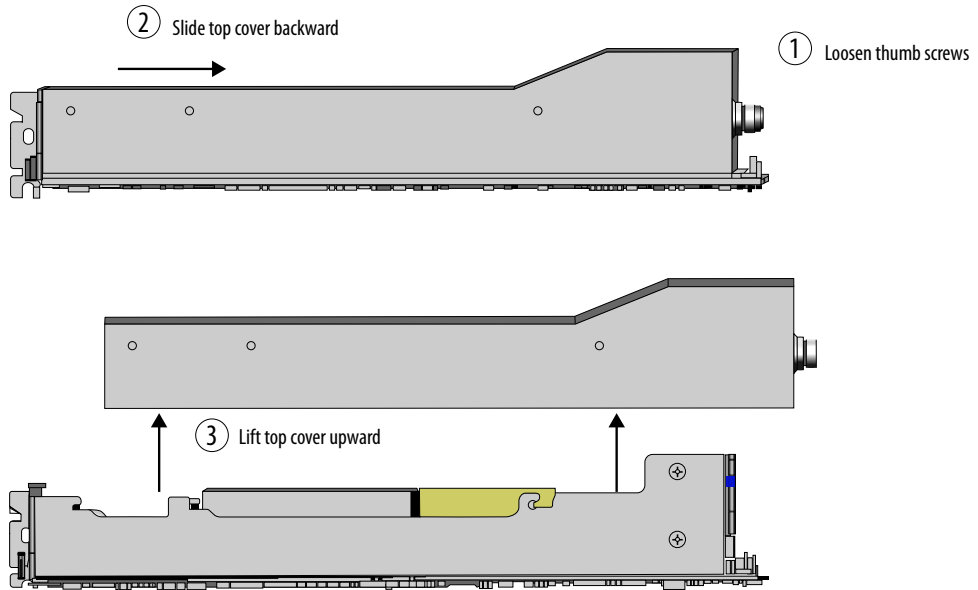
4.9.9. Top Cover Removal

The Intel Stratix 10 MX FPGA development kit is designed to operate with the top cover enclosed during normal operations.

To gain access to the top side of the board for tasks such as replacing DIMM module, HiLo module, or probing of test points, the top cover can be removed by following the instructions below:

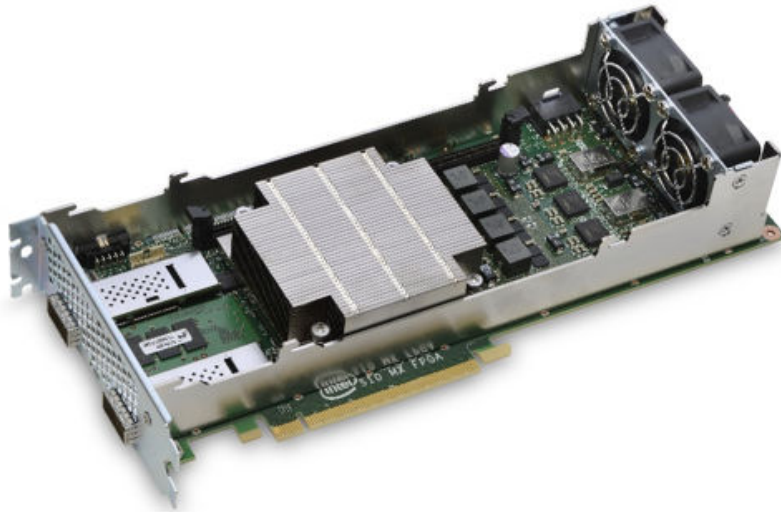
1. Loosen the two thumb screws on the rear of the enclose
2. Lift the top cover upward until it stops
3. Slide the top cover backward and lift again to remove

Figure 18. Top Cover Removal for Intel Stratix 10 MX FPGA development kit
Steps for removing the top cover



Note: Top cover is required for proper cooling of the board

Figure 19. Intel Stratix 10 MX FPGA development kit with top cover removed



5. Board Test System

The Intel Stratix 10 MX FPGA Development Kit includes an application called Board Test System (BTS) to test the functionality of this board. The BTS provides an easy-to-use Graphical User Interface (GUI) to alter functional settings and observe results. You can use the BTS to test board components, modify functional parameters, observe performance and measure power usage.

The BTS communicates over the JTAG bus to a test design running in the Intel Stratix 10 MX FPGA device. You can use the BTS to reconfigure the FPGA with test designs specific to the functionality that you are testing.

The BTS is also useful as a reference for designing systems.

Figure 20. BTS GUI Home

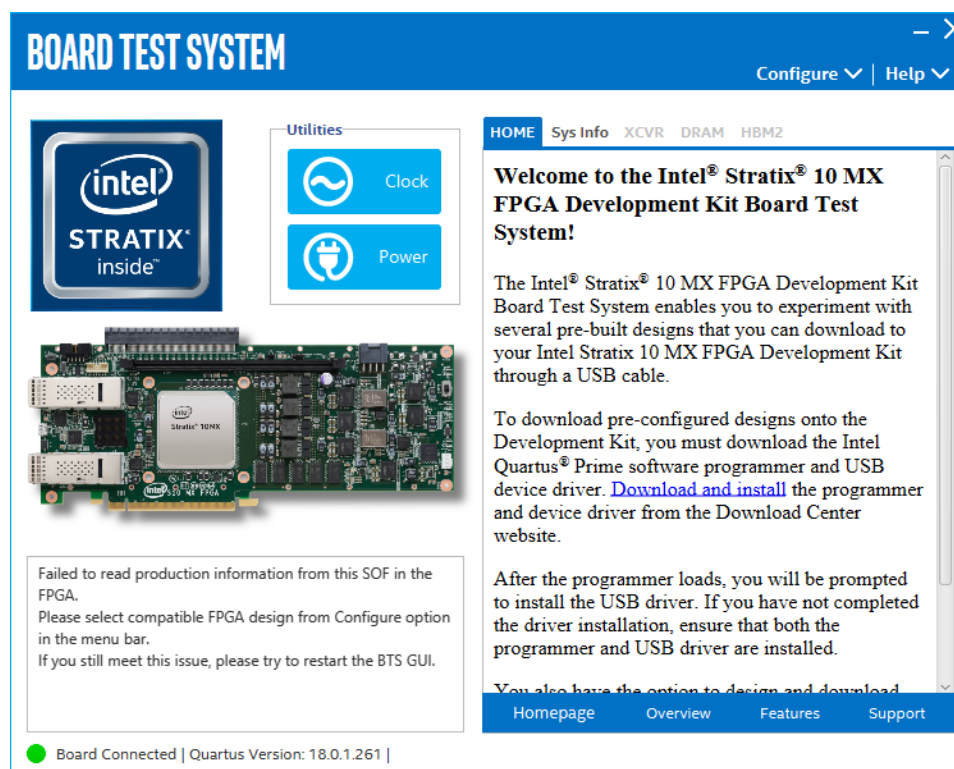
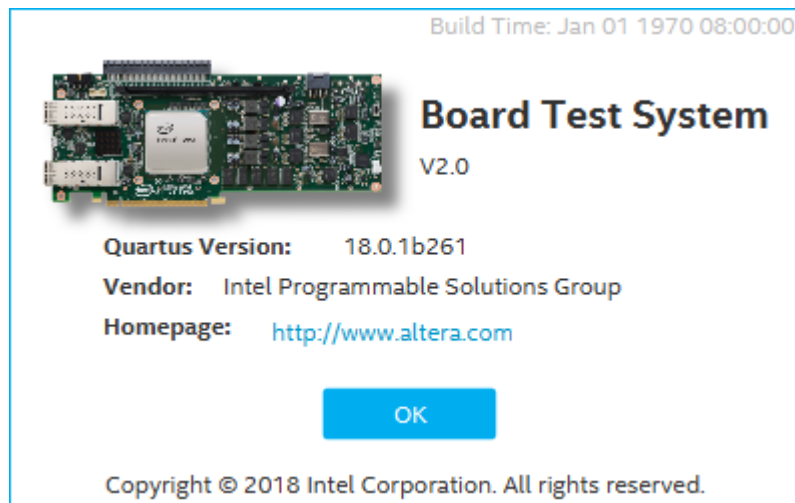




Figure 21. About BTS



5.1. Preparing the Board

Several designs are provided to test the major board features. Each design provides data for one or more tabs in the application. The **Configure Menu** identifies the appropriate design to download to the FPGA for each tab.

After successful FPGA configuration, the appropriate tab appears that allows you to exercise the related board features. Highlights appear in the board picture around the corresponding components.

The BTS communicates over the JTAG bus to a test design running in the FPGA. The BTS and Power Monitor share the JTAG bus with other applications like the Nios II debugger and the Signal Tap II Embedded Logic Analyzer. Because the BTS is designed based on the Intel Quartus Prime software, be sure to close other applications before you use the BTS.

The BTS relies on the Intel Quartus Prime software's specific library. Before running the BTS, open the Intel Quartus Prime software to automatically set the environment variable `$QUARTUS_ROOTDIR`. The BTS uses this environment variable to locate the Intel Quartus Prime library. The version of Intel Quartus Prime software set in the `QUARTUS_ROOTDIR` environment variable should be newer than version 14.1. For example, the Development Kit Installer version 15.1 requires that the Intel Quartus Prime software 14.1 or later version to be installed.

Also, to ensure that the FPGA is configured successfully, you should install the latest Intel Quartus Prime software that can support the silicon on the development kit. For this board, we recommend you install Intel Quartus Prime version 18.0.1b261.

Please refer to the `README.txt` file under `\examples\board_test_system` directory.

5.2. Running the Board Test System



Before you begin

With the power to the board turned off, follow these steps:

1. Connect the USB cable to your PC and the board.
2. Check whether the board switches and jumpers are set according to your preferences.
3. Turn on the power to the board.

To ensure operating stability, keep the USB cable connected and the board powered on when running the demonstration application. The BTS cannot run correctly unless the USB cable is attached and the board is powered on.

To run the BTS

1. Navigate to the `<package_dir>\examples\board_test_system` directory and run the `BoardTestSystem.exe` application.
2. A GUI appears, displaying the application tab corresponding to the design running in the FPGA. If the design loaded in the FPGA is not supported by the BTS GUI, you receive a message prompting you to configure your board with a valid BTS design. Refer to the **Configure Menu** on configuring your board.

If some design is running in the FPGA, the BTS GUI loads the design file (`.sof`) in the image folder to check the current running design in the FPGA, therefore the design running in the FPGA must be the same as the design file in the image folder.

5.3. Using the Board Test System

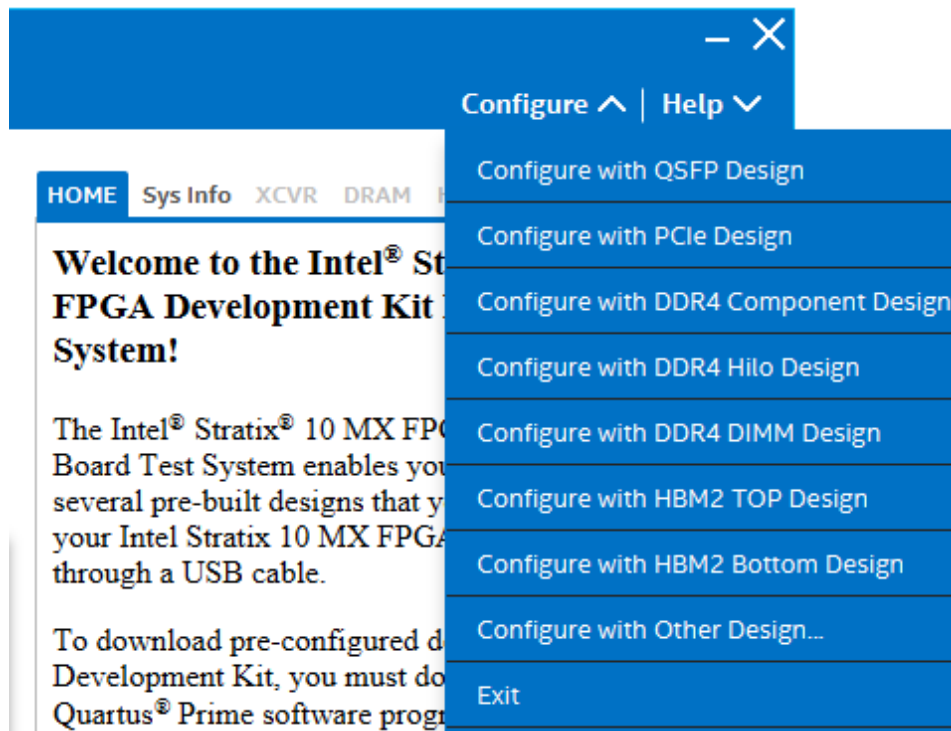
This section describes each tab in the BTS.

5.3.1. The Configure Menu

Use the Configure Menu to select the design you want to use. Each design example tests different board features. Select a design from this menu and the corresponding tabs become active for testing.



Figure 22. The Configure Menu



To configure the FPGA with a test system design, perform the following steps:

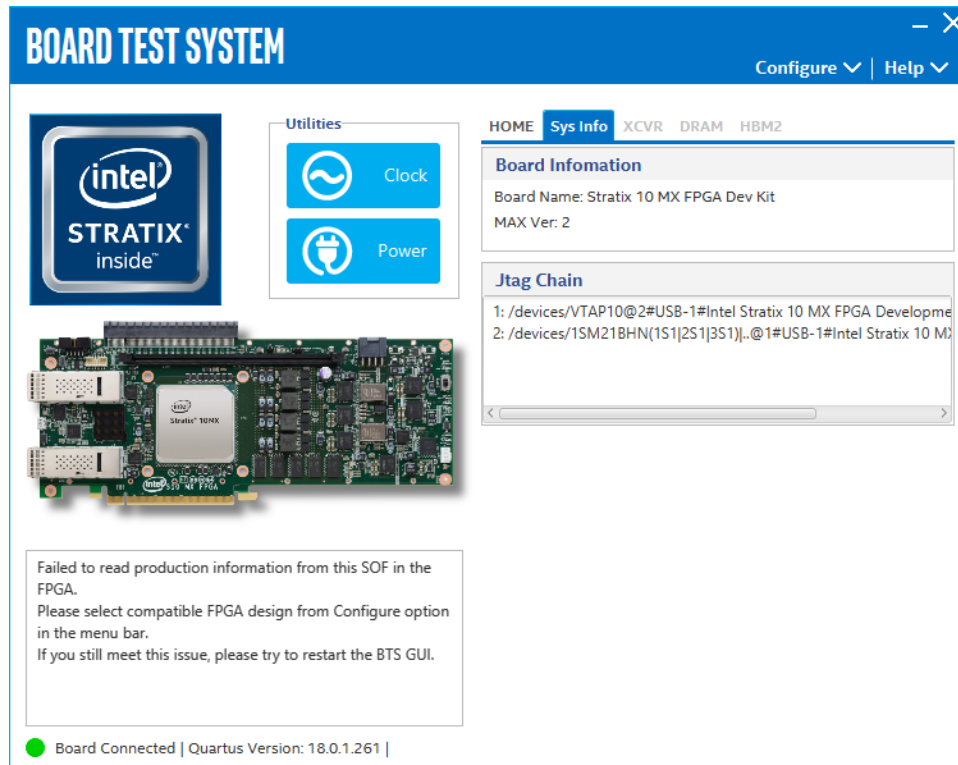
1. On the **Configure** menu, click the configure command that corresponds to the functionality you wish to test.
2. In the dialog box that appears, click **Configure** to download the corresponding design to the FPGA.
3. When configuration finishes, close Intel Quartus Prime if it's already open. The design begins running in the FPGA. The corresponding GUI application tabs that interface with the design are now enabled.

Note: If you use the Intel Quartus Prime Programmer for configuration, rather than the BTS GUI, you may need to restart the GUI.

5.3.2. The Sys Info Tab

The Sys Info tab shows the board's current configuration. The tab displays the contents of the Intel MAX 10 registers, the JTAG chain, the board's MAC address, and other details stored on the board.

Figure 23. The Sys Info Tab



The following sections describe the controls of the Sys Info tab.

Board Information

The Board Information control displays static information about your board:

- Board Name: Indicates the official name of the board given by the BTS.
- Board Revision: Indicates the revision of the board.
- MAX Ver: Indicates the version of Intel MAX 10 code currently running on the board.

JTAG Chain

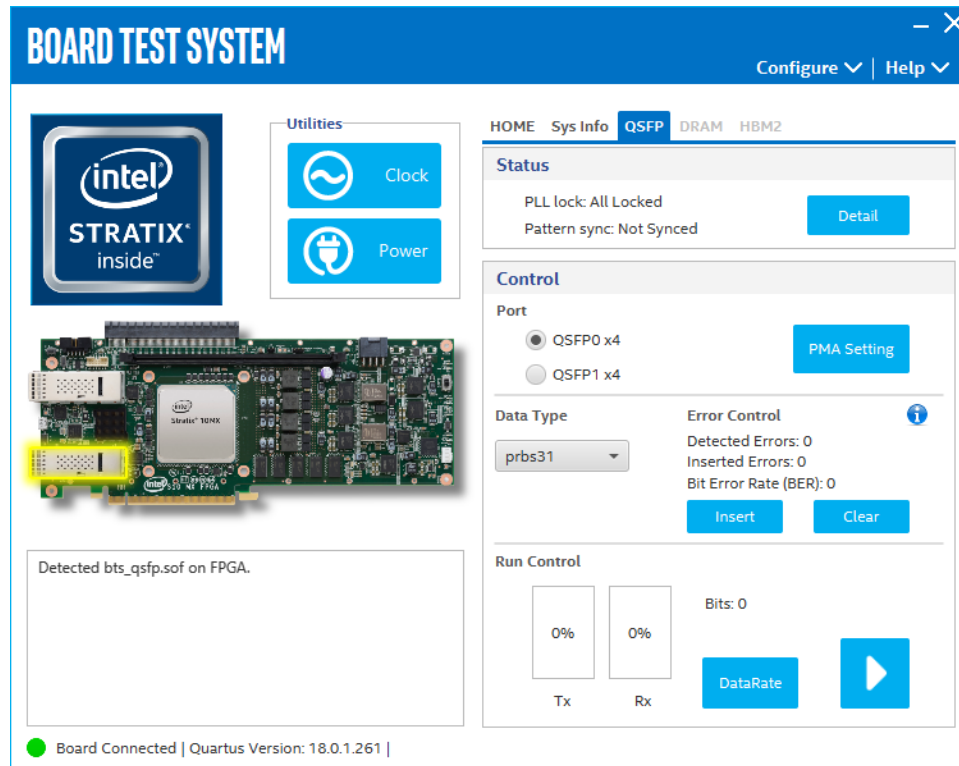
The JTAG chain shows all the devices currently in the JTAG chain.

5.3.3. The QSFP Tab

This tab allows you to perform loopback tests on the QSFP ports.



Figure 24. The QSFP Tab



The following sections describe the controls on the QSFP Tab

Status

Displays the following status information during a loopback test:

- **PLL Lock:** Shows the PLL locked or unlocked state.
- **Pattern sync:** Shows the pattern synced or not synced state. The pattern is considered synced when the start of the data sequence is detected.
- **Details:** Shows the PLL lock and pattern sync status:

Channel	PLL Lock Status	Pattern Sync Status	Errors
0	Locked	Synced	0
1	Locked	Synced	0
2	Locked	Synced	0
3	Locked	Synced	0

Port

Allows you to specify which interface to test. The following port tests are available:

- QSFP0 x4
- QSFP1 x4

PMA Setting

Allows you to make changes to the PMA parameters that affect the active transceiver interface. The following settings are available for analysis:

- **Serial Loopback:** Routes signals between the transmitter and the receiver.
- **VOD:** Specifies the voltage output differential of the transmitter buffer.
- **Pre-emphasis tap:**
 - 1st pre: Specifies the amount of pre-emphasis on the pre-tap of the transmitter buffer.
 - 1st post: Specifies the amount of pre-emphasis on the first post tap of the transmitter buffer.
- **Equalizer:** Specifies the CLTE EQ Gain for the receiver.
- **AC Gain:** Specifies the CLTE AC Gain for the receiver.
- **VGA:** Specifies the VGA gain value.

	Serial Loopback	Pre-emphasis tap					
		VOD	1st Pre	1st Post	Equalizer	AC Gain	VGA
<input type="checkbox"/> All CH	<input type="checkbox"/>	31	0	0	0	0	16
Ch0	<input type="checkbox"/>	31	0	0	0	8	16
Ch1	<input type="checkbox"/>	31	0	0	32	0	0
Ch2	<input type="checkbox"/>	31	0	0	31	8	0
Ch3	<input type="checkbox"/>	31	0	0	30	0	0

Data Type

Specifies the type of data contained in the transactions. The following data types are available for analysis:

- **PRBS 7:** Selects pseudo-random 7-bit sequences.
- **PRBS 15:** Selects pseudo-random 15-bit sequences.
- **PRBS 23:** Selects pseudo-random 23-bit sequences.
- **PRBS 31:** Selects pseudo-random 31-bit sequences.
- **HF:** Selects highest frequency divide-by-2 data pattern 10101010.
- **LF:** Selects lowest frequency divide-by-33 data pattern.



Error Control

Displays data errors detected during analysis and allows you to insert errors:

- **Detected errors:** Displays the number of data errors detected in the hardware.
- **Inserted errors:** Displays the number of errors inserted into the transmit data stream.
- **Insert:** Inserts a one-word error into the transmit data stream each time you click the button. Insert is only enabled during transaction performance analysis.
- **Clear:** Resets the Detected errors and Inserted errors counters to zeroes.

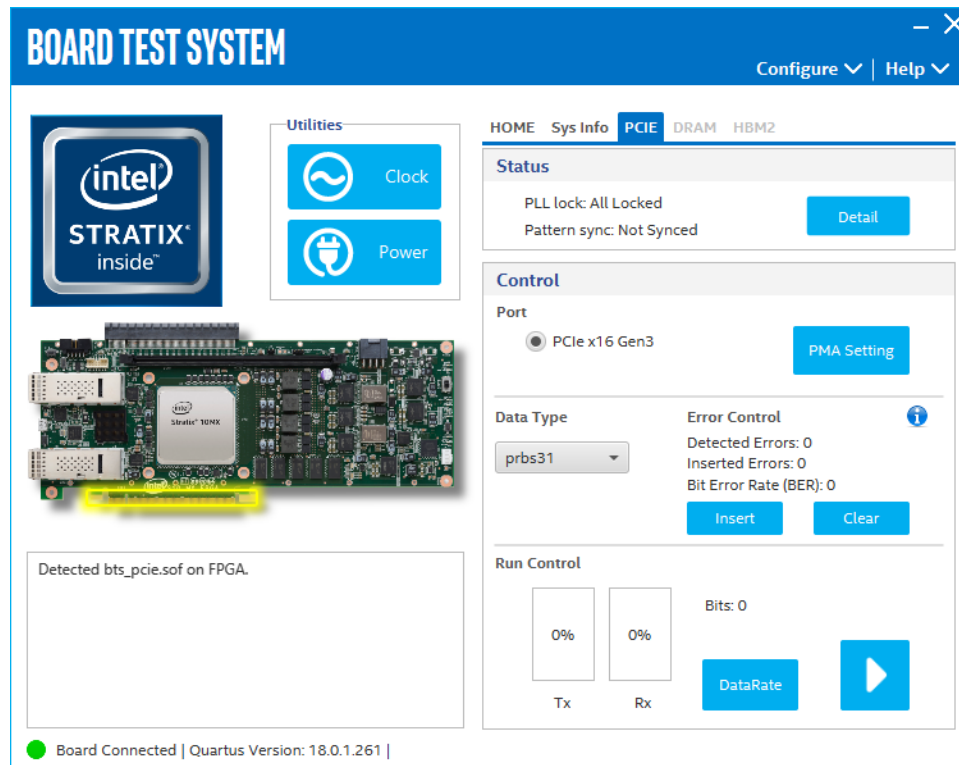
Loopback

- **Start:** Initiates the selected ports transaction performance analysis. Always click Clear before Start.
- **Stop:** Terminates transaction performance analysis.
- **TX and RX performance bars:** Show the percentage of maximum theoretical data rate that the requested transactions are able to achieve.

5.3.4. The PCIE Tab

This tab allows you to run a PCIe loopback test on your board. You can also load the design and use an oscilloscope to measure an eye diagram of the PCIe transmit signals.

Figure 25. The PCIE Tab



The following sections describe the controls on the PCIE tab.

Status

Displays the following status information during a loopback test:

- **PLL Lock:** Shows the PLL locked or unlocked state.
- **Pattern sync:** Shows the pattern synced or not synced state. The pattern is considered synced when the start of the data sequence is detected.
- **Details:** Shows the PLL lock and pattern sync status:

Channel	PLL Lock Status	Pattern Sync Status	Errors
0	Locked	Synced	0
1	Locked	Synced	0
2	Locked	Synced	0
3	Locked	Synced	0
4	Locked	Synced	0
5	Locked	Synced	0
6	Locked	Synced	0
7	Locked	Synced	0
8	Locked	Synced	0
9	Locked	Synced	0
10	Locked	Synced	0
11	Locked	Synced	0
12	Locked	Synced	0
13	Locked	Synced	0
14	Locked	Synced	0
15	Locked	Synced	0

Port

PCIe x16 Gen3

PMA Setting

Allows you to make changes to the PMA parameters that affect the active transceiver interface. The following settings are available for analysis:



- **Serial Loopback:** Routes signals between the transmitter and the receiver.
- **VOD:** Specifies the voltage output differential of the transmitter buffer.
- **Pre-emphasis tap:**
 - 1st pre: Specifies the amount of pre-emphasis on the pre-tap of the transmitter buffer.
 - 1st post: Specifies the amount of pre-emphasis on the first post tap of the transmitter buffer.
- **Equalizer:** Specifies the CLTE EQ Gain for the receiver.
- AC Gain: Specifies the CLTE AC Gain for the receiver.
- **VGA:** Specifies the VGA gain value.

All PMA settings should be changed as given in the figure below:

PMA SETTING — X

	Serial Loopback	Pre-emphasis tap					
		VOD	1st Pre	1st Post	Equalizer	AC Gain	VGA
<input type="checkbox"/> All CH	<input type="checkbox"/>	31	0	0	0	0	0
Ch0	<input type="checkbox"/>	31	0	0	0	0	0
Ch1	<input type="checkbox"/>	31	0	0	0	0	0
Ch2	<input type="checkbox"/>	31	0	0	0	0	0
Ch3	<input type="checkbox"/>	31	0	0	0	0	0
Ch4	<input type="checkbox"/>	31	0	0	0	0	0
Ch5	<input type="checkbox"/>	31	0	0	0	0	0
Ch6	<input type="checkbox"/>	31	0	0	0	0	0
Ch7	<input type="checkbox"/>	31	0	0	0	0	0
Ch8	<input type="checkbox"/>	31	0	0	0	0	0
Ch9	<input type="checkbox"/>	31	0	0	0	0	0
Ch10	<input type="checkbox"/>	31	0	0	0	0	0
Ch11	<input type="checkbox"/>	31	0	0	0	0	0
Ch12	<input type="checkbox"/>	31	0	0	0	0	0
Ch13	<input type="checkbox"/>	31	0	0	0	0	0
Ch14	<input type="checkbox"/>	31	0	0	0	0	0
Ch15	<input type="checkbox"/>	31	0	0	0	0	0

Data Type

Specifies the type of data contained in the transactions. The following data types are available for analysis:

- **PRBS 7:** Selects pseudo-random 7-bit sequences.
- **PRBS 15:** Selects pseudo-random 15-bit sequences.
- **PRBS 23:** Selects pseudo-random 23-bit sequences.
- **PRBS 31:** Selects pseudo-random 31-bit sequences.
- **HF:** Selects highest frequency divide-by-2 data pattern 10101010.
- **LF:** Selects lowest frequency divide-by-33 data pattern.

Error Control

Displays data errors detected during analysis and allows you to insert errors:



- **Detected errors:** Displays the number of data errors detected in the hardware.
- **Inserted errors:** Displays the number of errors inserted into the transmit data stream.
- **Insert error:** Inserts a one-word error into the transmit data stream each time you click the button. Insert error is only enabled during transaction performance analysis.
- **Clear:** Resets the detected errors and inserted errors counters to zeroes.

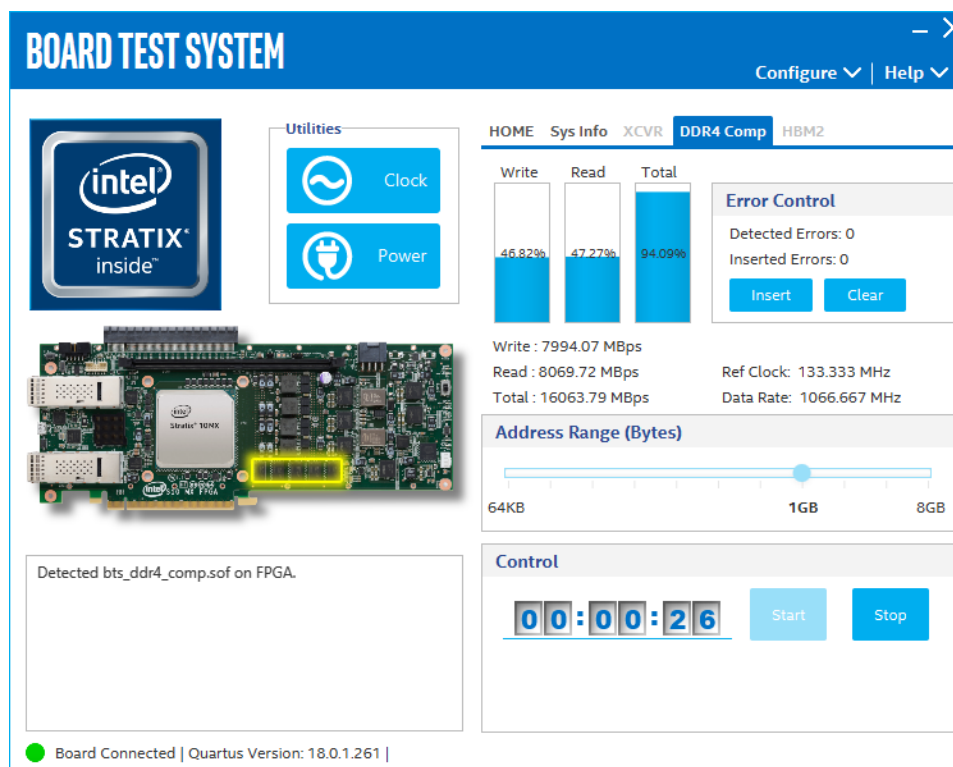
Loopback

- **Start:** Initiates the selected port's transaction performance analysis. Always click Clear before Start.
- **Stop:** Terminates transaction performance analysis.
- **TX and RX performance bars:** Show the percentage of maximum theoretical data rate that the requested transactions are able to achieve.

5.3.5. The Component DDR4 Tab

This tab allows you to read and write Component DDR4 memory on your board.

Figure 26. The Component DDR4 Tab



The following sections describe the controls on the Component DDR4 tab.



Start

Initiates DDR4 memory transaction performance analysis.

Stop

Terminates transaction performance analysis.

Performance Indicator

These controls display current transaction performance analysis information collected since you last clicked Start:

- **Write, Read and Total performance bars:** Show the percentage of maximum theoretical data rate that the requested transactions are able to achieve.
- **Write (MBps), Read (MBps) and Total (MBps):** Show the number of bytes analyzed per second.
- **Data Bus:** 72 bits(8 bits ECC) wide and the frequency is 1066 MHz double data rate. 2133 Mbps per pin. Equating to a theoretical maximum bandwidth of 136,512 Mbps or 17,064 MBps.

Error Control

This control displays data errors detected during analysis and allows you to insert errors:

- **Detected errors:** Displays the number of data errors detected in the hardware.
- **Inserted errors:** Displays the number of errors inserted into the transaction stream.
- **Insert:** Inserts a one-word error into the transaction stream each time you click the button. Insert Error is only enabled during transaction performance analysis.
- **Clear:** Resets the detected error and inserted error counters to zeroes.

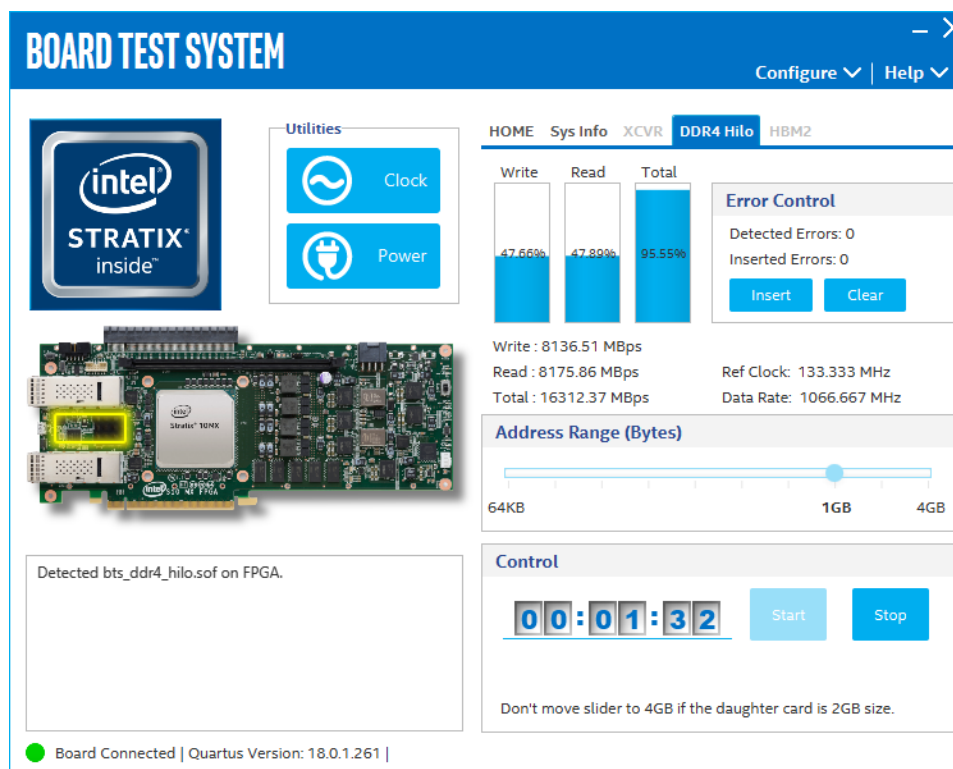
Address Range

Determines the number of addresses to use in each iteration of reads and writes.

5.3.6. The HiLo DDR4 Tab

This tab allows you to read and write HiLo DDR4 memory on your board.

Figure 27. The HiLo DDR4 Tab



The following sections describe the controls on the DDR4 tab.

Start

Initiates DDR4 memory transaction performance analysis.

Stop

Terminates transaction performance analysis.

Performance Indicators

These controls display current transaction performance analysis information collected since you last clicked Start:

- **Write, Read and Total performance bars:** Show the percentage of maximum theoretical data rate that the requested transactions are able to achieve.
- **Write (MBps), Read (MBps) and Total (MBps):** Show the number of bytes analyzed per second.
- **Data Bus:** 72 bits (8 bits ECC) wide and the frequency is 1066 MHz double data rate. 2133 Mbps per pin. Equating to a theoretical maximum bandwidth of 136,512 Mbps or 17,064 MBps.

Error Control

This control displays data errors detected during analysis and allows you to insert errors:

- **Detected errors:** Displays the number of data errors detected in the hardware.
- **Inserted errors:** Displays the number of errors inserted into the transaction stream.
- **Insert:** Inserts a one-word error into the transaction stream each time you click the button. Insert Error is only enabled during transaction performance analysis.
- **Clear:** Resets the detected error and inserted error counters to zeroes.

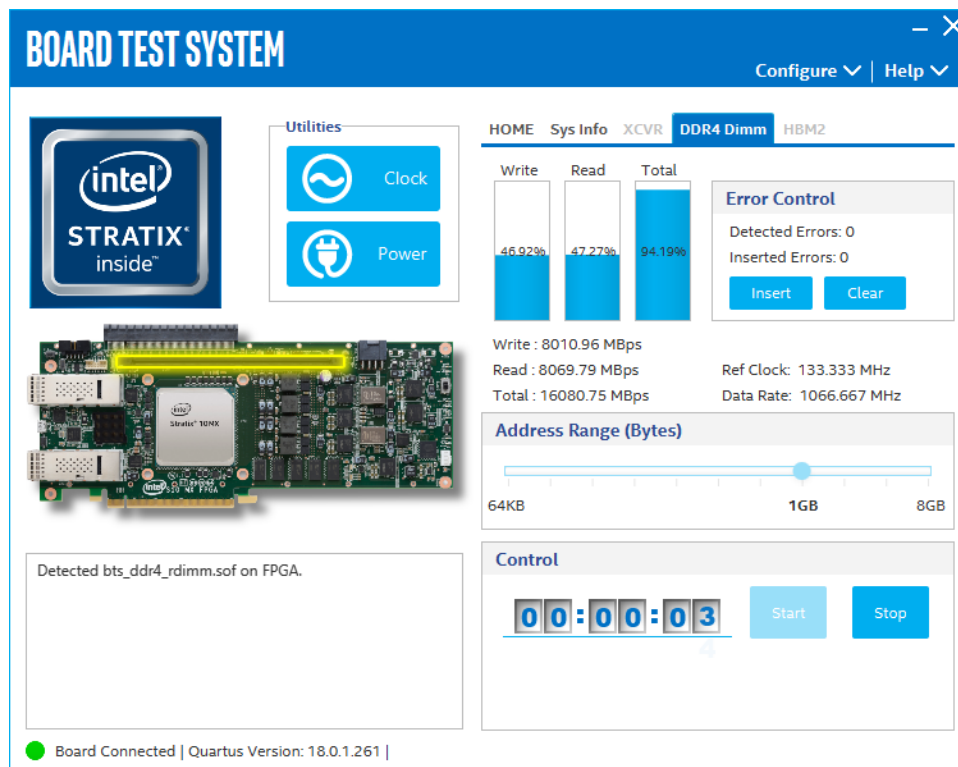
Address Range

Determines the number of addresses to use in each iteration of reads and writes.

5.3.7. The DDR4 Dimm Tab

This tab allows you to read and write Dual Inline Memory Module (DIMM) DDR4 memory on your board.

Figure 28. The DDR4 Dimm Tab



The following sections describe the controls on the DDR4 tab.

Start

Initiates DDR4 memory transaction performance analysis.

Stop

Terminates transaction performance analysis.



Performance Indicators

These controls display current transaction performance analysis information collected since you last clicked Start:

- **Write, Read and Total performance bars:** Show the percentage of maximum theoretical data rate that the requested transactions are able to achieve.
- **Write (MBps), Read (MBps) and Total (MBps):** Show the number of bytes analyzed per second.
- **Data Bus:** 72 bits (8 bits ECC) wide and the frequency is 1066 MHz double data rate. 2133 Mbps per pin. Equating to a theoretical maximum bandwidth of 136,512 Mbps or 17,064 MBps.

Error Control

This control displays data errors detected during analysis and allows you to insert errors:

- **Detected errors:** Displays the number of data errors detected in the hardware.
- **Inserted errors:** Displays the number of errors inserted into the transaction stream.
- **Insert:** Inserts a one-word error into the transaction stream each time you click the button. Insert Error is only enabled during transaction performance analysis.
- **Clear:** Resets the detected error and inserted error counters to zeroes.

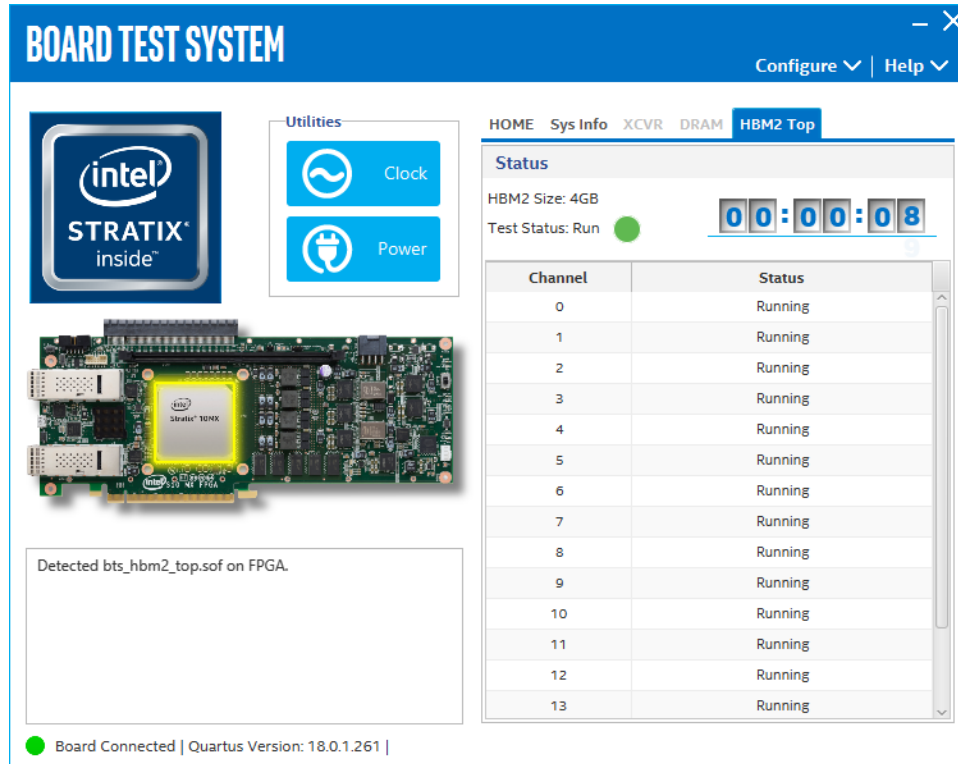
Address Range

Determines the number of addresses to use in each iteration of reads and writes.

5.3.8. The HBM2 Top Tab

This tab allows you to read and write the top bank of HBM2 on your board.

Figure 29. The HBM2 Top Tab



The following sections describe the controls on the HBM2 tab.

Status Indicators

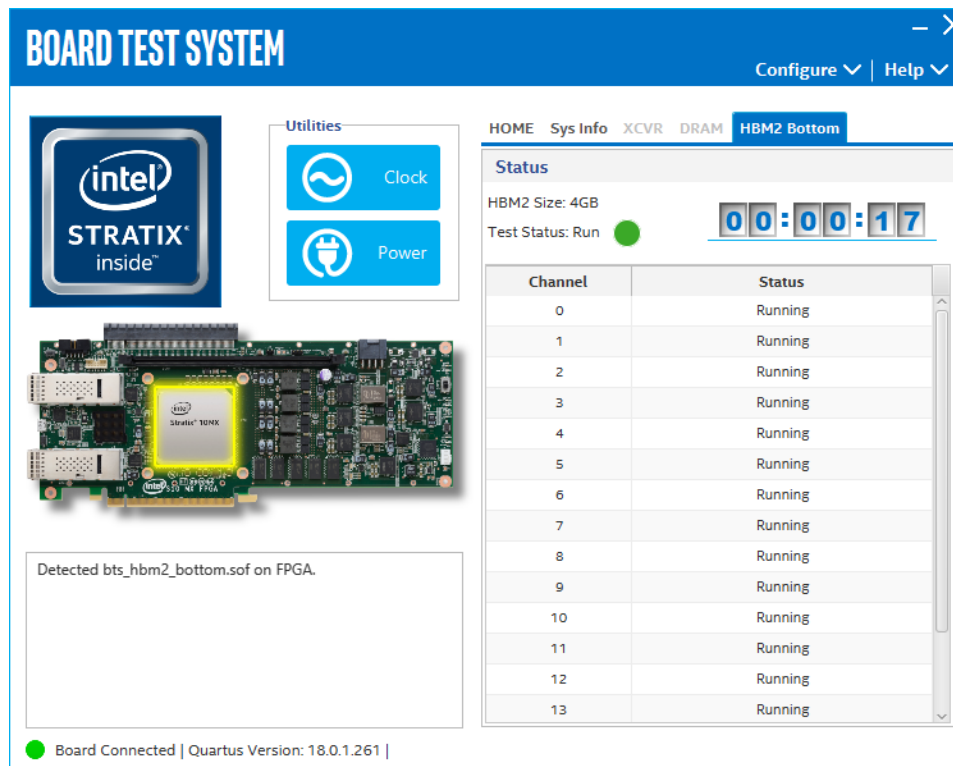
- **HBM2 Size:** Indicates the memory size of HBM2.
- **Test Status:** Indicates the status of the overall test, the table shows each channel status of HBM2.

5.3.9. The HBM2 Bottom Tab

This tab allows you to read and write the bottom bank of HBM2 on your board.



Figure 30. The HBM2 Bottom Tab



The following sections describe the controls on the HBM2 tab.

Status Indicators

- **HBM2 Size:** Indicates the memory size of HBM2.
- **Test Status:** Indicates the status of the overall test, the table shows each channel status of HBM2.

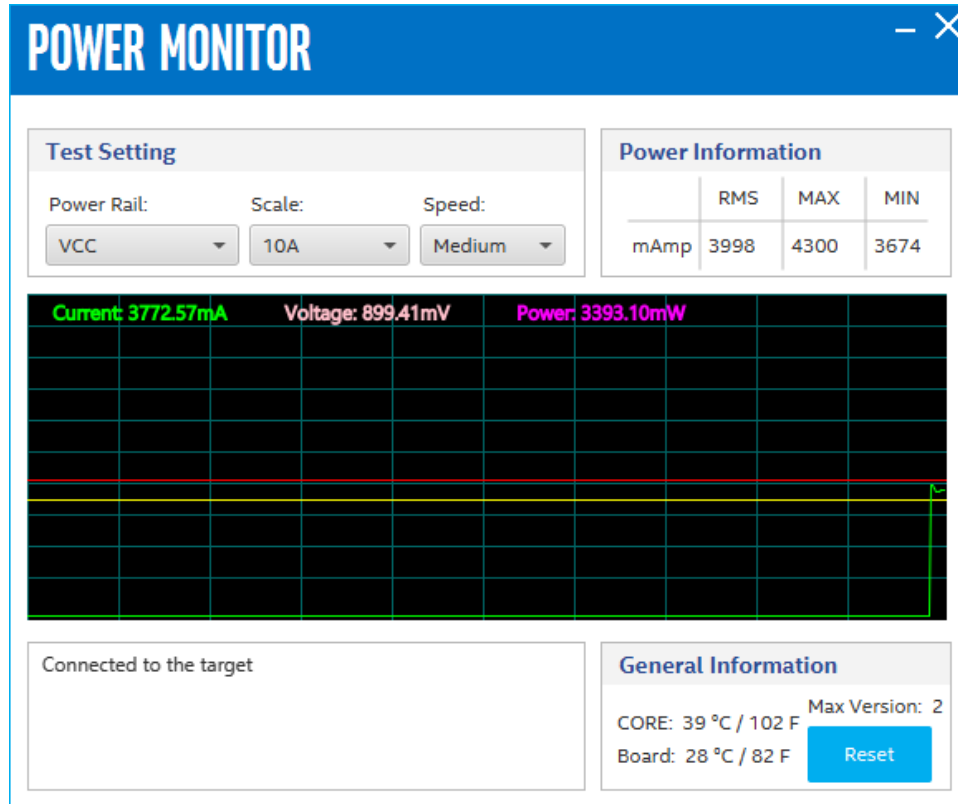
5.3.10. Power Monitor

The Power Monitor measures and reports current power information and communicates with the Intel MAX 10 device on the board through the JTAG bus. A power monitor circuit attached to the Intel MAX 10 device allows you to measure the power that the Intel Stratix 10 MX FPGA is consuming.

To start the application, click the **Power Monitor** icon in the BTS. You can also run the Power Monitor as a stand-alone application. The `PowerMonitor.exe` resides in the `<package_dir>\examples\board_test_system` directory.

Note: You cannot run the stand-alone power application and the BTS simultaneously. Also, you cannot run power and clock interface at the same time.

Figure 31. Power Monitor Interface



The controls on the Power Monitor are described below.

Test Settings

- **Power Rails:** Indicates the currently selected power rail. After selecting the desired rail, click Reset to refresh the screen with updated board readings.
- **Scale:** Specifies the amount to scale the power graph. Select a smaller number to zoom-in to see finer detail. Select a larger number to zoom-out to view the entire range of recorded values.
- **Speed:** Specifies how often to refresh the graph.

Power Information

Displays the root mean square (RMS) current, maximum and minimum numerical power readings in mA.

Graph

Displays the mA power consumption of your board over time. The green line indicates the current value. The red line indicates the maximum value read since the last reset. The yellow line indicates the minimum value read since the last reset.

General Information

Displays the Intel MAX 10 version and current temperature of the FPGA and the board.



Reset

Clears the graph, resets the minimum and maximum values and restarts the Power Monitor.

5.3.11. Clock Controller

The Clock Controller application sets the Si5338 programmable oscillators to any frequency between 0.16 MHz and 710 MHz.

The Clock Controller application sets the Si5341 programmable oscillators to any frequency between 0.1 MHz and 712.5 MHz.

The Clock Control communicates with the Intel MAX 10 on the board through the JTAG bus. The programmable oscillator are connected to the Intel MAX 10 device through a 2-wire serial bus.

Figure 32. Clock Controller - Si5338

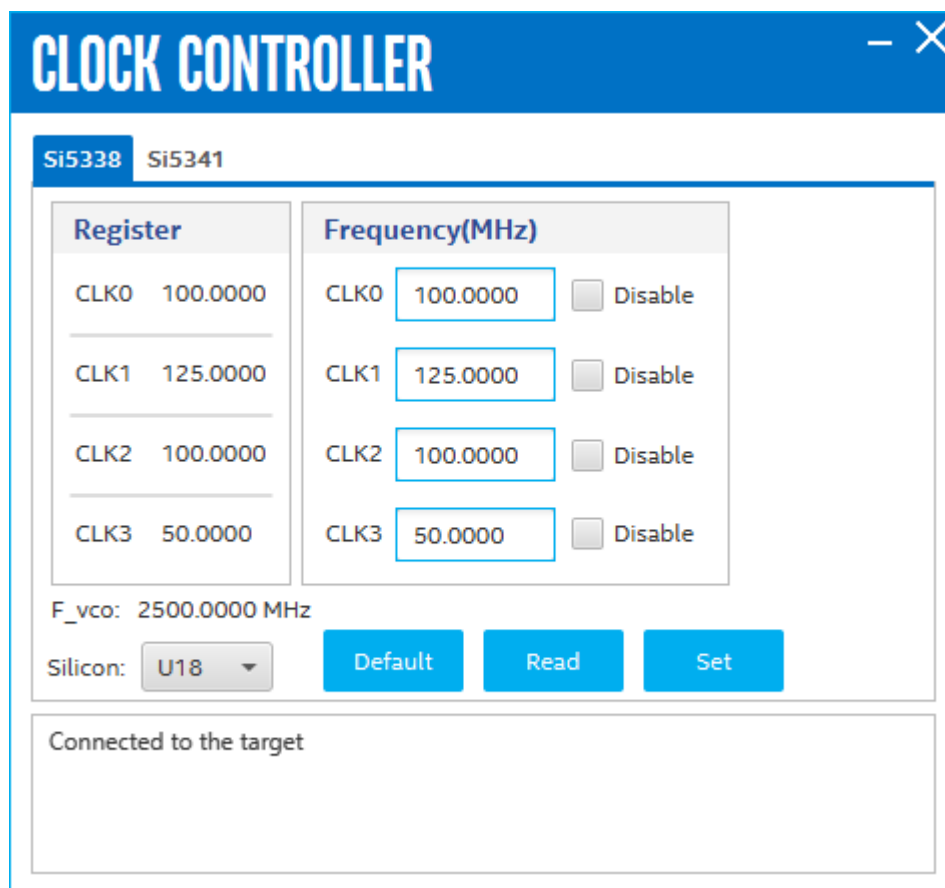
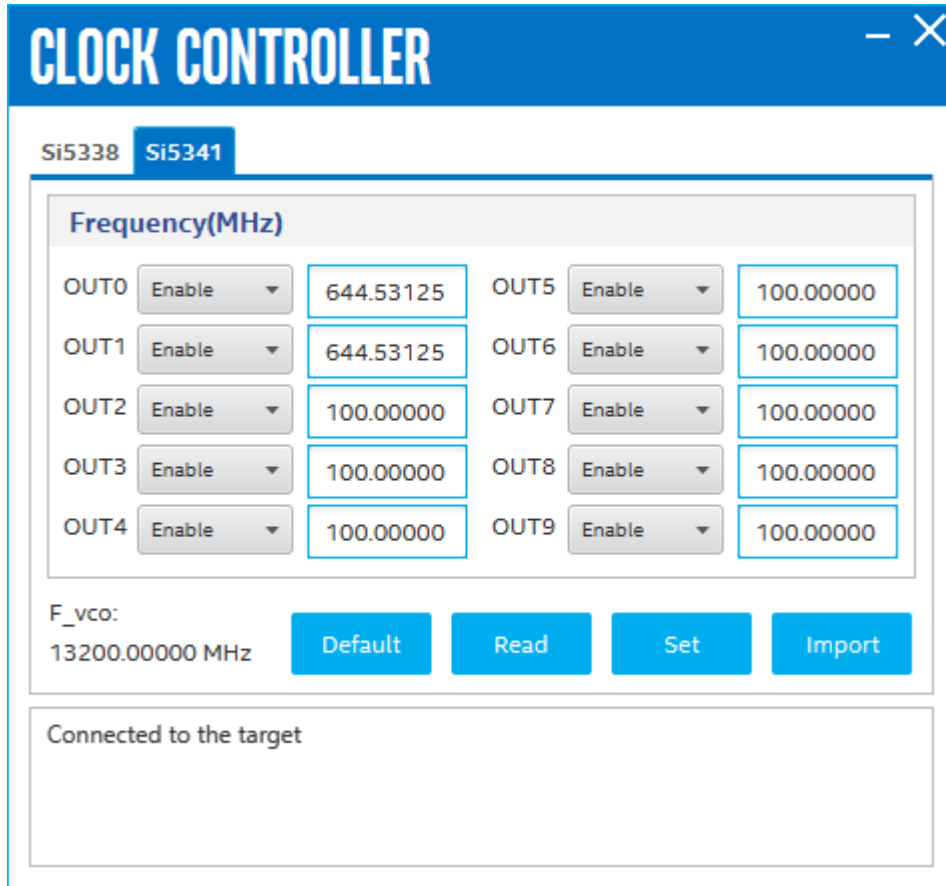


Figure 33. Clock Controller - Si5341



Si5338 tab and Si5341 tab display the same GUI controls for each clock generators. Each tab allows for separate control. The Si5338 is capable of synthesizing four independent user-programmable clock frequencies up to 710 MHz.

The controls of the clock controller are described below:

F_vco

Displays the generating signal value of the voltage-controlled oscillator.

Register

Display the current frequencies for each oscillator.

Frequency

Allows you to specify the frequency of the clock MHz.

Read

Reads the current frequency setting for the oscillator associated with the active tab.



Default

Sets the frequency for the oscillator associated with the active tab back to its default value. This can also be accomplished by power cycling the board.

Set

Sets the programmable oscillator frequency for the selected clock to the value in the CLK0 to CLK3 controls for the Si5338. Frequency changes might take several milliseconds to take effect. You might see glitches on the clock during this time. Intel recommends resetting the FPGA logic after changing frequencies.

Import

Import register map file generated from Silicon Laboratories ClockBuilder Desktop.

A. Additional Information

A.1. Add SmartVID settings in the QSF file

Intel Stratix 10 FPGA silicon assembled on the Intel Stratix 10 MX FPGA Development Kit enables SmartVID feature by default.

You may encounter the following error message when you switch from using the example design to your own design:

Error(19192): File <filename>.sof is incomplete - Power management settings are not set up appropriately on VID part"

To prevent Intel Quartus Prime from generating an error message due to incomplete SmartVID settings, you must put constraints listed below into the Intel Quartus Prime project QSF file.

Open your Intel Quartus Prime project QSF file, copy and paste the constraints listed below in the QSF file.

Before, you compile your project with correct SmartVID settings, ensure that there are no other similar settings with different values.

Constraints

```
set_global_assignment -name VID_OPERATION_MODE "PMBUS MASTER"
set_global_assignment -name USE_PWRMGT_SCL SDM_IO14
set_global_assignment -name USE_PWRMGT_SDA SDM_IO11
set_global_assignment -name USE_CONF_DONE SDM_IO16
set_global_assignment -name USE_INIT_DONE SDM_IO0
set_global_assignment -name PWRMGT_BUS_SPEED_MODE "100 KHZ"
set_global_assignment -name PWRMGT_SLAVE_DEVICE0_ADDRESS 47
set_global_assignment -name PWRMGT_PAGE_COMMAND_ENABLE ON
```

The Intel Stratix 10 device family offers SmartVID standard power devices in all speed grades. Lower power fixed-voltage devices are also available in all speed grades except for the fastest speed grade. Please refer to *Intel Stratix 10 Power Management User Guide* for additional information.

Related Information

[Intel Stratix 10 Power Management User Guide](#)

A.2. Safety and Regulatory Information



ENGINEERING DEVELOPMENT PRODUCT - NOT FOR RESALE OR LEASE

This development kit is intended for laboratory development and engineering use only.

This development kit is designed to allow:

- Product developers and system engineers to evaluate electronic components, circuits, or software associated with the development kit to determine whether to incorporate such items in a finished product.
- Software developers to write software applications for use with the end product.

This kit is not a finished product and when assembled may not be resold or otherwise marketed unless all required Federal Communications Commission (FCC) equipment authorizations are first obtained.

Operation is subject to the condition that this product not cause harmful interference to licensed radio stations and that this product accept harmful interference.

Unless the assembled kit is designed to operate under Part 15, Part 18 or Part 95 of the United States Code of Federal Regulations (CFR) Title 47, the operator of the kit must operate under the authority of an FCC licenseholder or must secure an experimental authorization under Part 5 of the United States CFR Title 47.

Safety Assessment and CE mark requirements have been completed, however, other certifications that may be required for installation and operation in your region have not been obtained.

A.2.1. Safety Warnings



Power Supply Hazardous Voltage

AC mains voltages are present within the power supply assembly. No user serviceable parts are present inside the power supply.

Power Connect and Disconnect

The AC power supply cord is the primary disconnect device from mains (AC power) and used to remove all DC power from the board/system. The socket outlet must be installed near the equipment and must be readily accessible.

	WARNING	
	RISK OF ELECTRIC SHOCK	
<p>Connect only to a properly earth grounded outlet. Apparaten skall anslutas till jordat uttag när den ansluts till ett nätverk.</p>		

System Grounding (Earthing)

To avoid shock, you must ensure that the power cord is connected to a properly wired and grounded receptacle. Ensure that any equipment to which this product is attached is also connected to properly wired and grounded receptacles.

	WARNING	
	RISK OF ELECTRIC SHOCK	
<p>Do not attempt to modify or use the supplied AC power cord if it is not the exact type and rating required.</p>		

Power Cord Requirements

The connector that plugs into the wall outlet must be a grounding-type male plug designed for use in your region. It must have marks showing certification by an agency in your region. The connector that plugs into the AC receptacle on the power supply must be an IEC 320, sheet C13, female connector. If the power cord supplied with the system does not meet requirements for use in your region, discard the cord and do not use it with adapters.






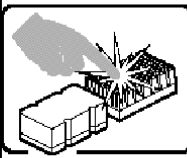
Lightning/Electrical Storm

Do not connect/disconnect any cables or perform installation/maintenance of this product during an electrical storm.

Risk of Fire

To reduce the risk of fire, keep all flammable materials a safe distance away from the boards and power supply. You must configure the development kit on a flame retardant surface.

A.2.2. Safety Cautions

	CAUTION	
	Hot Surfaces and Sharp Edges	
Integrated Circuits and heat sinks may be hot if the system has been running. Also, there might be sharp pins and edges on some boards. Contact should be avoided.		

Caution: Hot Surfaces and Sharp Edges. Integrated Circuits and heat sinks may be hot if the system has been running. Also, there might be sharp edges on some boards. Contact should be avoided.

Thermal and Mechanical Injury

Certain components such as heat sinks, power regulators, and processors may be hot. Heatsink fans are not guarded. Power supply fan may be accessible through guard. Care should be taken to avoid contact with these components.





Cooling Requirements

Maintain a minimum clearance area of 5 centimeters (2 inches) around the side, front and back of the board for cooling purposes. Do not block power supply ventilation holes and fan.

Electro-Magnetic Interference (EMI)

This equipment has not been tested for compliance with emission limits of FCC and similar international regulations. Use of this equipment in a residential location is prohibited. This equipment generates, uses and can radiate radio frequency energy which may result in harmful interference to radio communications. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment on and off, the user is required to take measures to eliminate this interference.

Telecommunications Port Restrictions

The wireline telecommunications ports (modem, xDSL, T1/E1) on this product must not be connected to the Public Switched Telecommunication Network (PSTN) as it might result in disruption of the network. No formal telecommunication certification to FCC, R&TTE Directive, or other national requirements have been obtained.



Electrostatic Discharge (ESD) Warning

A properly grounded ESD wrist strap must be worn during operation/installation of the boards, connection of cables, or during installation or removal of daughter cards. Failure to use wrist straps can damage components within the system.



Attention: Please return this product to Intel for proper disposition. If it is not returned, refer to local environmental regulations for proper recycling. Do not dispose of this product in unsorted municipal waste.

Ecology Conformance Marking for WEEE and China RoHS



A.3. Compliance and Conformity Statement

CE EMI Conformity Caution

This development kit is delivered conforming to relevant standards mandated by Directive 2014/30/EU. Because of the nature of programmable logic devices, it is possible for the user to modify the development kit in such a way as to generate electromagnetic interference (EMI) that exceeds the limits established for this equipment. Any EMI caused as a result of modifications to the delivered material is the responsibility of the user of this development kit.



B. Revision History

B.1. Revision History

Table 29. Revision History for Intel Stratix 10 MX FPGA Development Kit User Guide

Document Version	Changes
2020.06.15	Updated Add SmartVID settings in the QSF file on page 90 [Constraints script updated] Constraints Updated: <ul style="list-style-type: none"> • PWRMGT_BUS_SPEED_MODE "100 KHZ" • PWRMGT_SLAVE_DEVICE0_ADDRESS 47
2020.02.12	Updated Development Kit block diagram in General Development Kit Description on page 4 [Correction: DDR4 is 16Gb x5]
2019.11.29	<ul style="list-style-type: none"> • Add support for production versions of development board: <ul style="list-style-type: none"> — Intel Stratix 10 MX FPGA H-Tile (8 GB) — Intel Stratix 10 MX FPGA H-Tile (16 GB) • Remove support for ES version of development board
2019.09.20	Updated <i>SW2 DIP JTAG Switch Default Settings (Board Bottom) Table</i> in Default Switch and Jumper Settings on page 11
2019.08.22	Added Add SmartVID settings in the QSF file on page 90
2018.10.12	Engineering Silicon (ES) Release.

Компания «Океан Электроники» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Поставка оригинальных импортных электронных компонентов напрямую с производств Америки, Европы и Азии, а так же с крупнейших складов мира;
- Широкая линейка поставок активных и пассивных импортных электронных компонентов (более 30 млн. наименований);
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Помощь Конструкторского Отдела и консультации квалифицированных инженеров;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Поставка электронных компонентов под контролем ВП;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
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- Поставка специализированных компонентов военного и аэрокосмического уровня качества (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Actel, Aeroflex, Peregrine, VPT, Syfer, Eurofarad, Texas Instruments, MS Kennedy, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

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